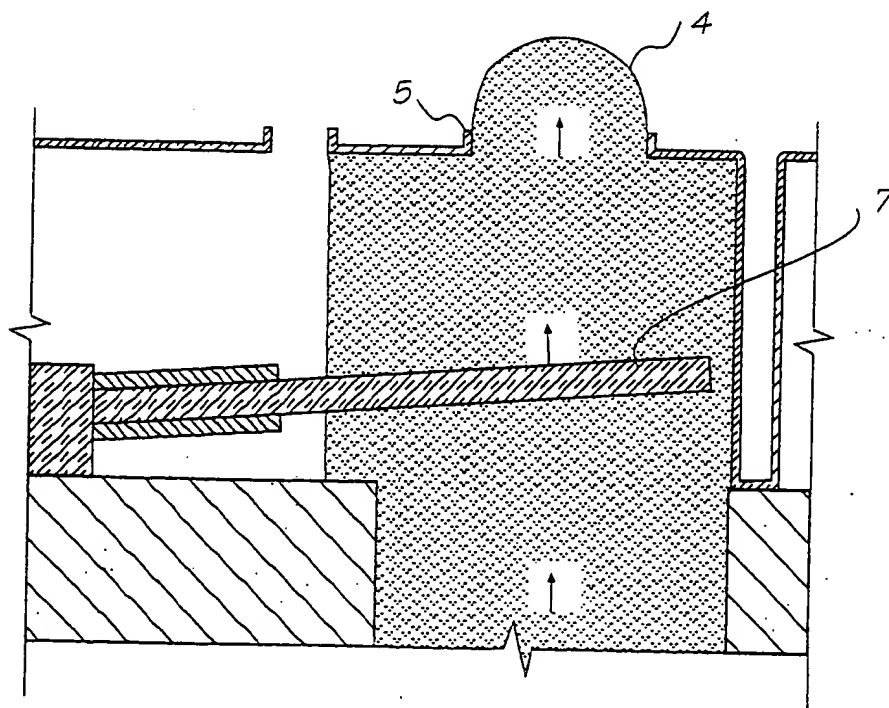
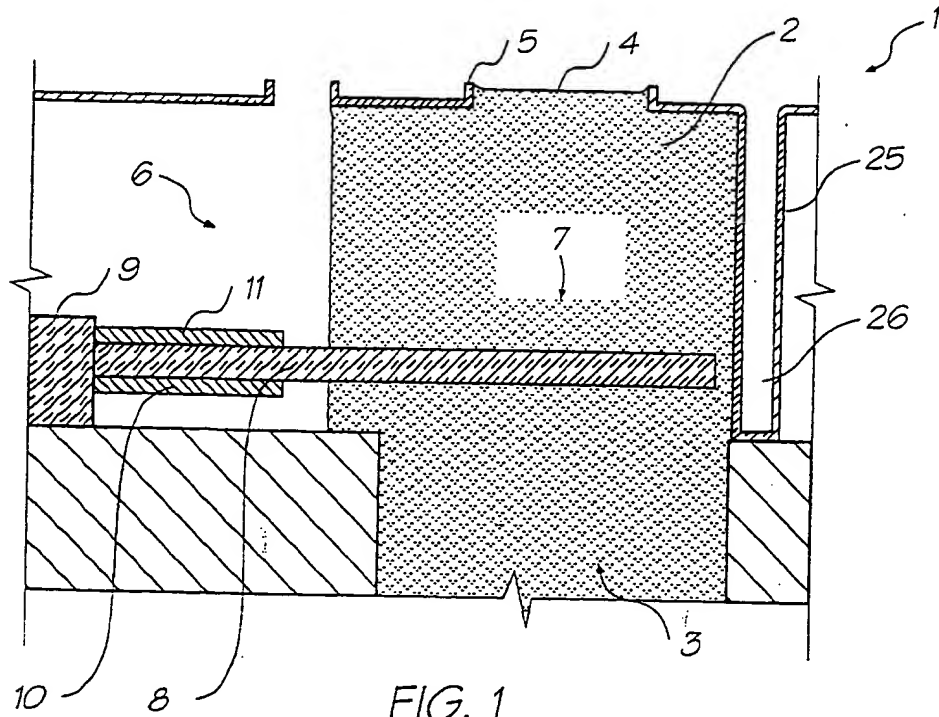


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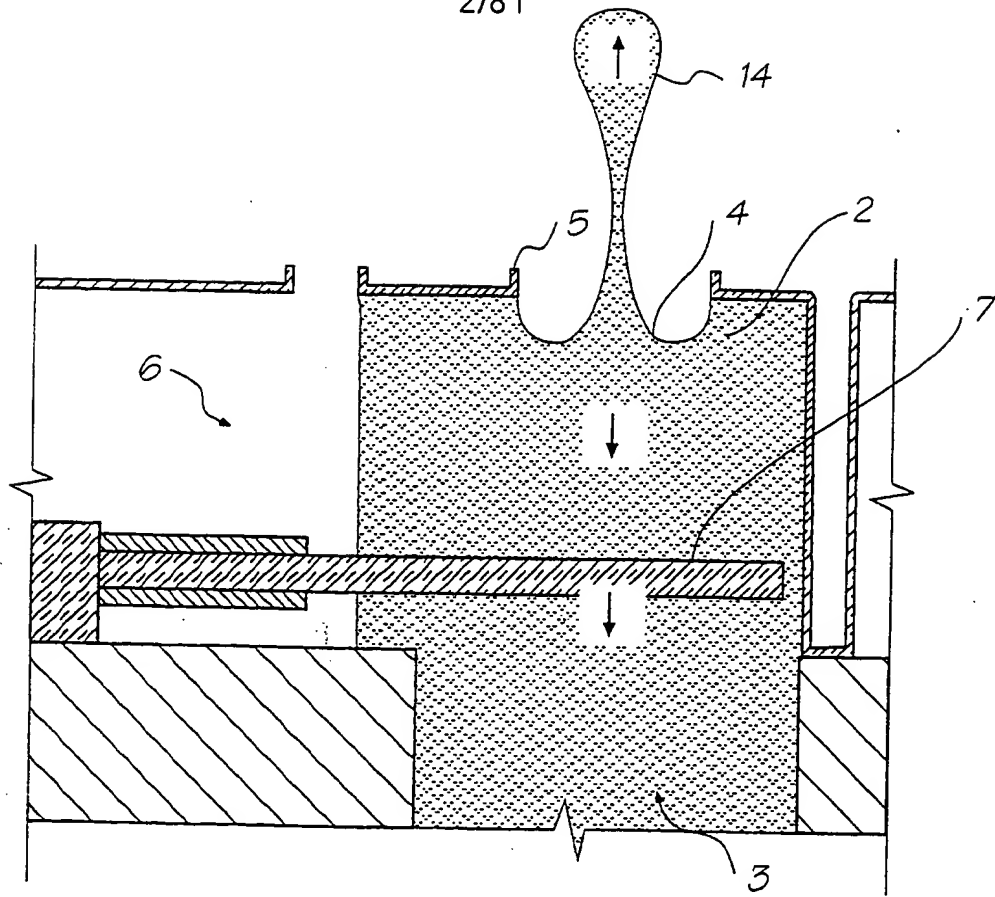


FIG. 3

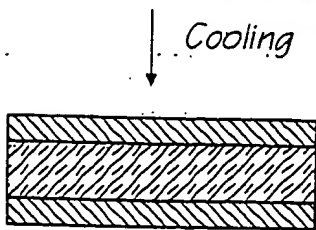
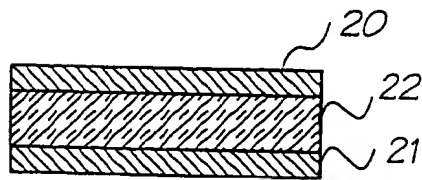


FIG. 4

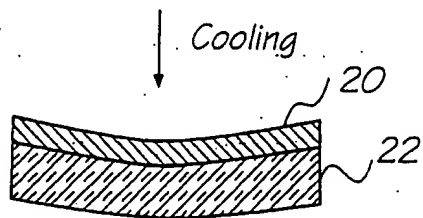
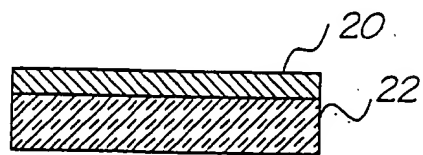


FIG. 5

093571 041604
for 255650

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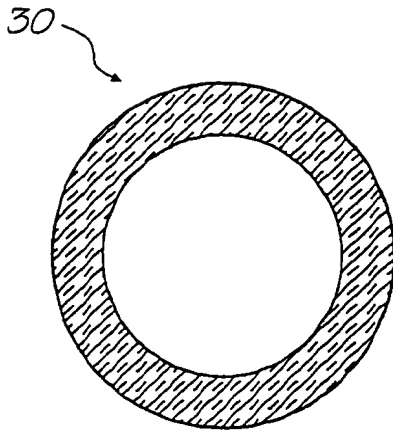


FIG. 6

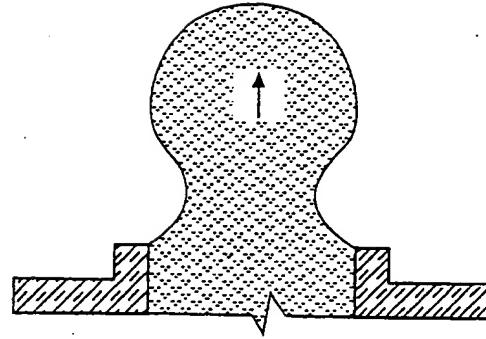


FIG. 7

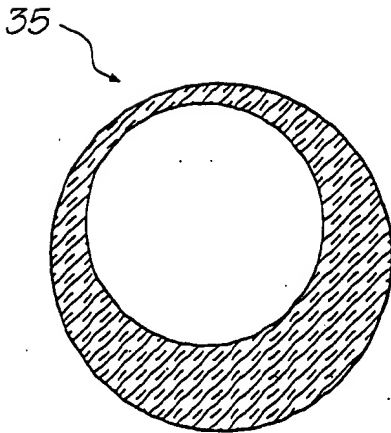


FIG. 8

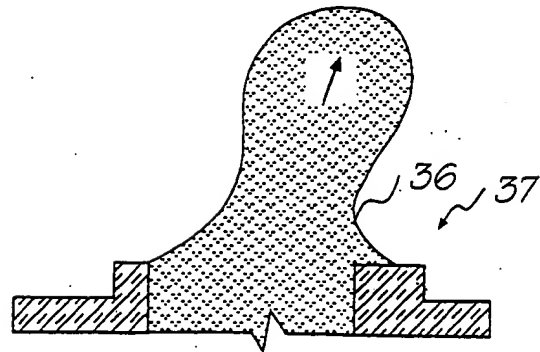


FIG. 9

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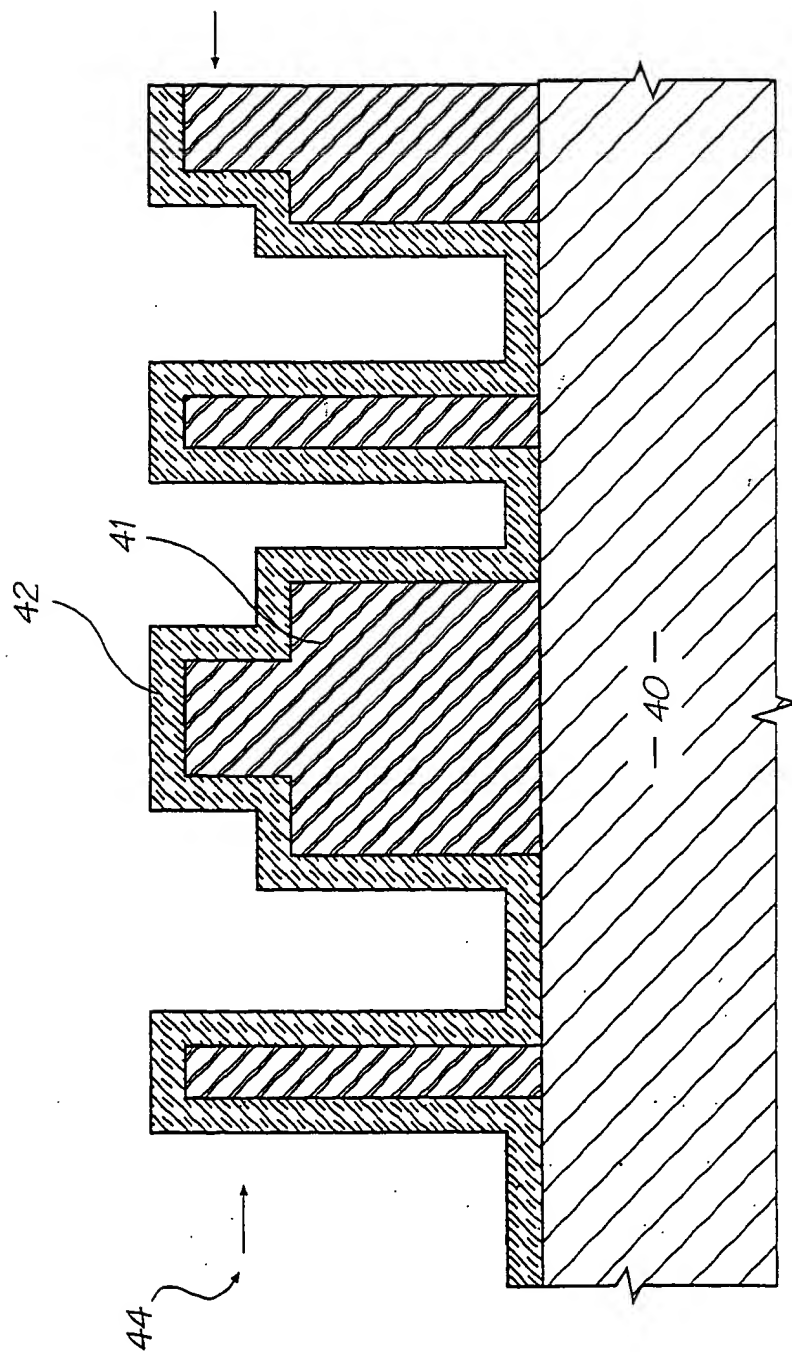


FIG. 10

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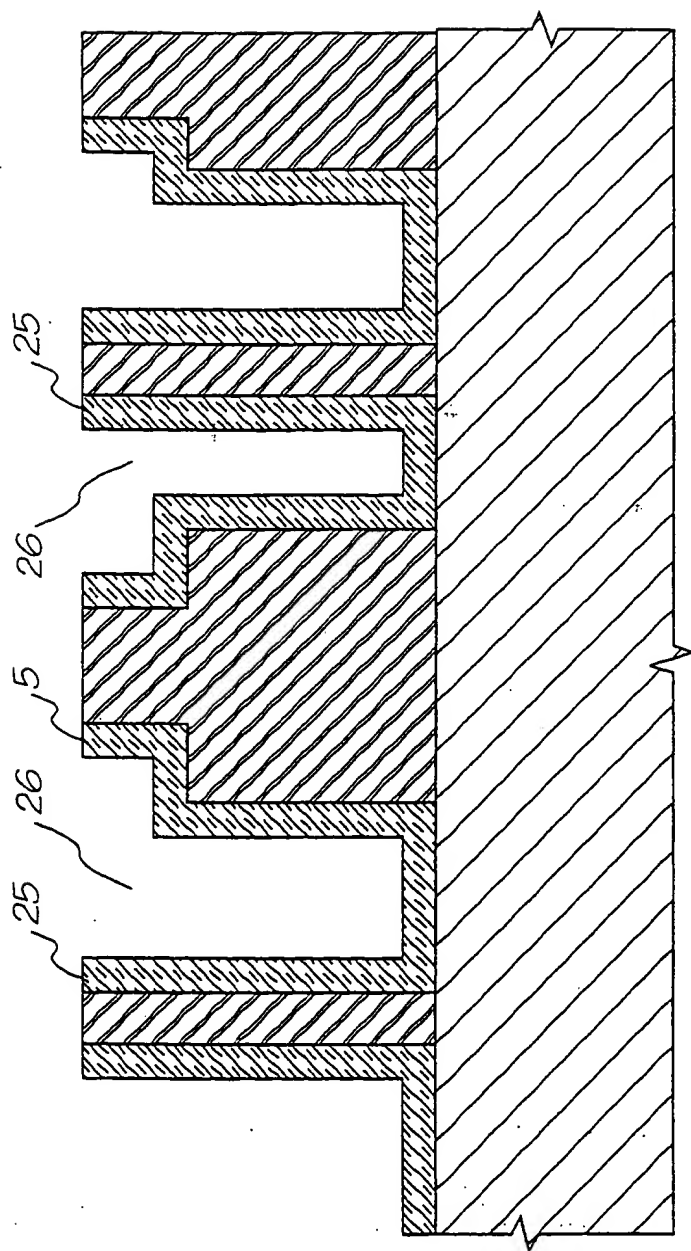


FIG. 11

FIG. 11

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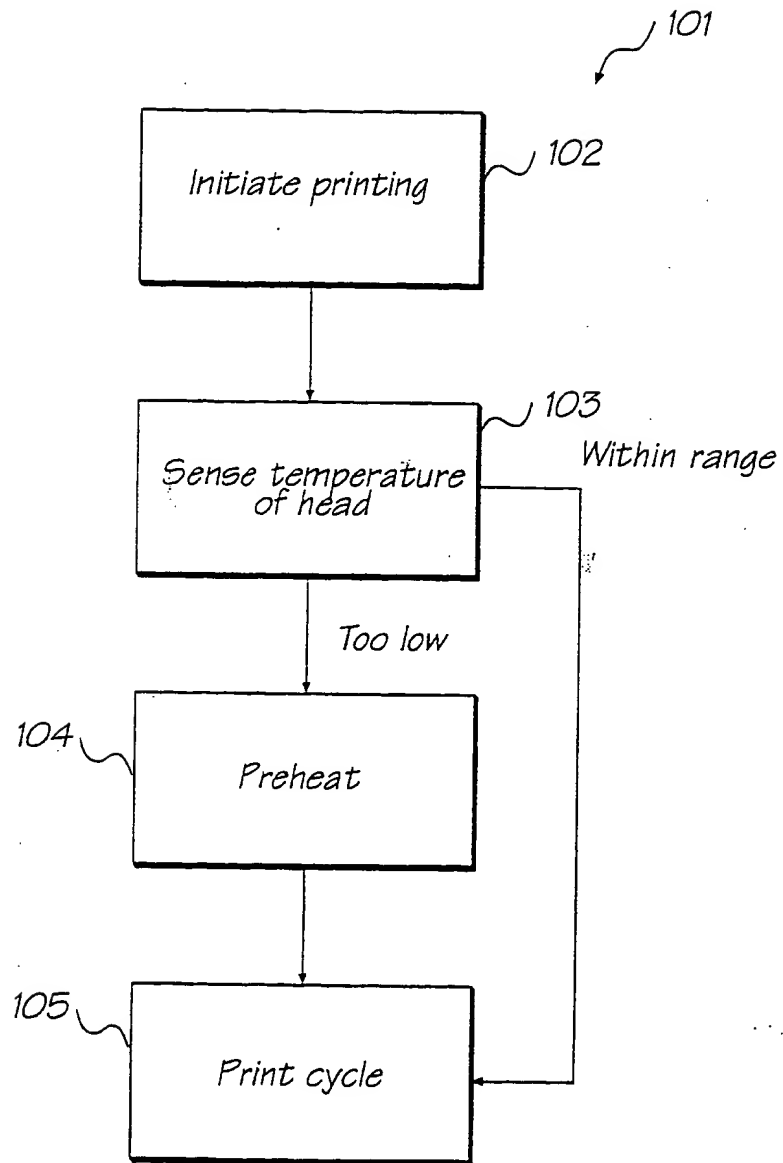


FIG. 12

FIG. 13

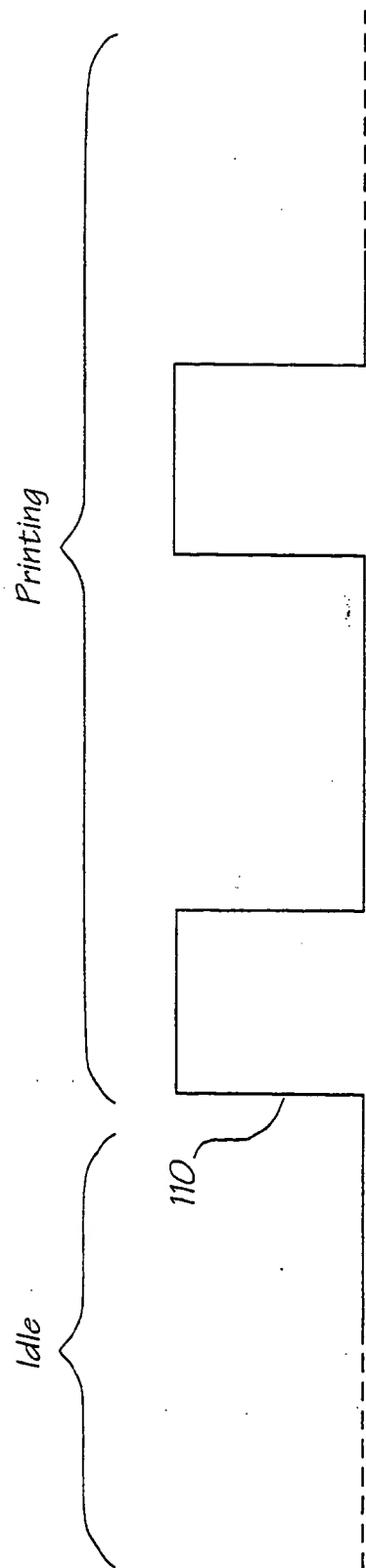


FIG. 13

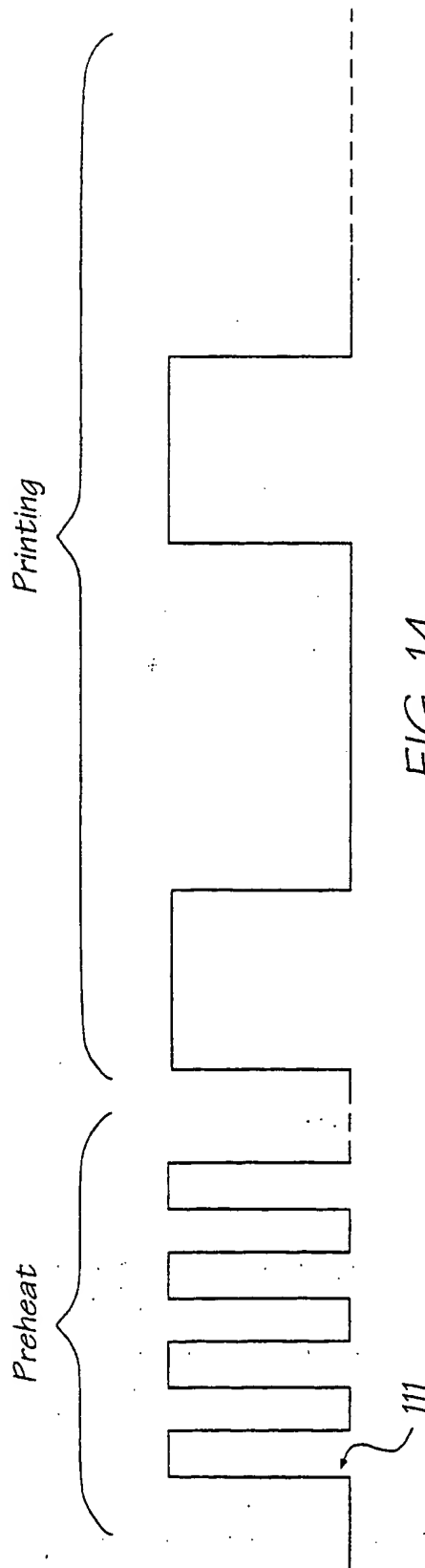


FIG. 14

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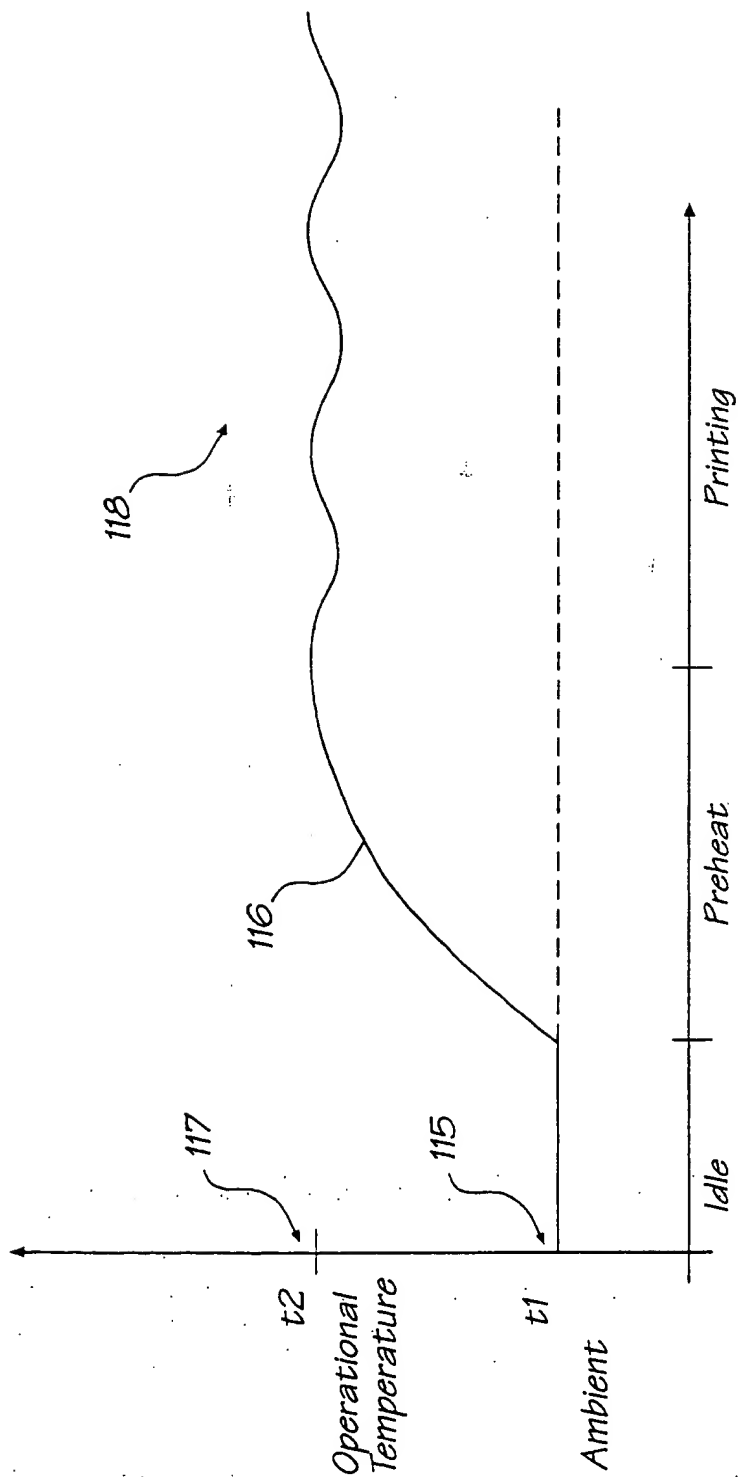


FIG. 15

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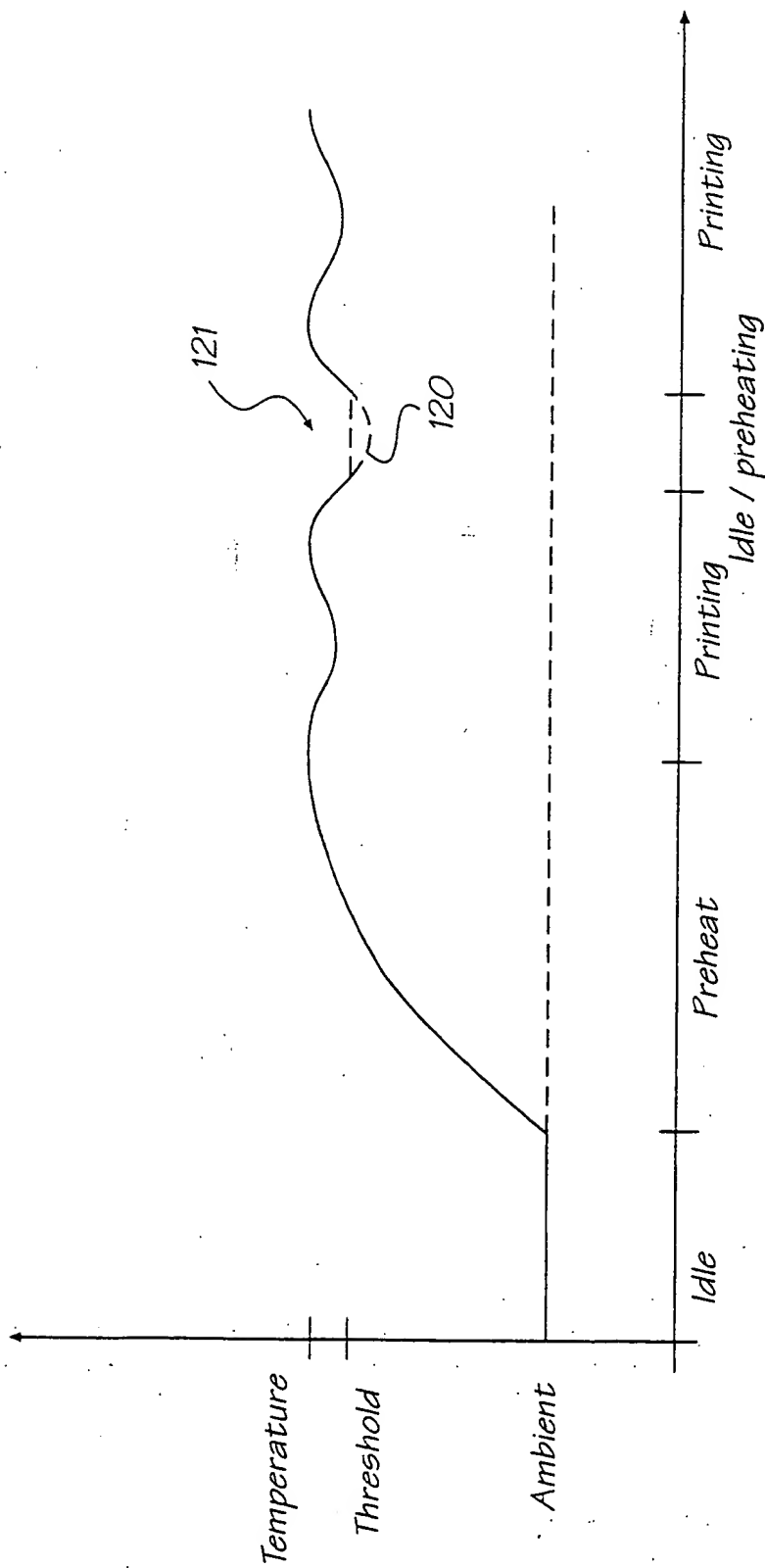


FIG. 16

FIG. 16

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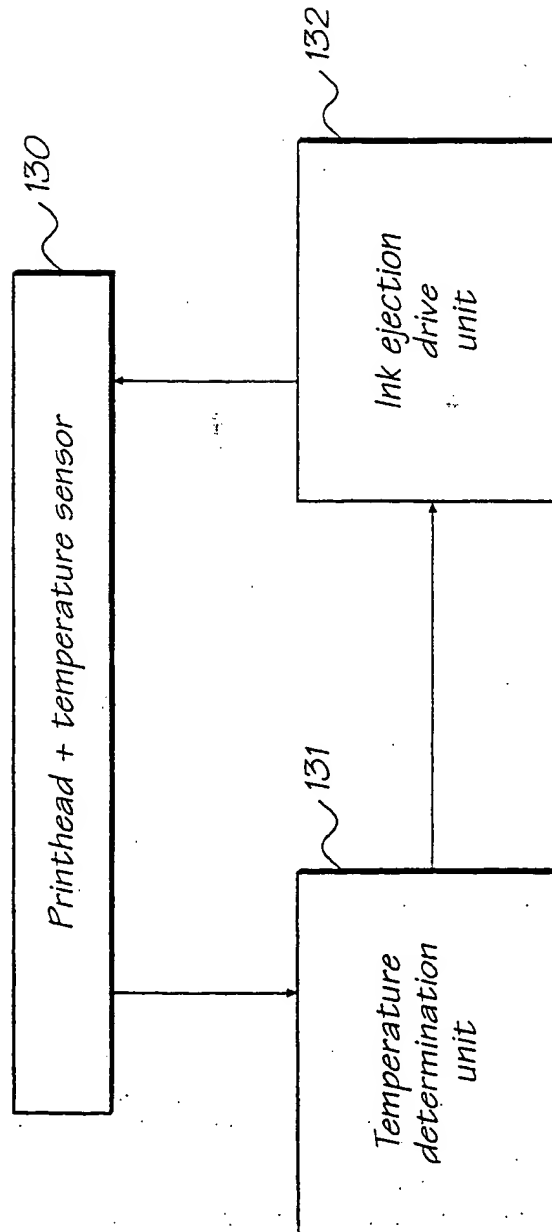


FIG. 17

FIG. 17

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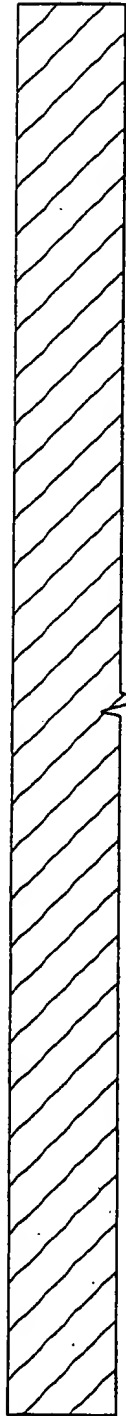
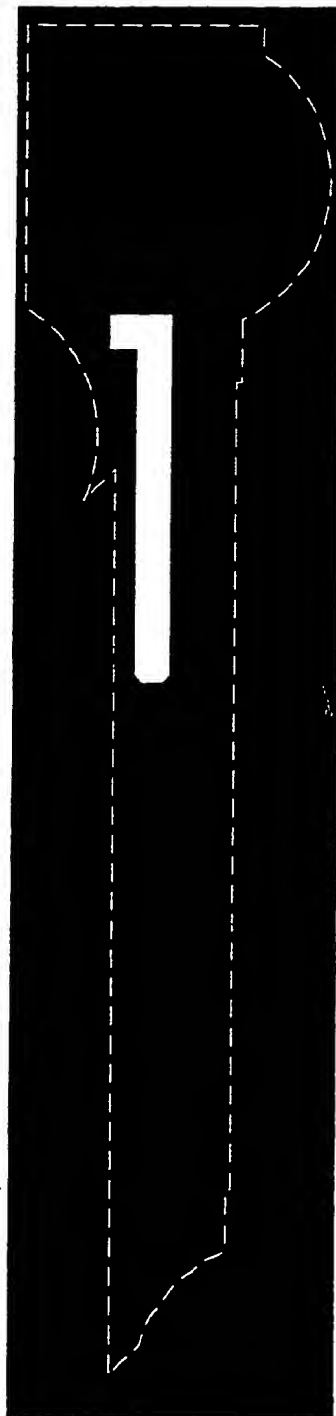


FIG. 18



N-Well mask

FIG. 19

210



Implant N-Well

FIG. 20

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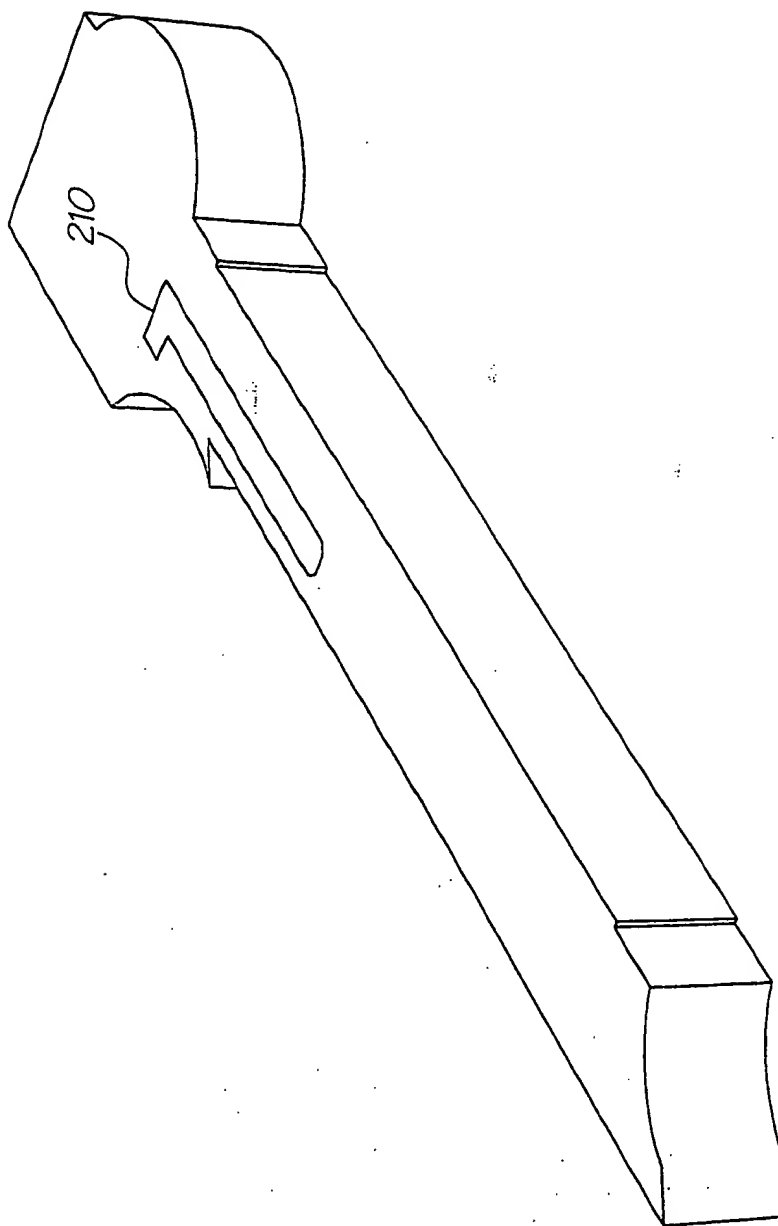
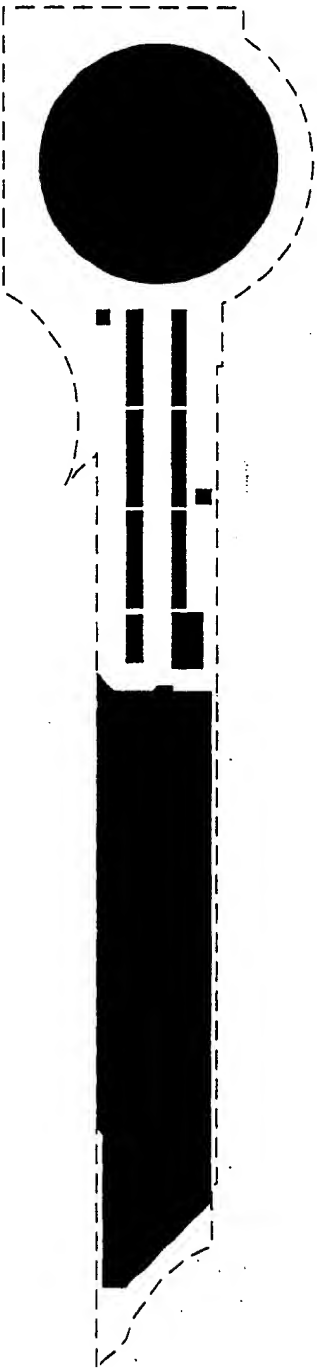


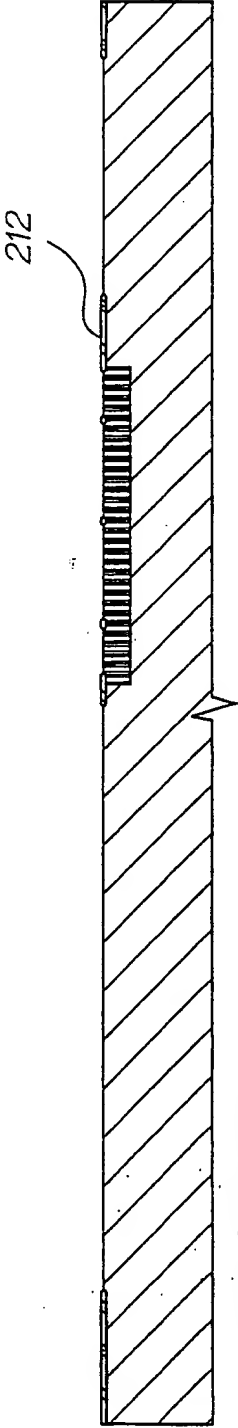
FIG. 21

FIG. 21



Active mask

FIG. 22



Grow field oxide

FIG. 23

FIG. 24a FIG. 24b

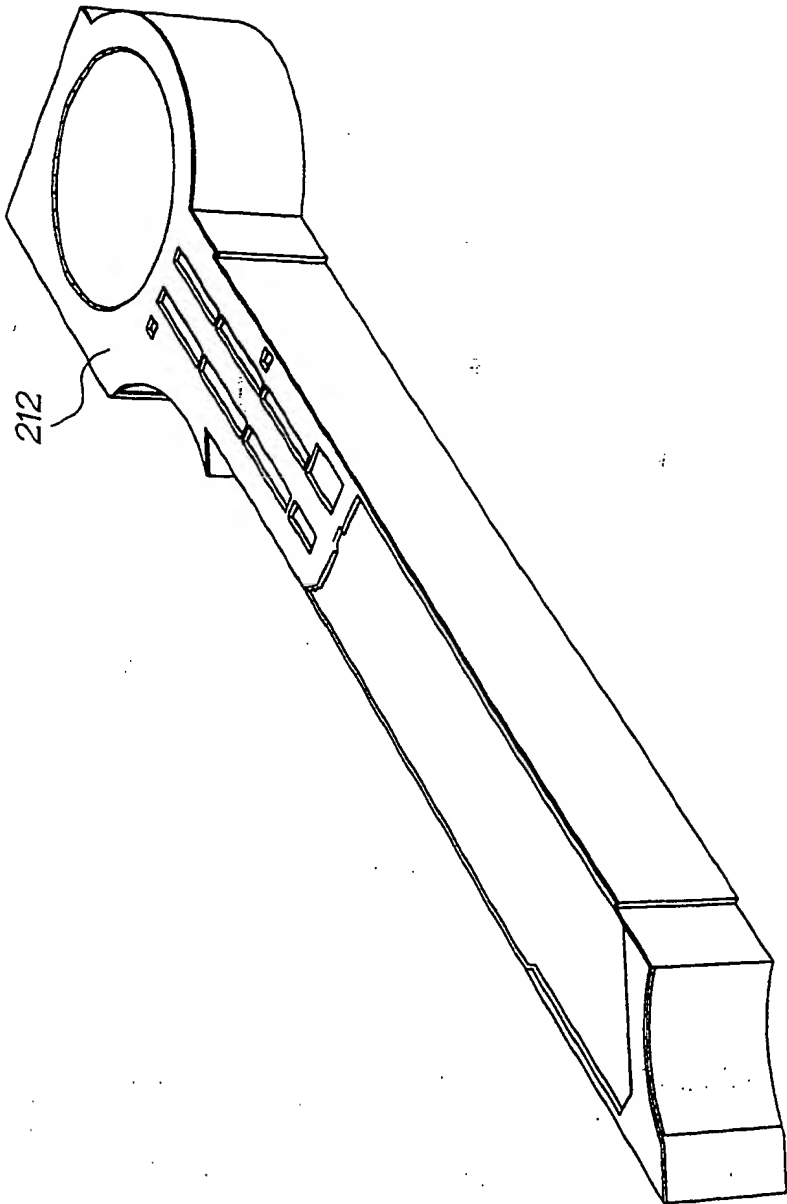
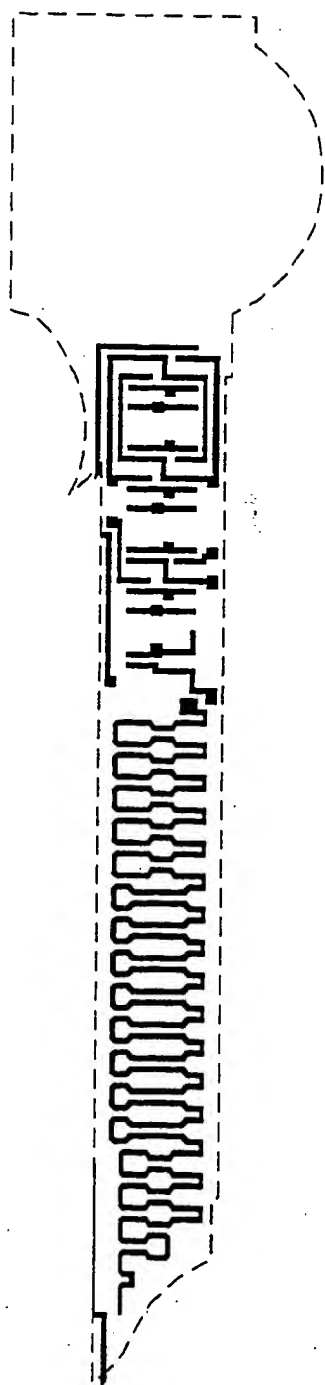


FIG. 24

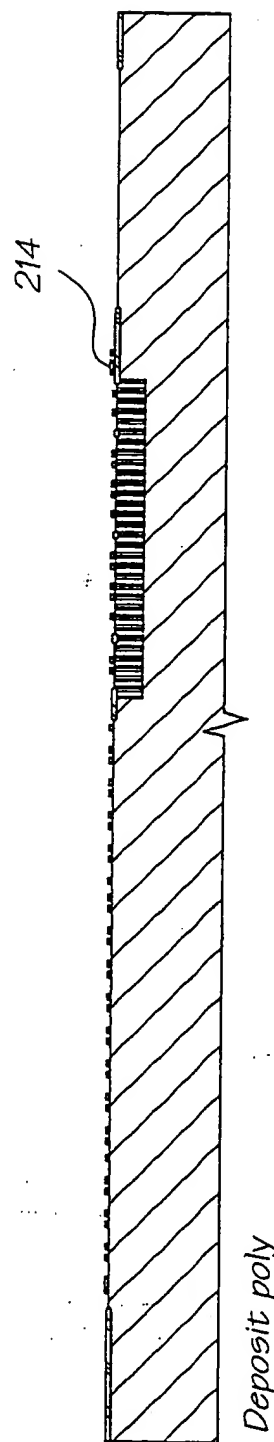
FIG. 24

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Poly mask

FIG. 25



Deposit poly

FIG. 26

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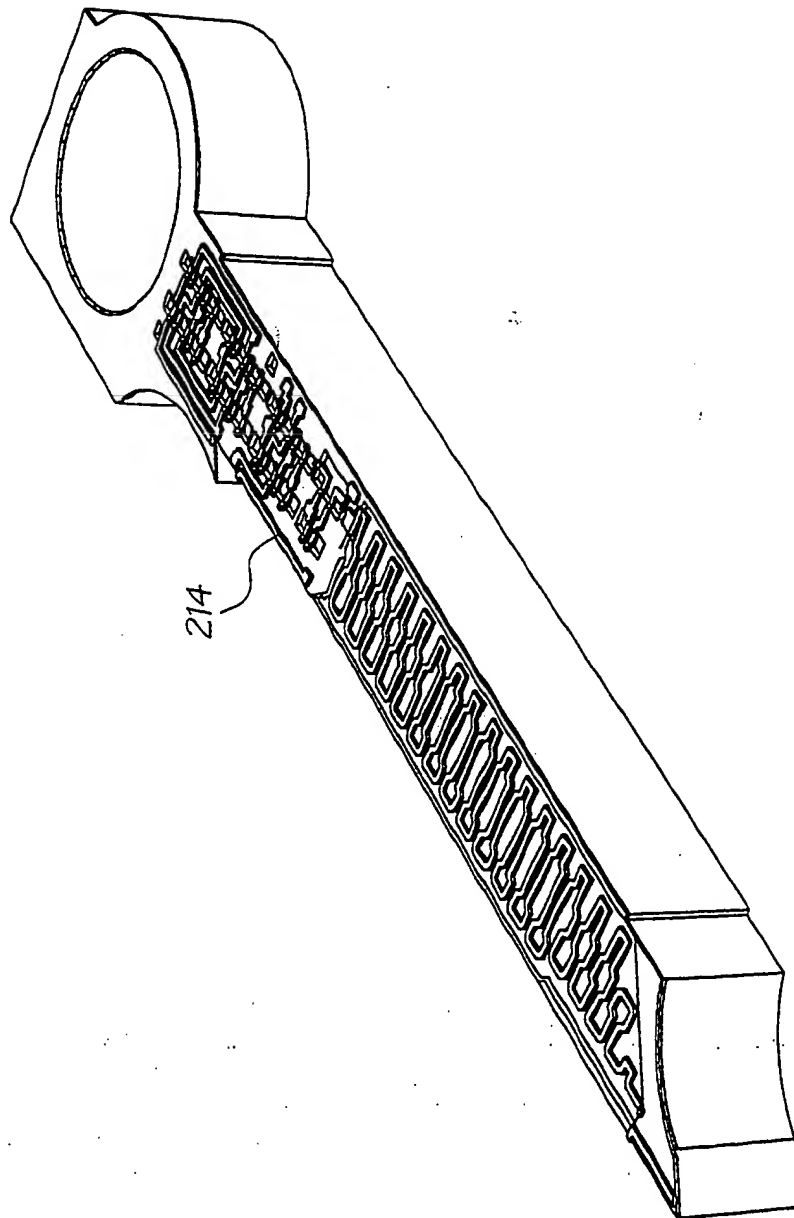
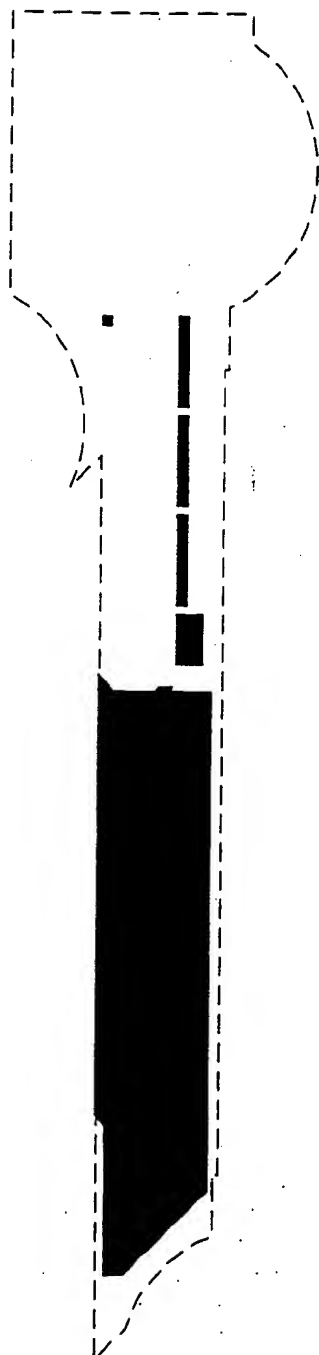


FIG. 27

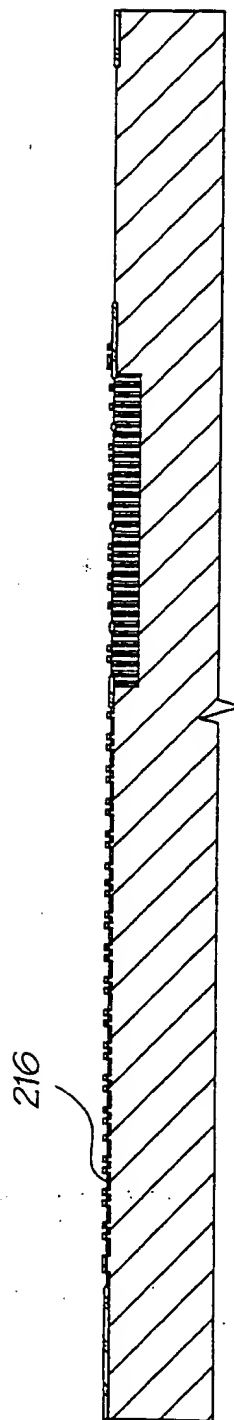
FIG. 27

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n+ mask

FIG. 28



n+ implant

FIG. 29

FIG. 28

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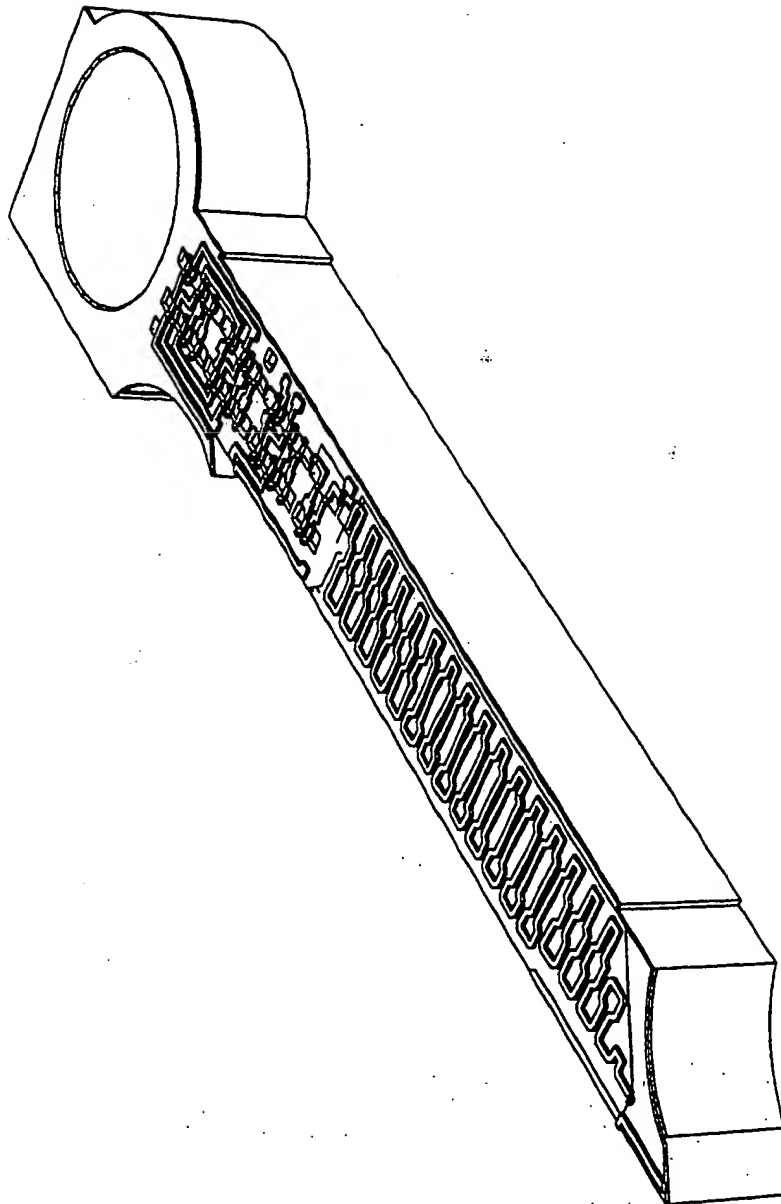
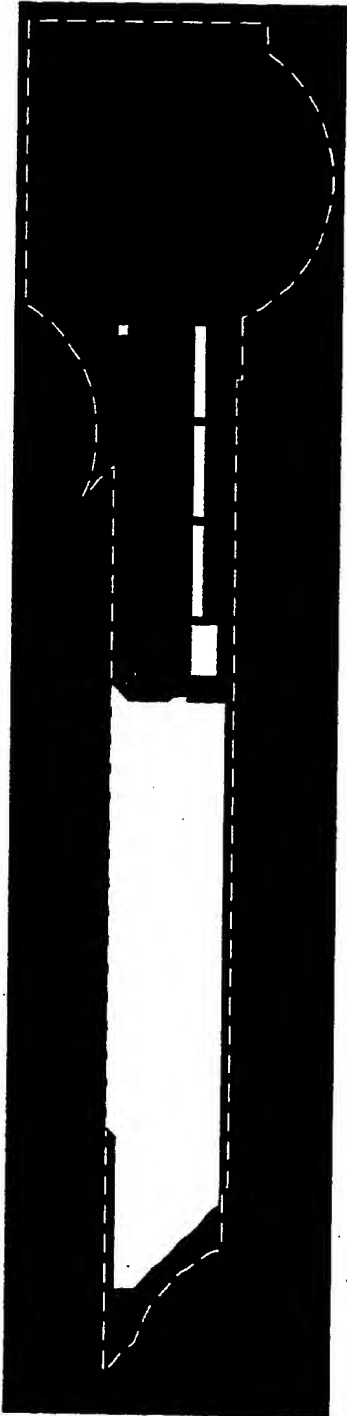


FIG. 30

FIG. 30

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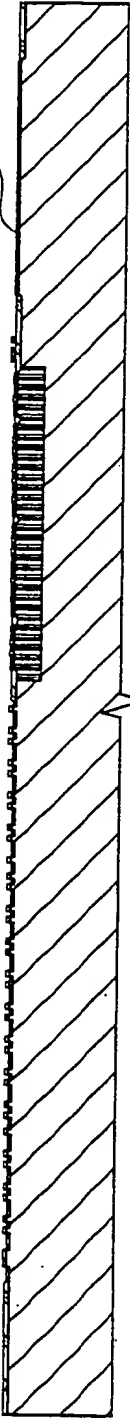
FIG. 31



p+ mask

FIG. 31

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p+ implant

FIG. 32

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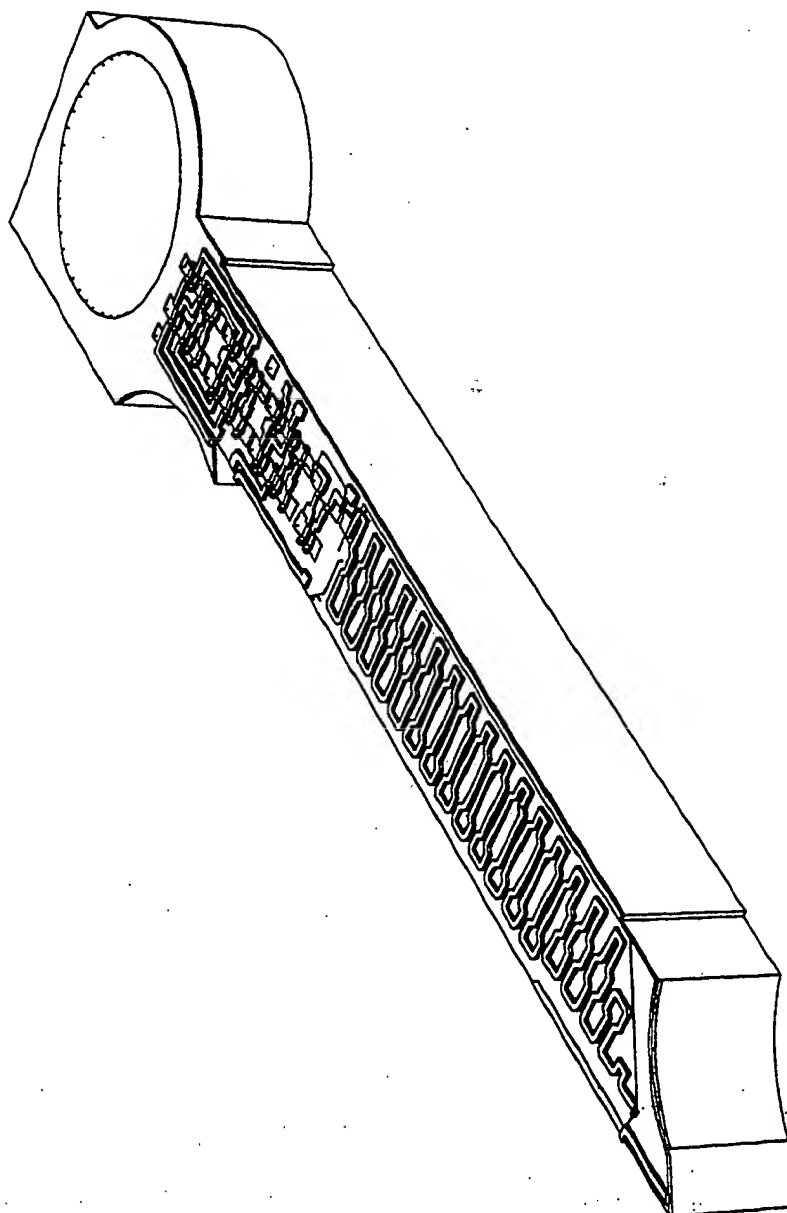
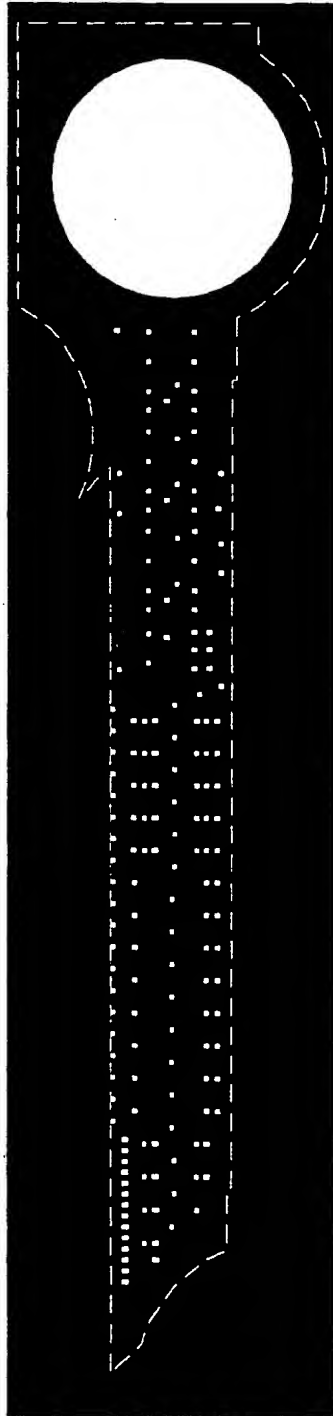


FIG. 33

TOP VIEW

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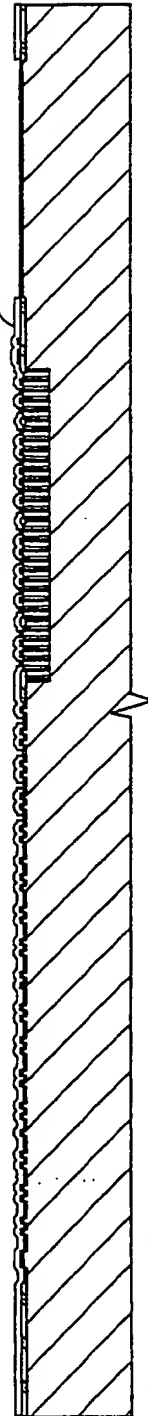
FIG. 34



Contacts mask

FIG. 34

220



Deposit ILD 1, etch contacts

FIG. 35

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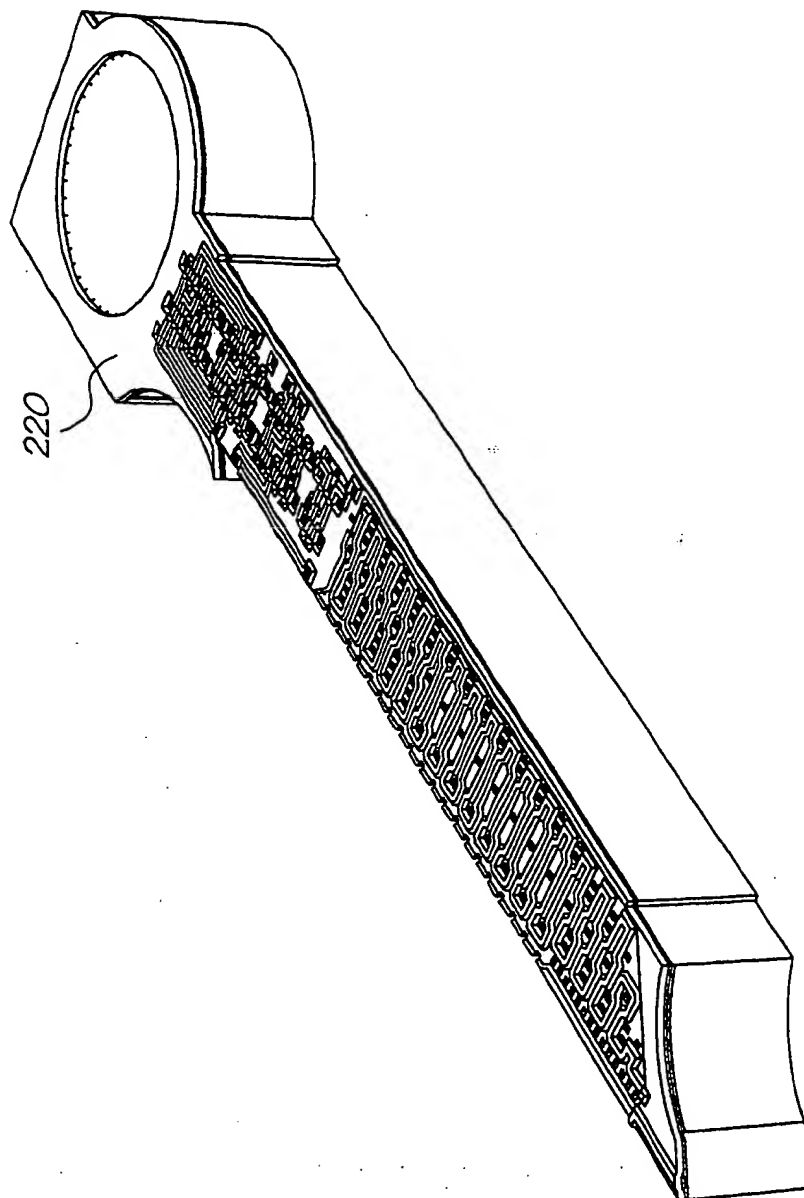
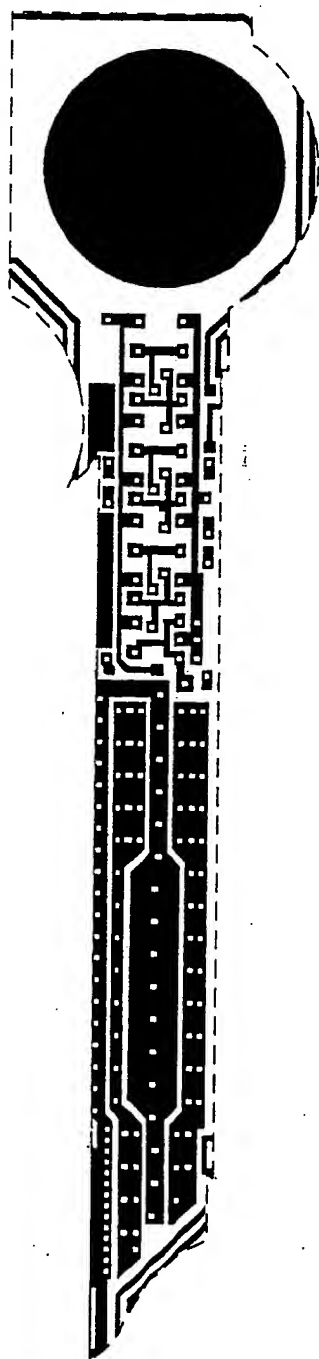


FIG. 36

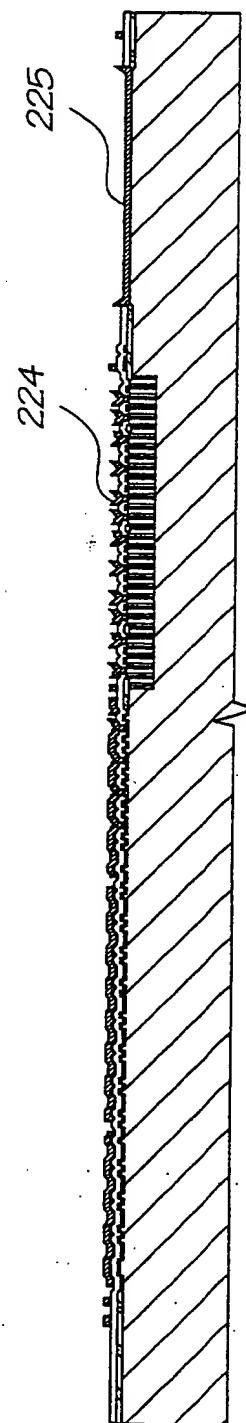
FIG. 36

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Metal 1 mask

FIG. 37



Deposit Metal 1

FIG. 38

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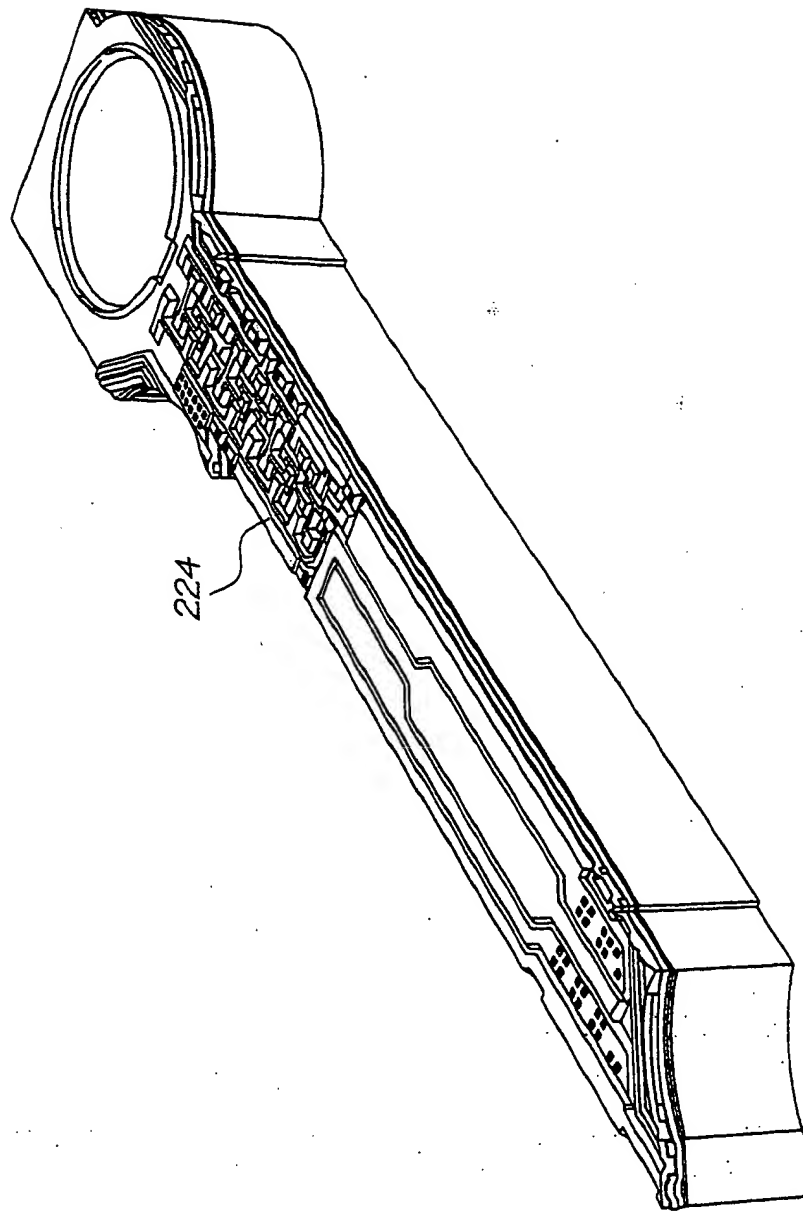


FIG. 39

FIG. 39

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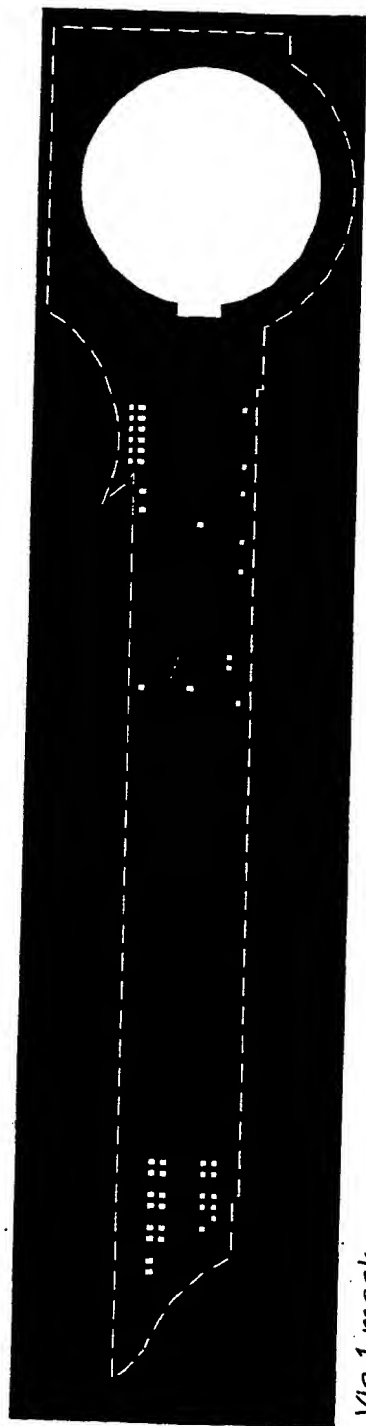


FIG. 40

Via 1 mask

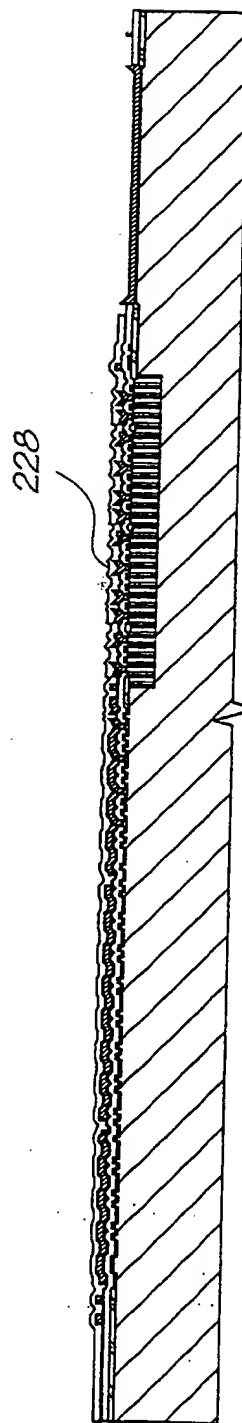
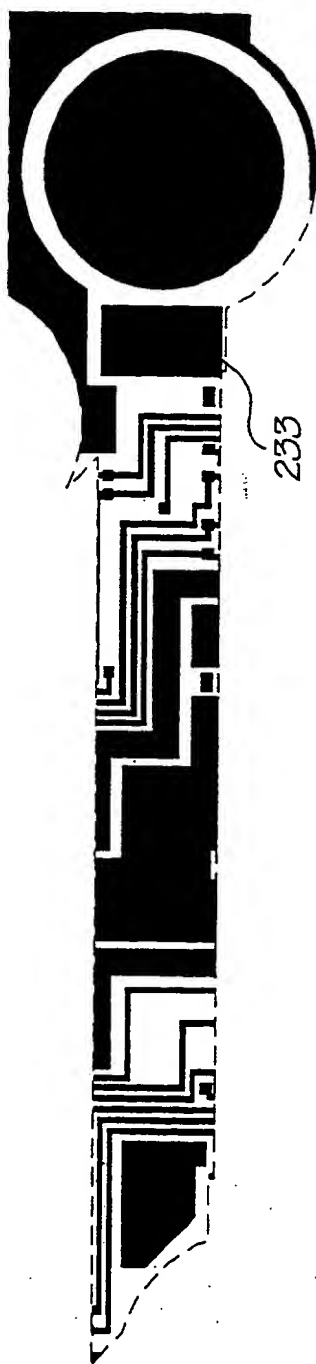


FIG. 41

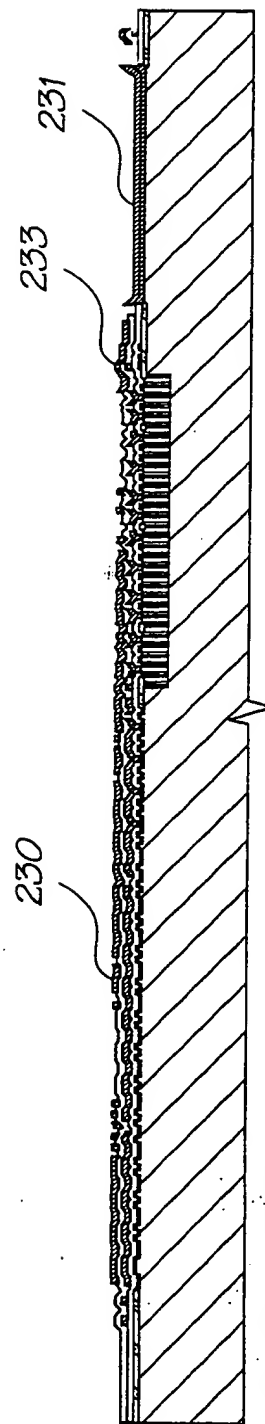
Deposit ILD 2, etch vias

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Metal 2 mask

FIG. 42



Deposit metal 2

FIG. 43

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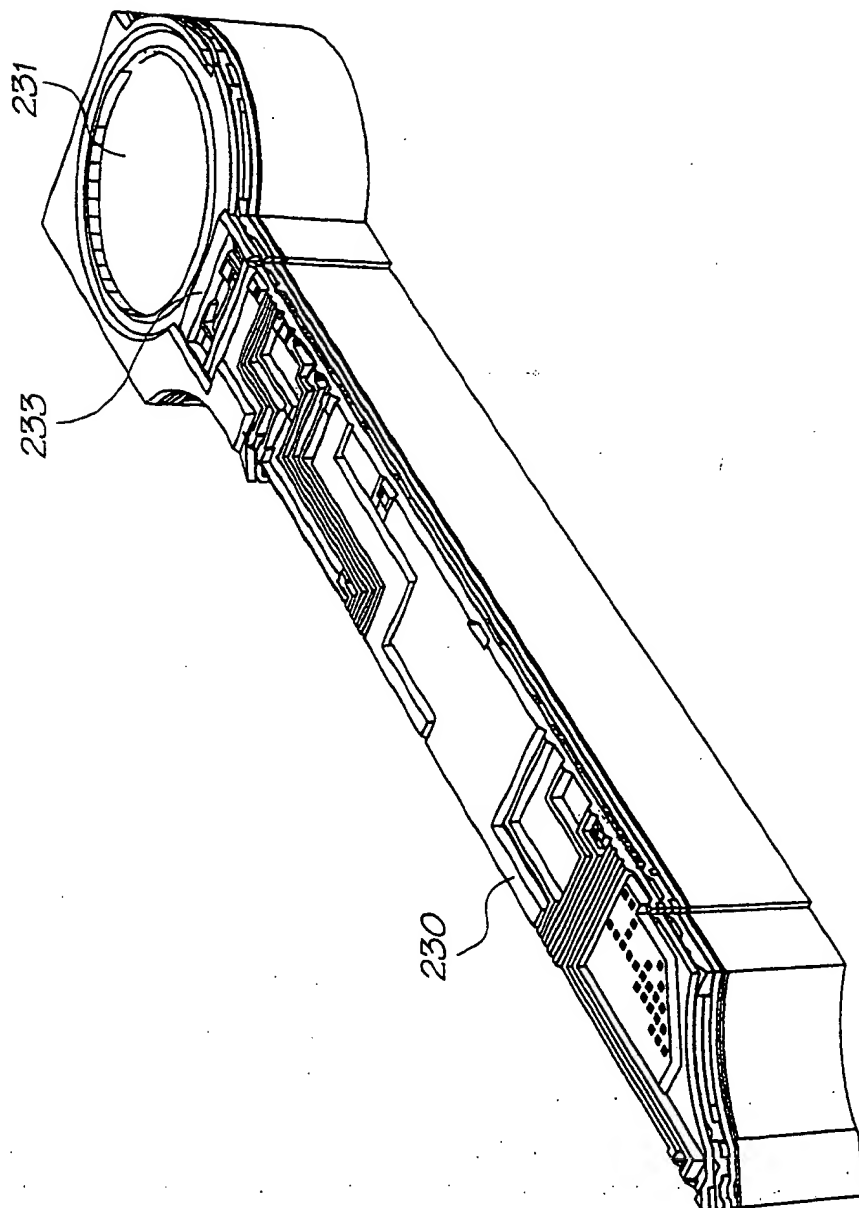
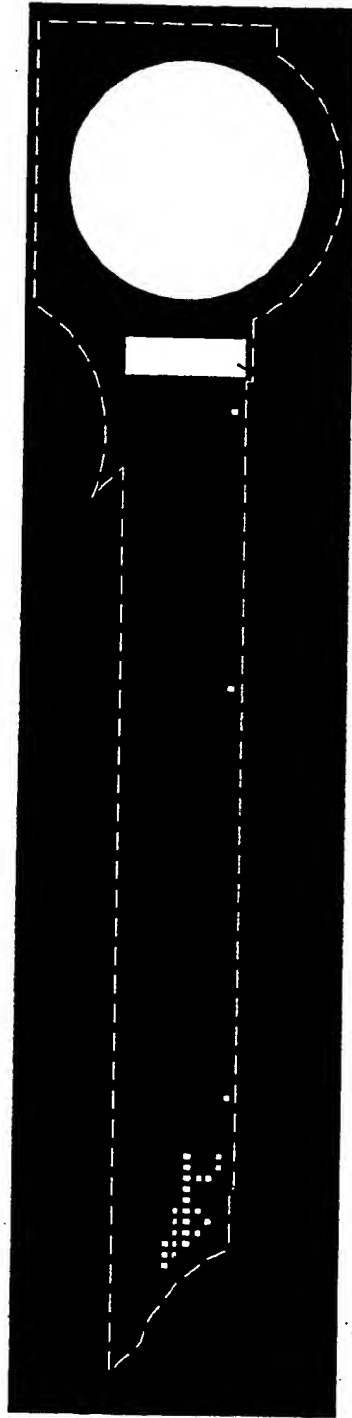


FIG. 44

FIG. 44

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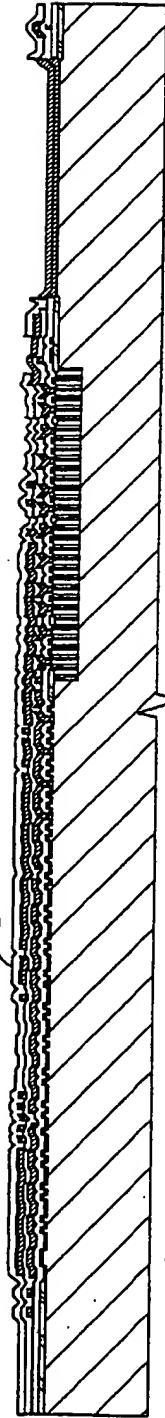
FIG. 45



Via 2 mask

FIG. 45

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Deposit ILD 3, etch vias

FIG. 46

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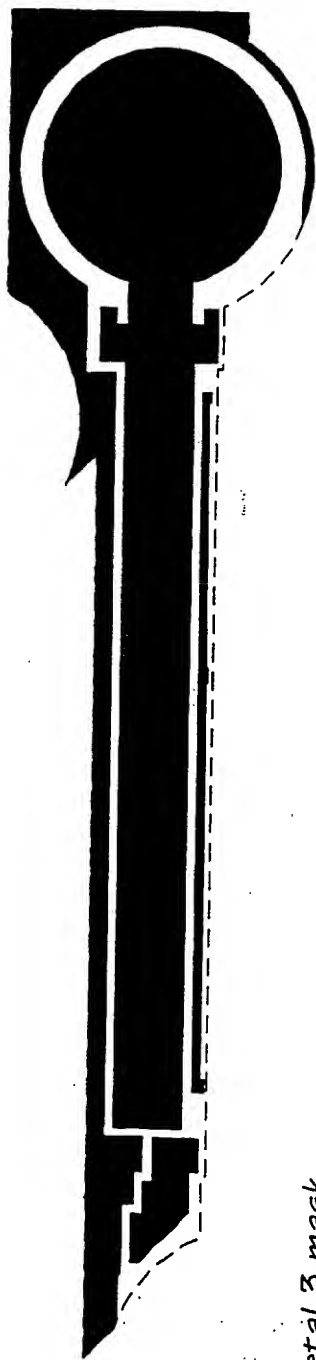


FIG. 47

Metal 3 mask

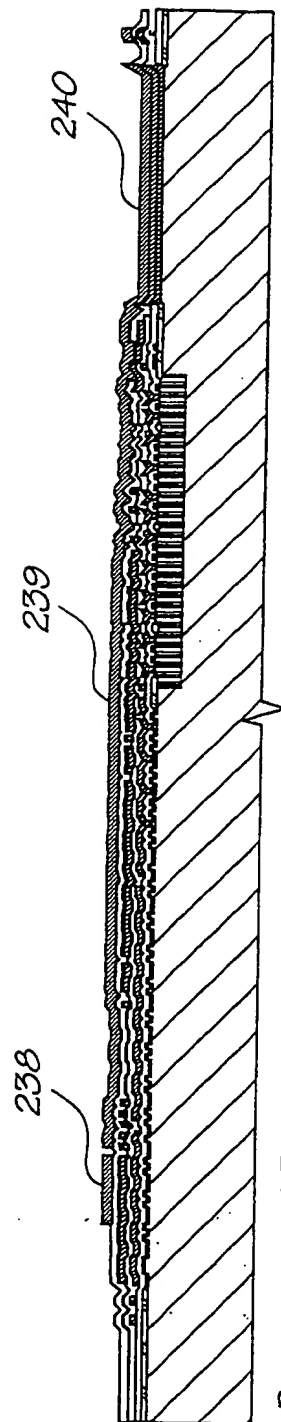


FIG. 48

Deposit metal 3

FIG. 47

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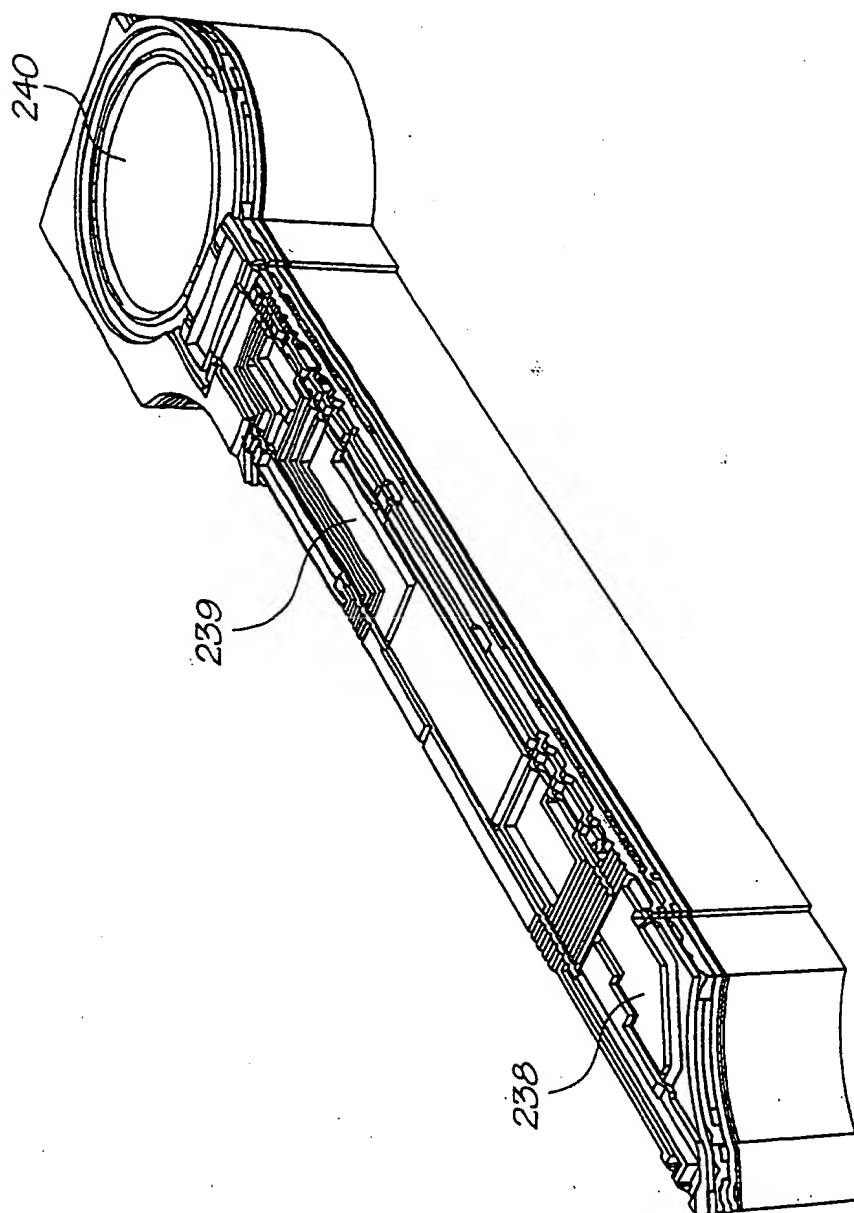
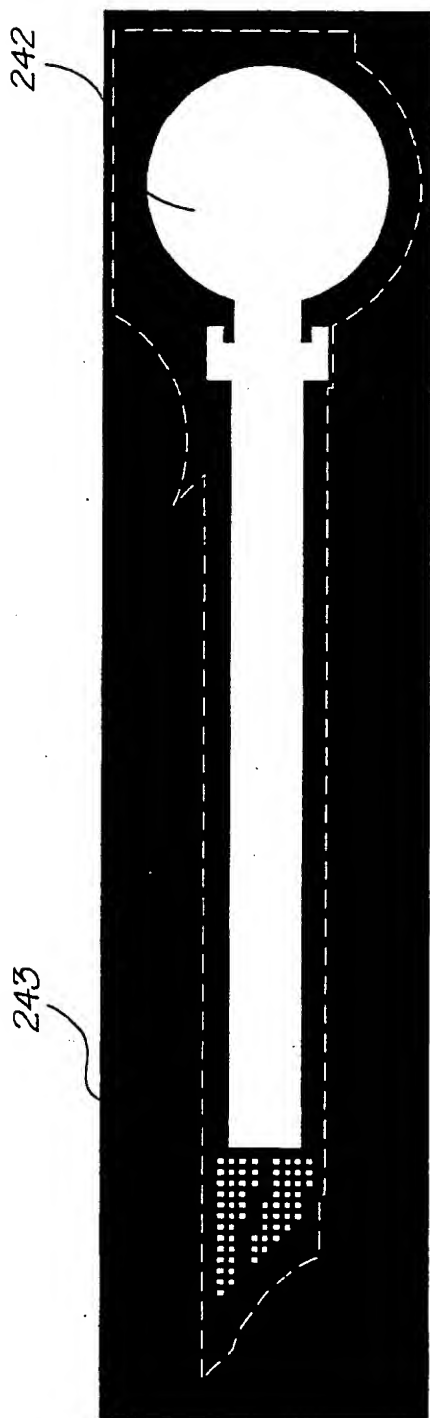


FIG. 49

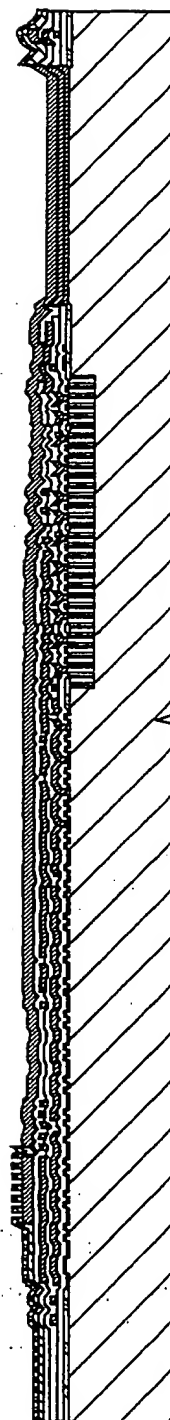
FIG. 49

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Via 3 / Passivation mask

FIG. 50



Deposit passivation oxide & nitride, etch vias

FIG. 51

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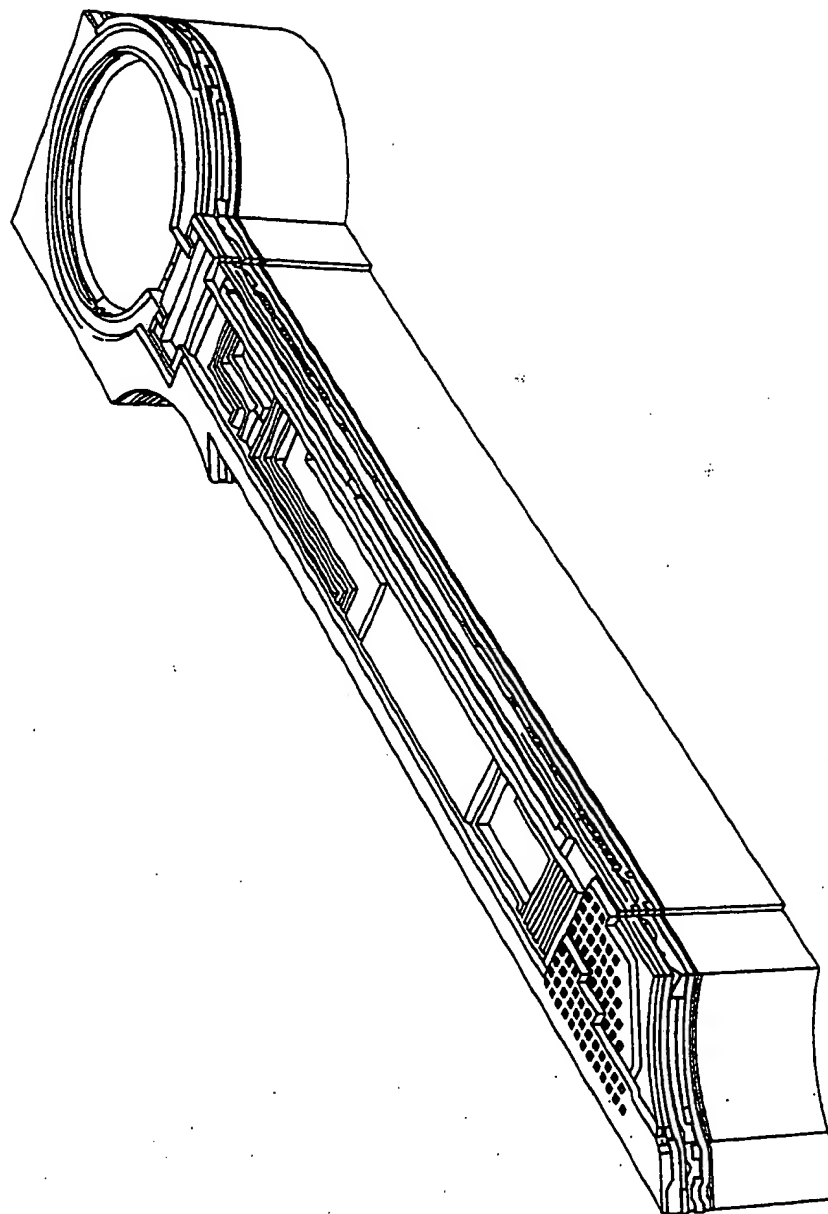
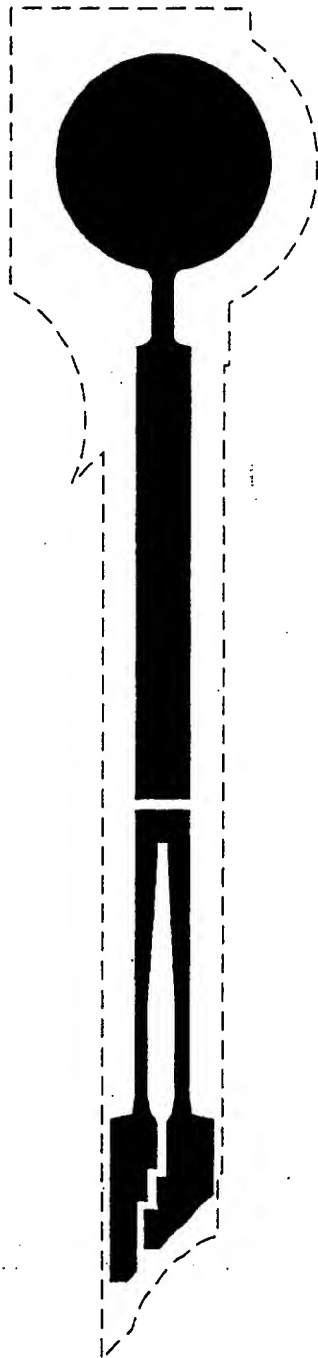


FIG. 52

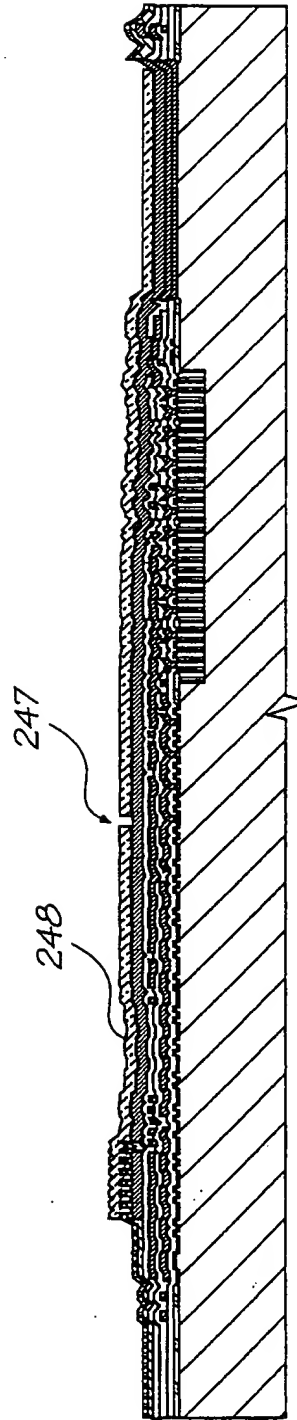
FIG. 52

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Heater mask

FIG. 53



Deposit heater TiN

FIG. 54

FIG. 53

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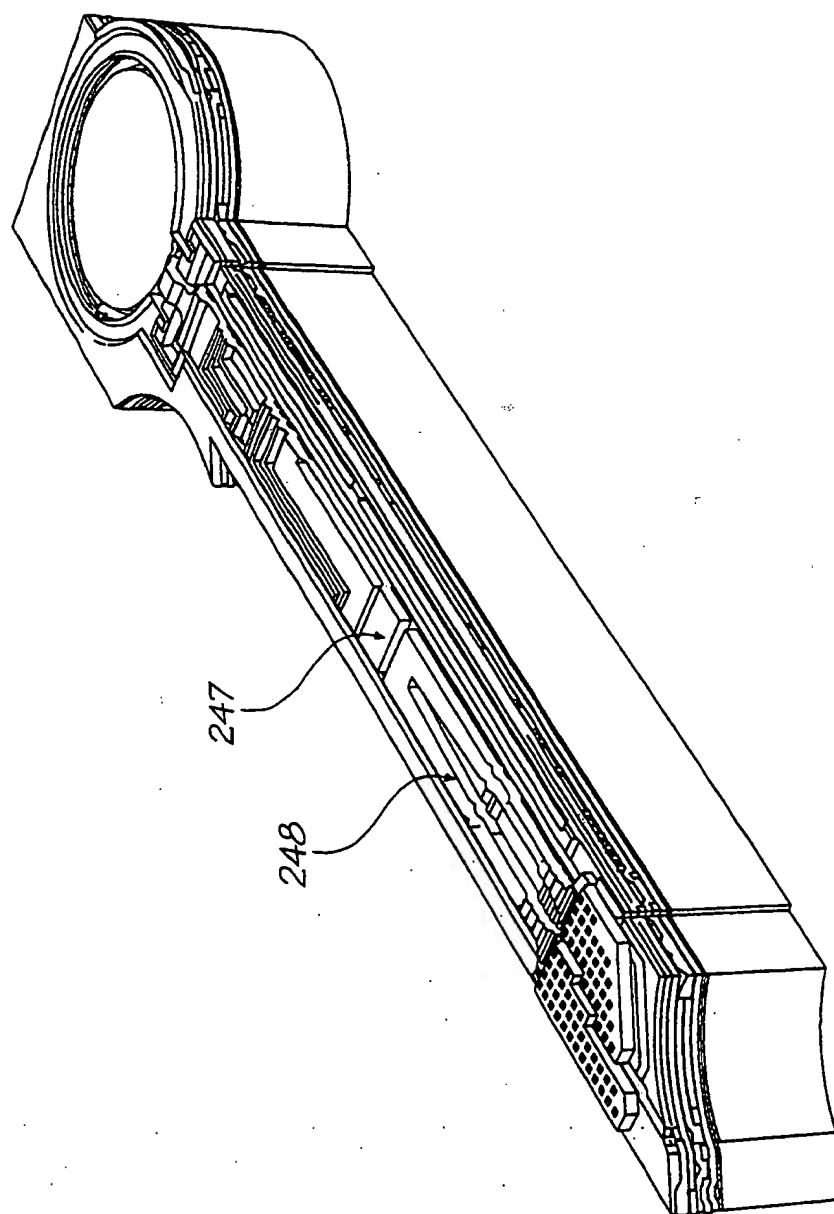
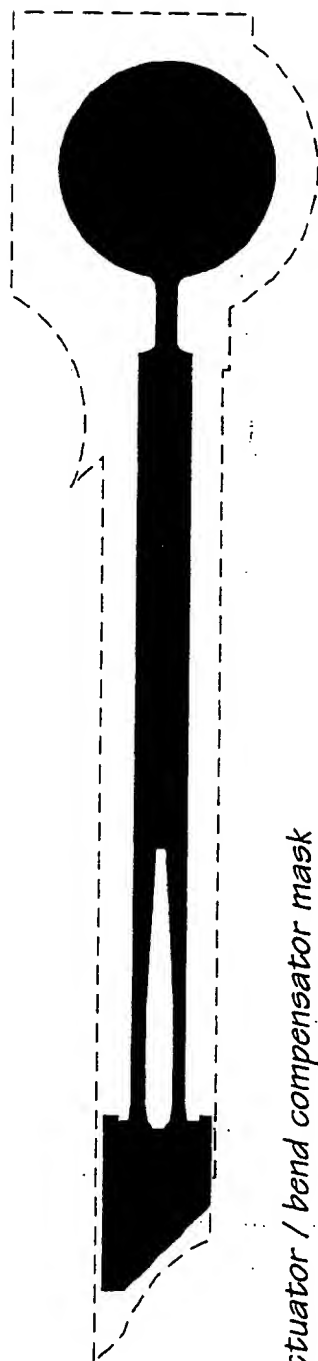


FIG. 55

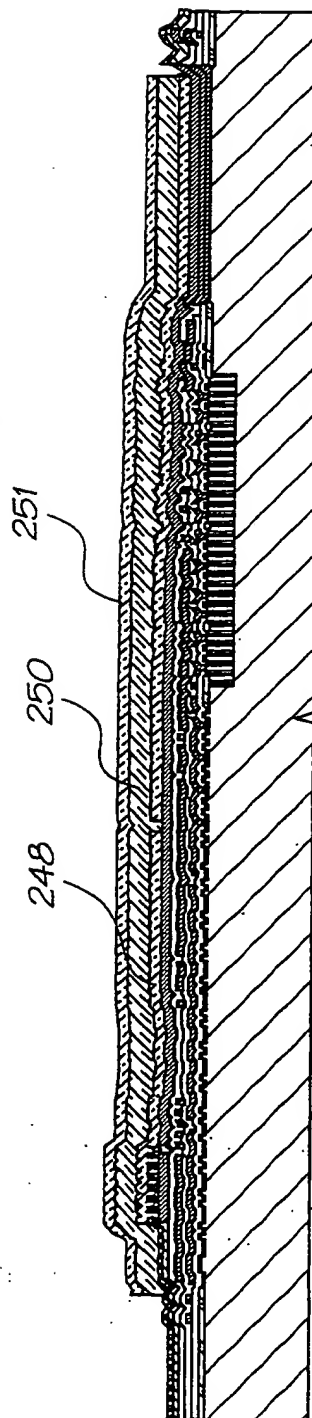
FIG. 55

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Actuator / bend compensator mask

FIG. 56



Deposit actuator glass and bend compensator TiN, etch together

FIG. 57

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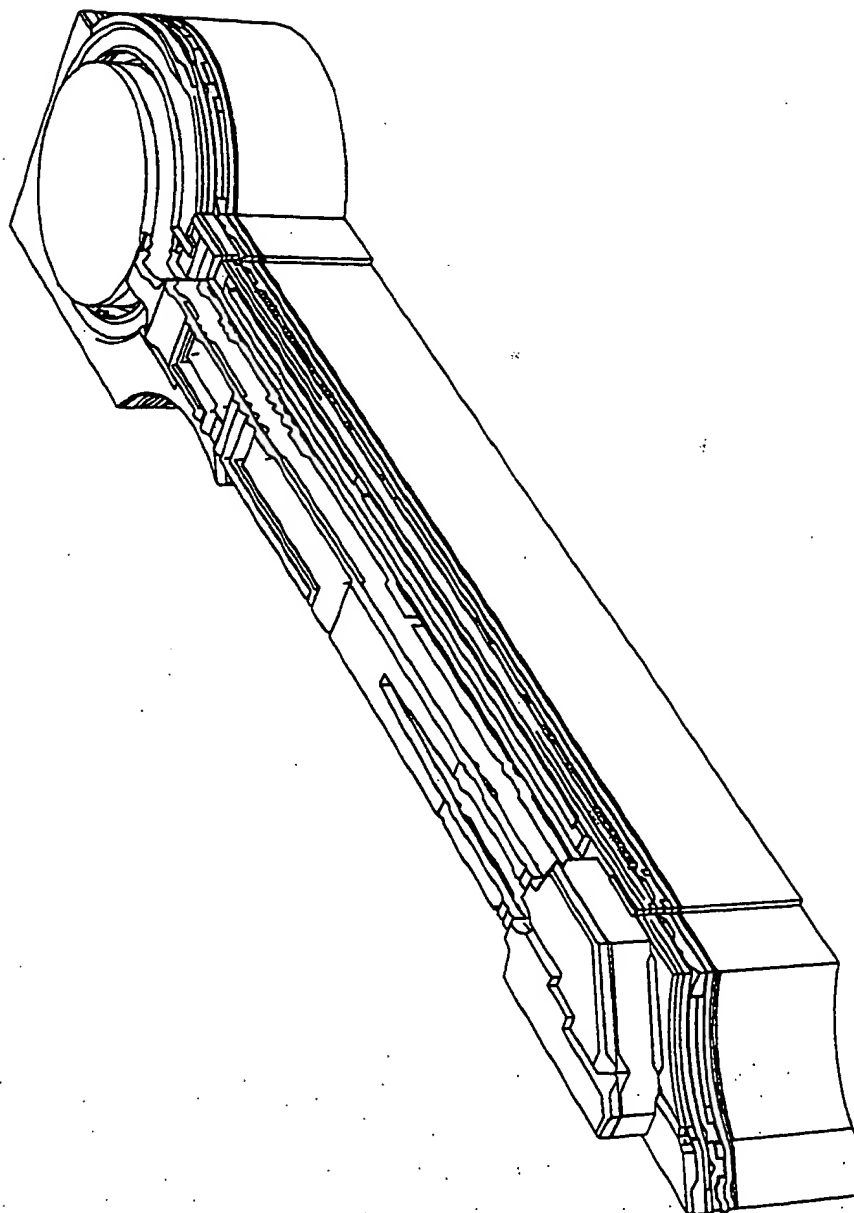
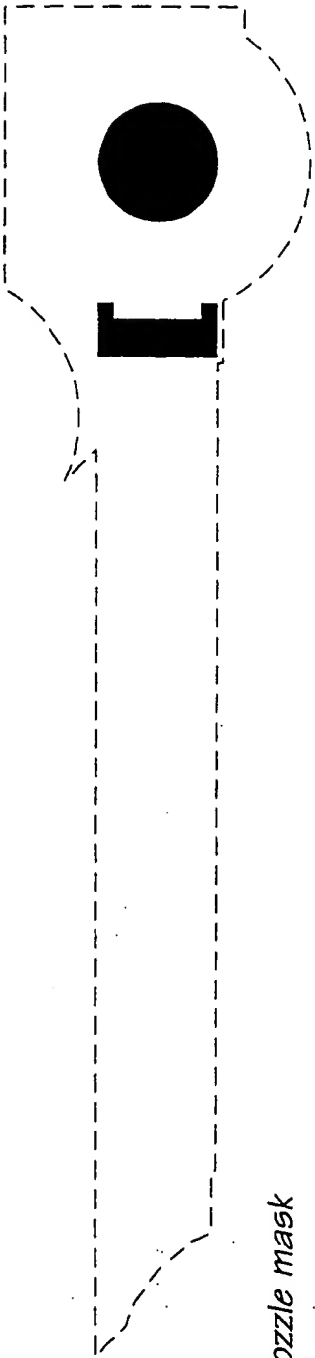


FIG. 58

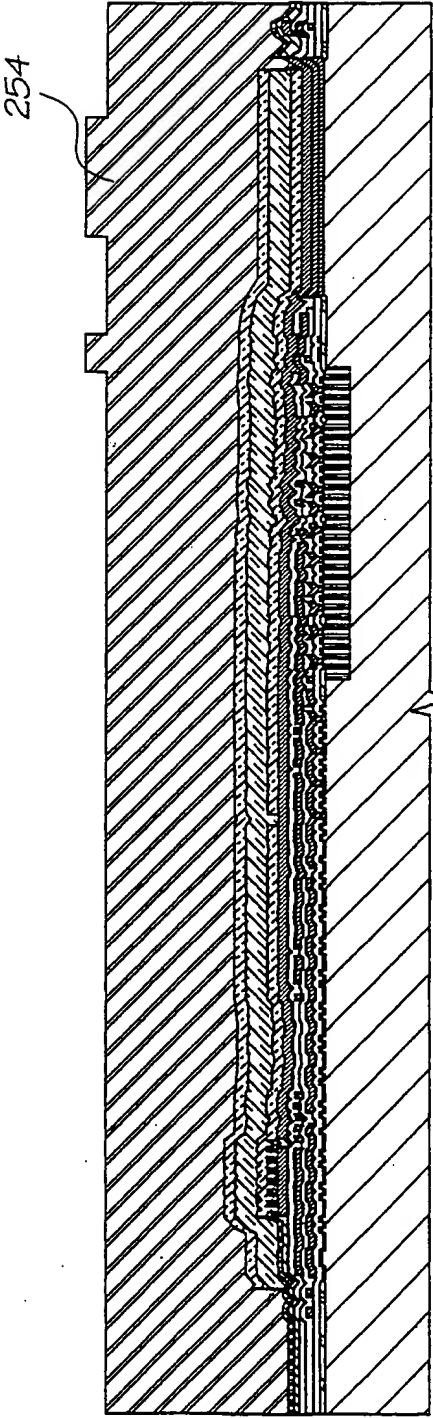
FIG. 58

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Nozzle mask

FIG. 59



Deposit sacrificial layer, etch nozzles

FIG. 60

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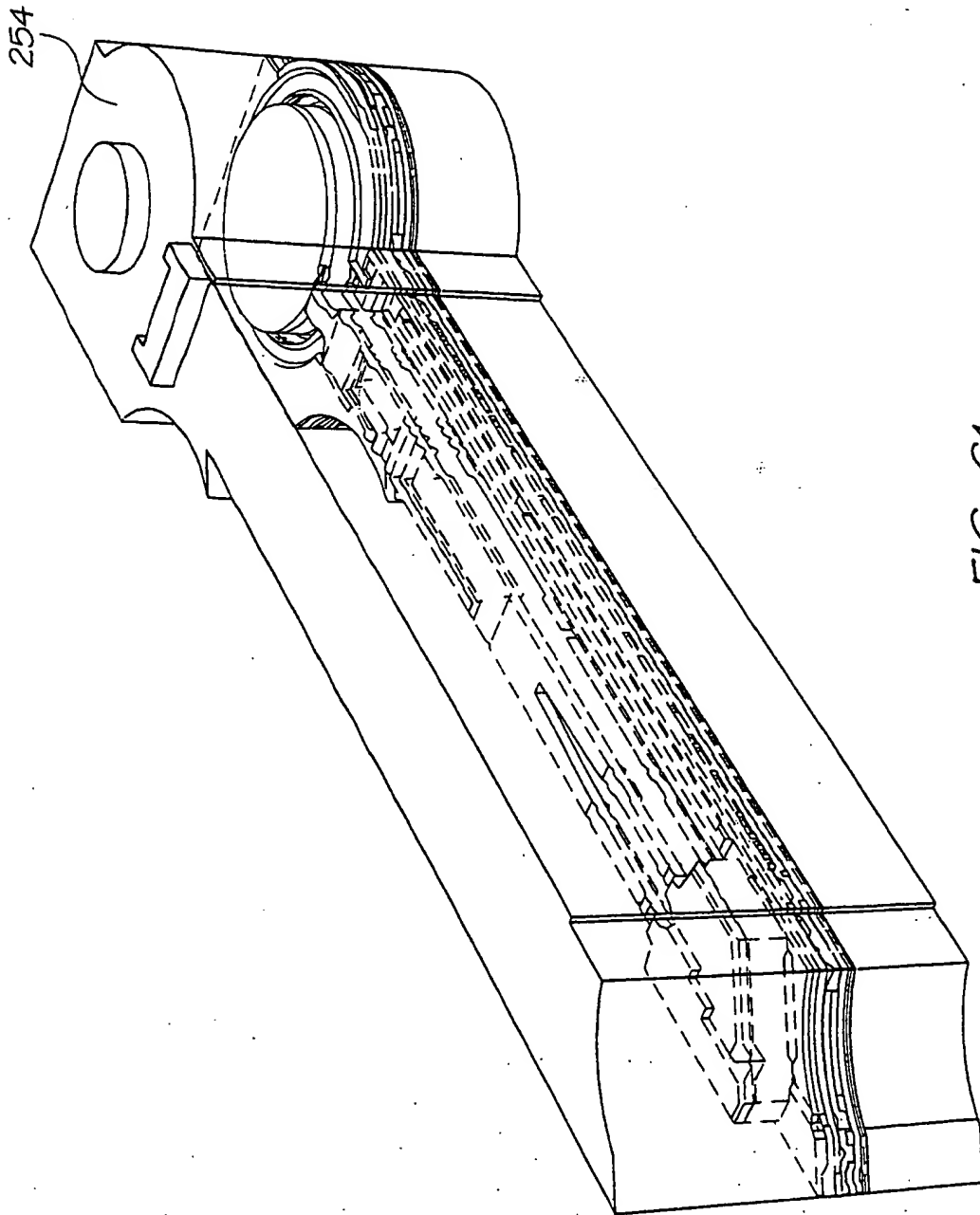
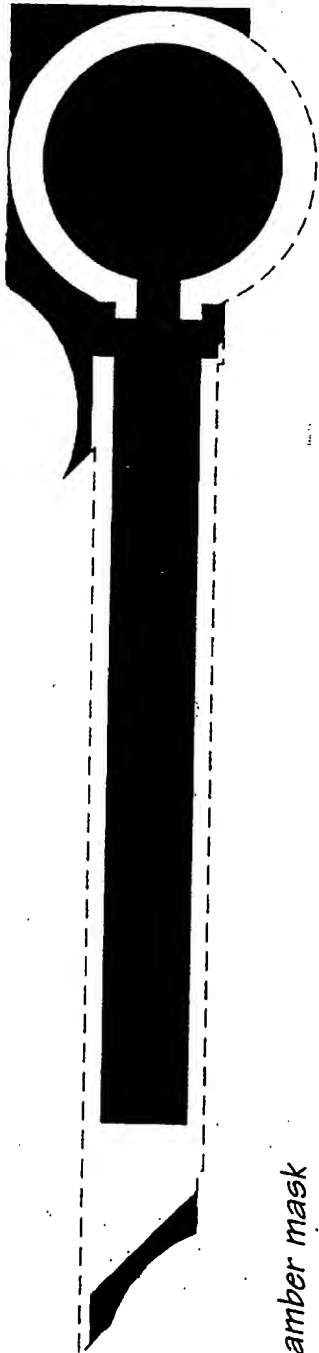


FIG. 61

FIG. 61

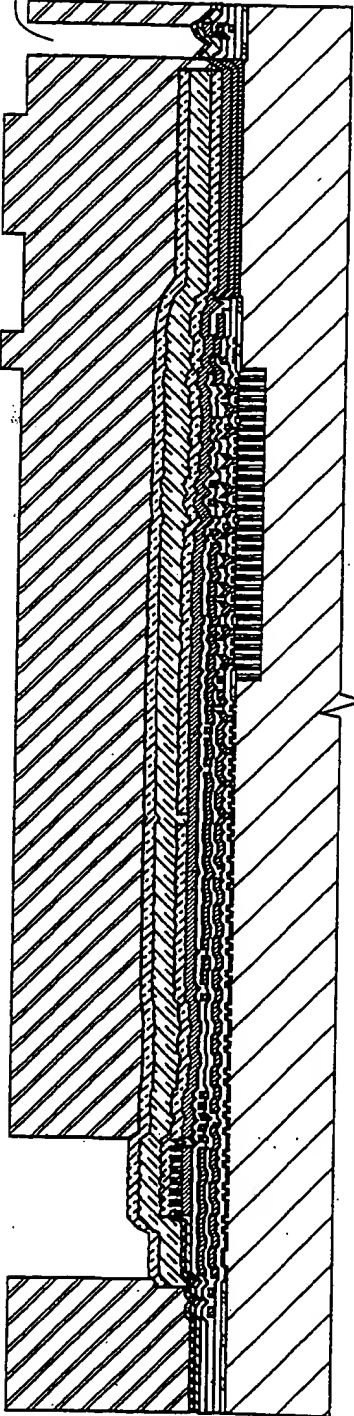
FIG. 62



Chamber mask

FIG. 62

255



Etch chambers in sacrificial layer

FIG. 63

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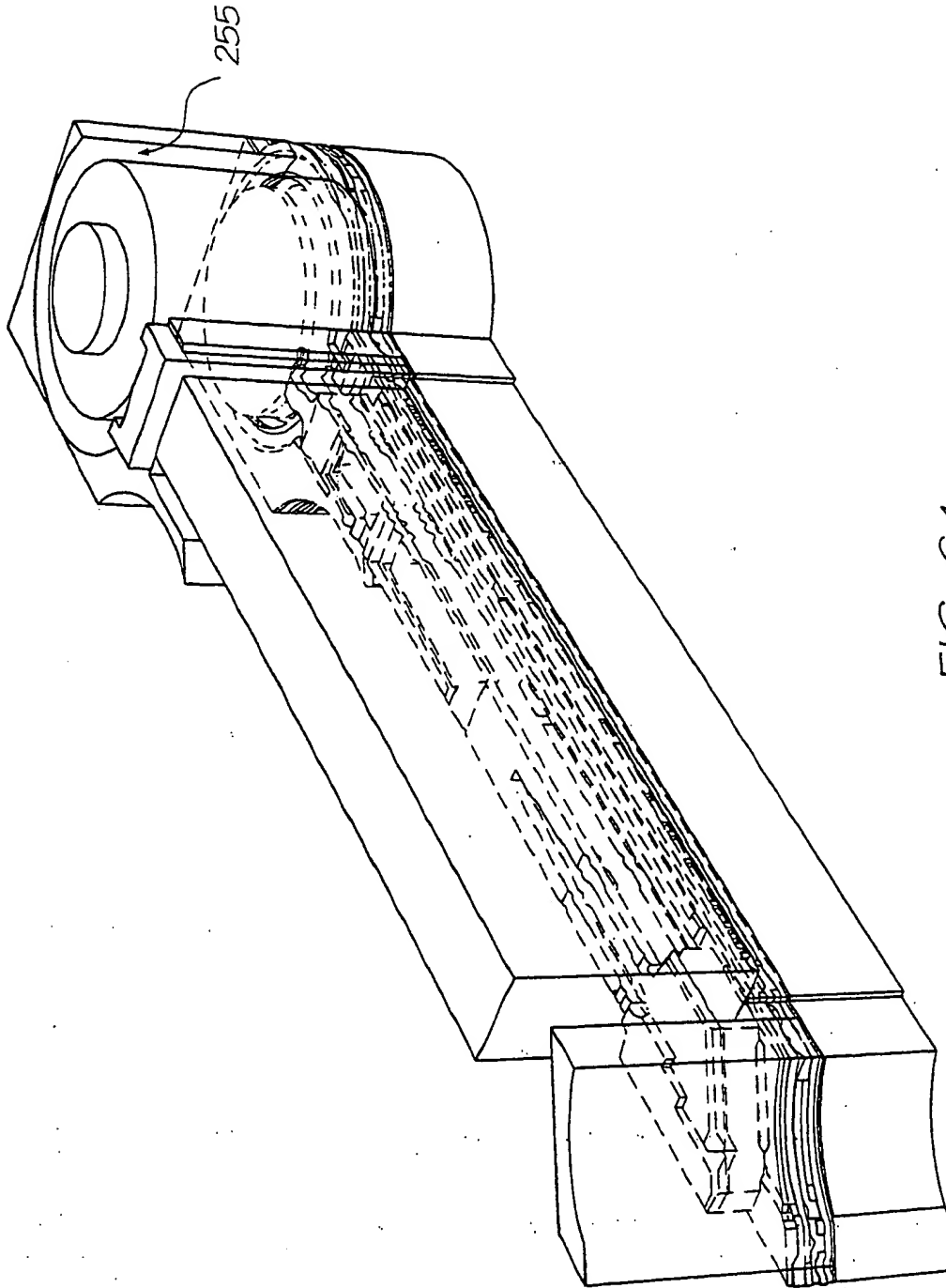


FIG. 64

FIG. 64

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FIG. 64

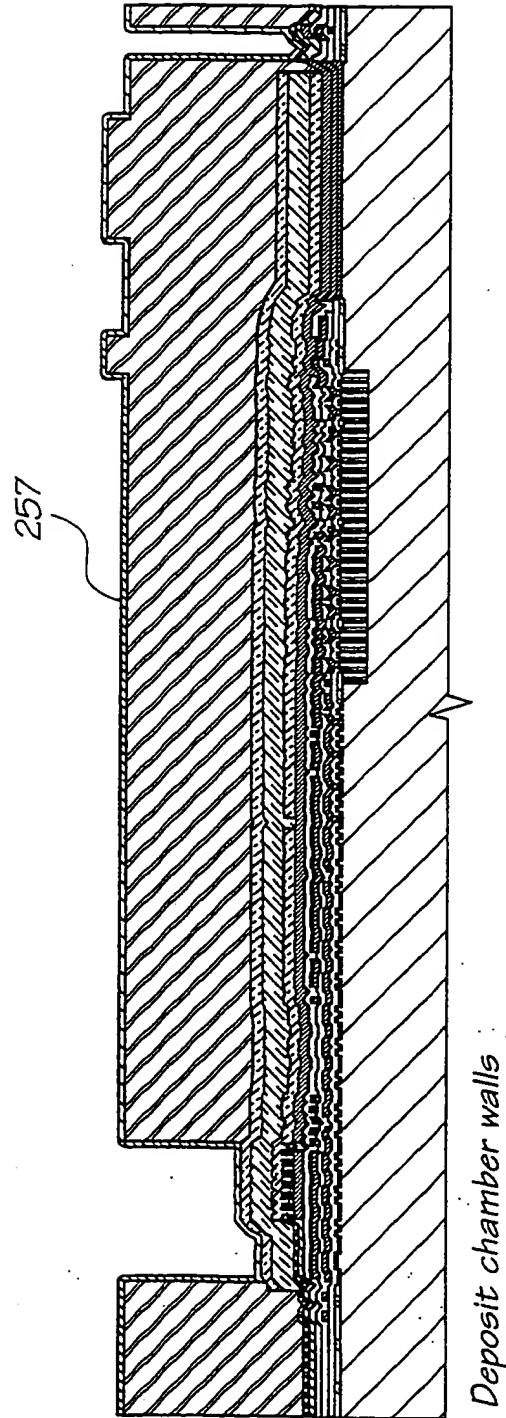
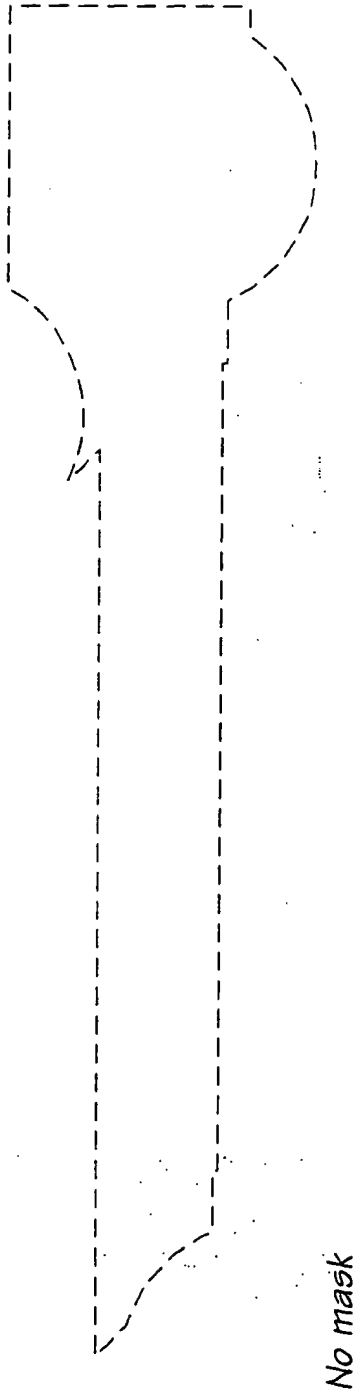


FIG. 65

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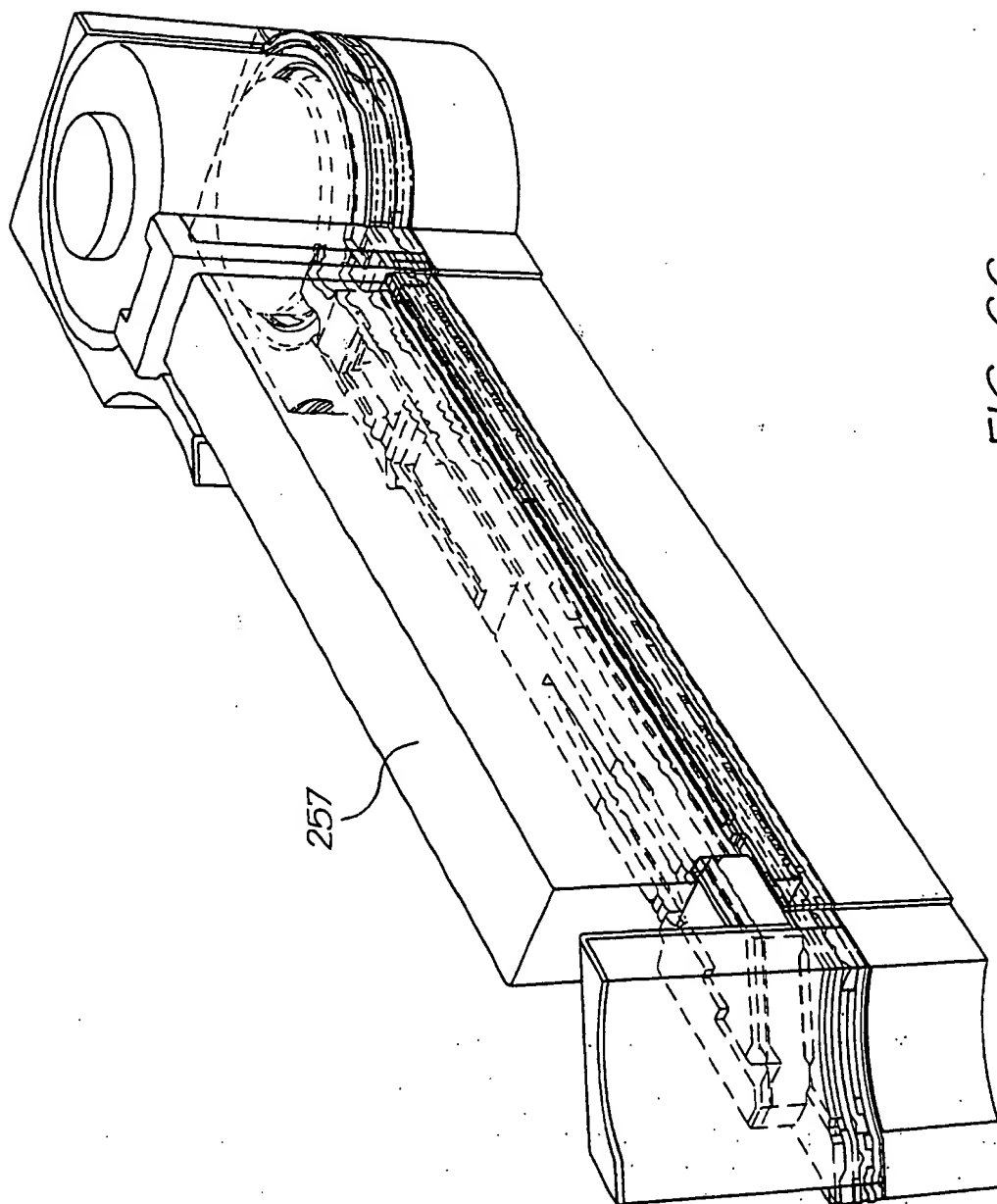
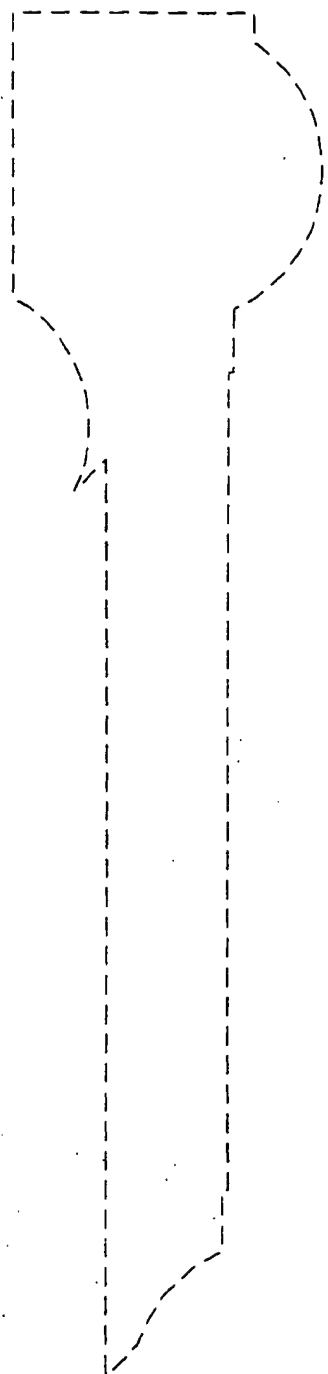


FIG. 66

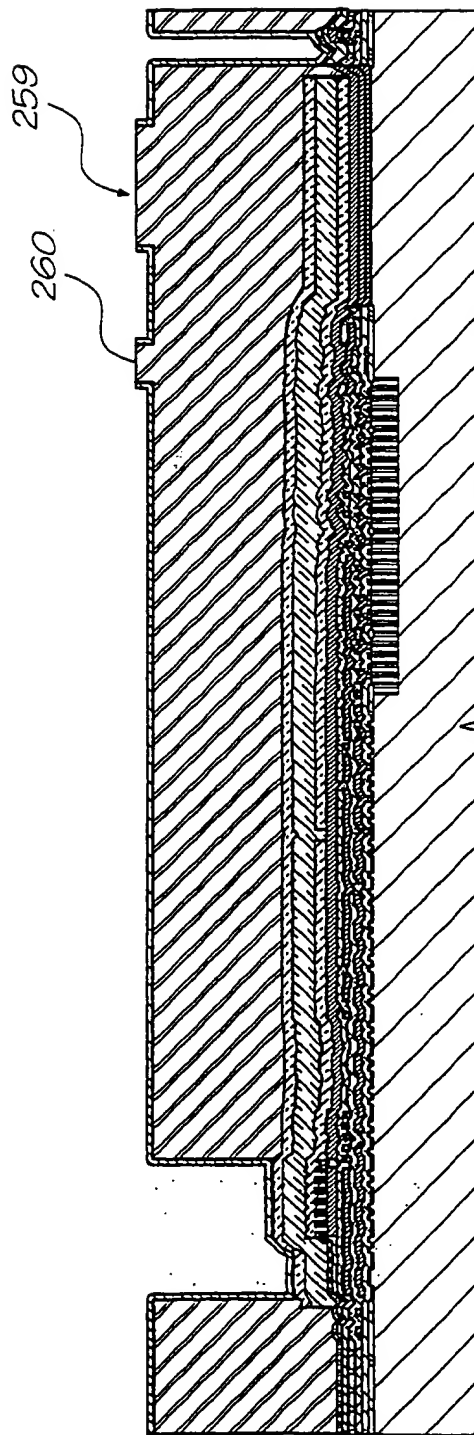
FIG. 66

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FIG. 67



No mask



Form self-aligned nozzles using CMP

FIG. 67

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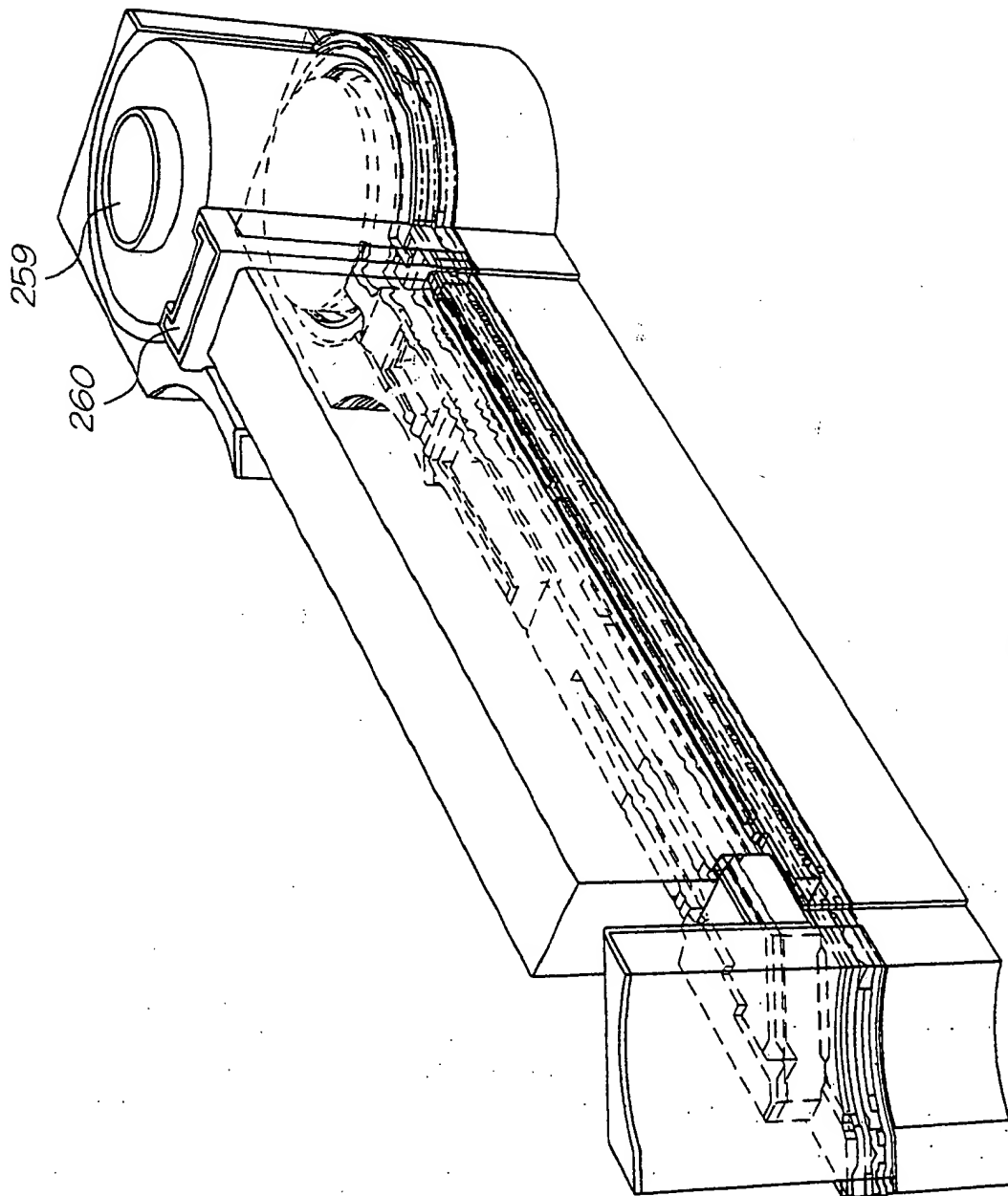
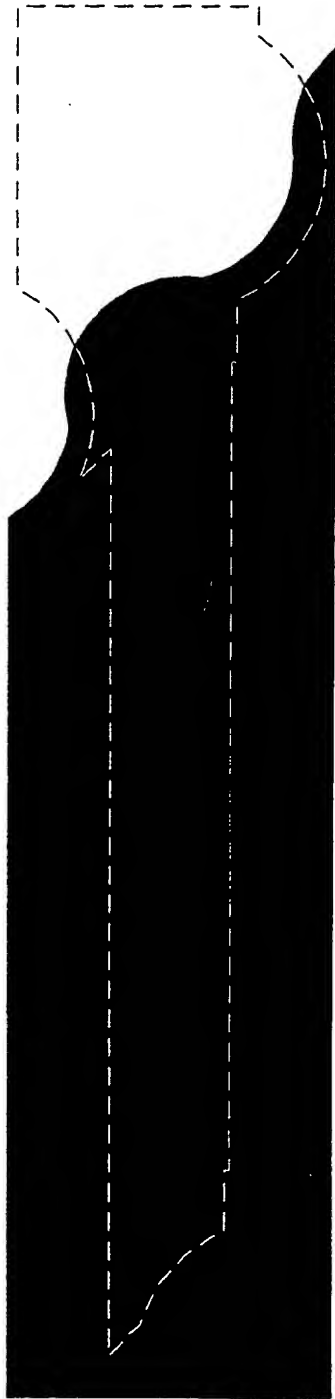


FIG. 68

FIG. 68

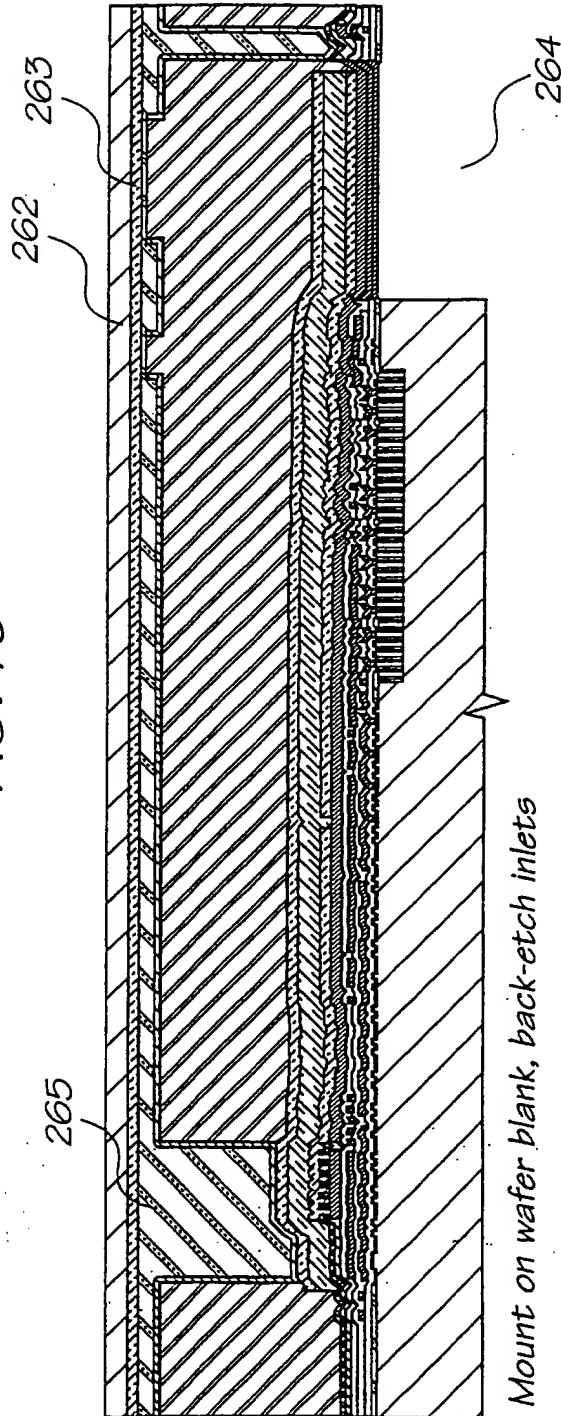
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FIG. 69



Back-etch inlet mask

FIG. 70



Mount on wafer blank, back-etch inlets

FIG. 69

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FIG. 70

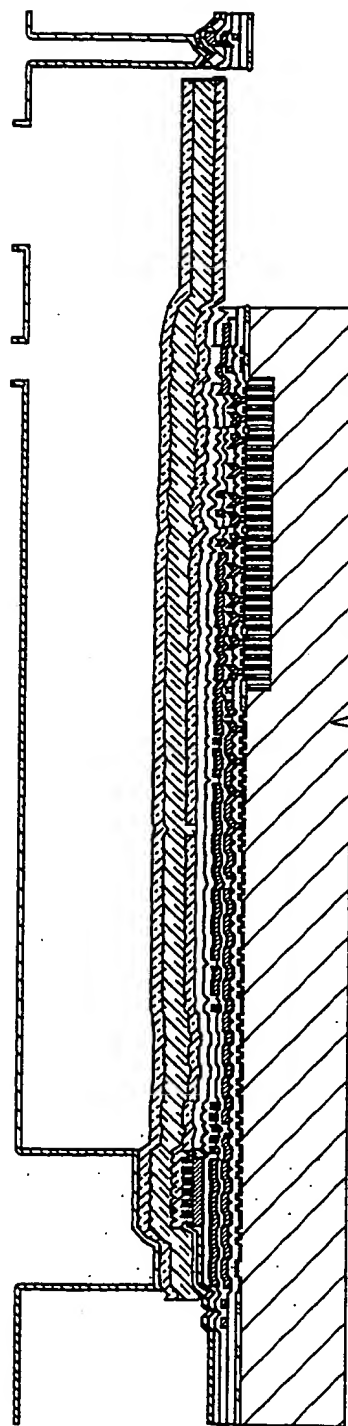
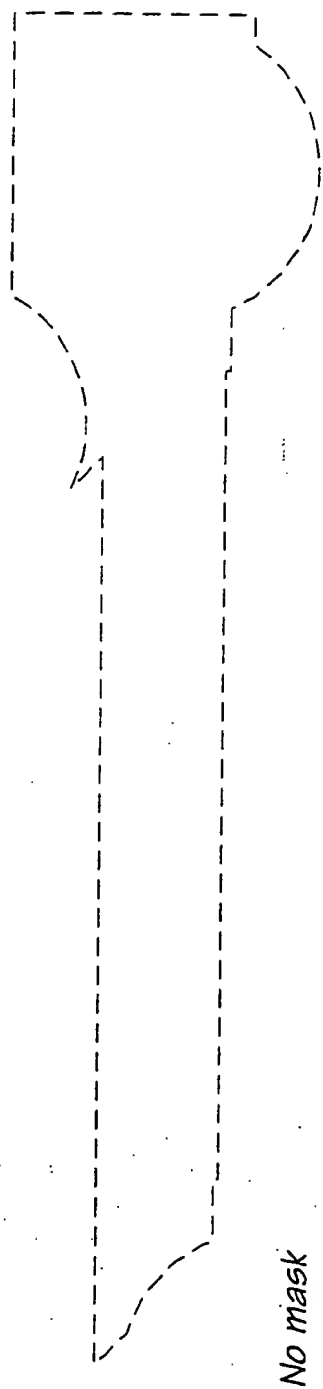


FIG. 71

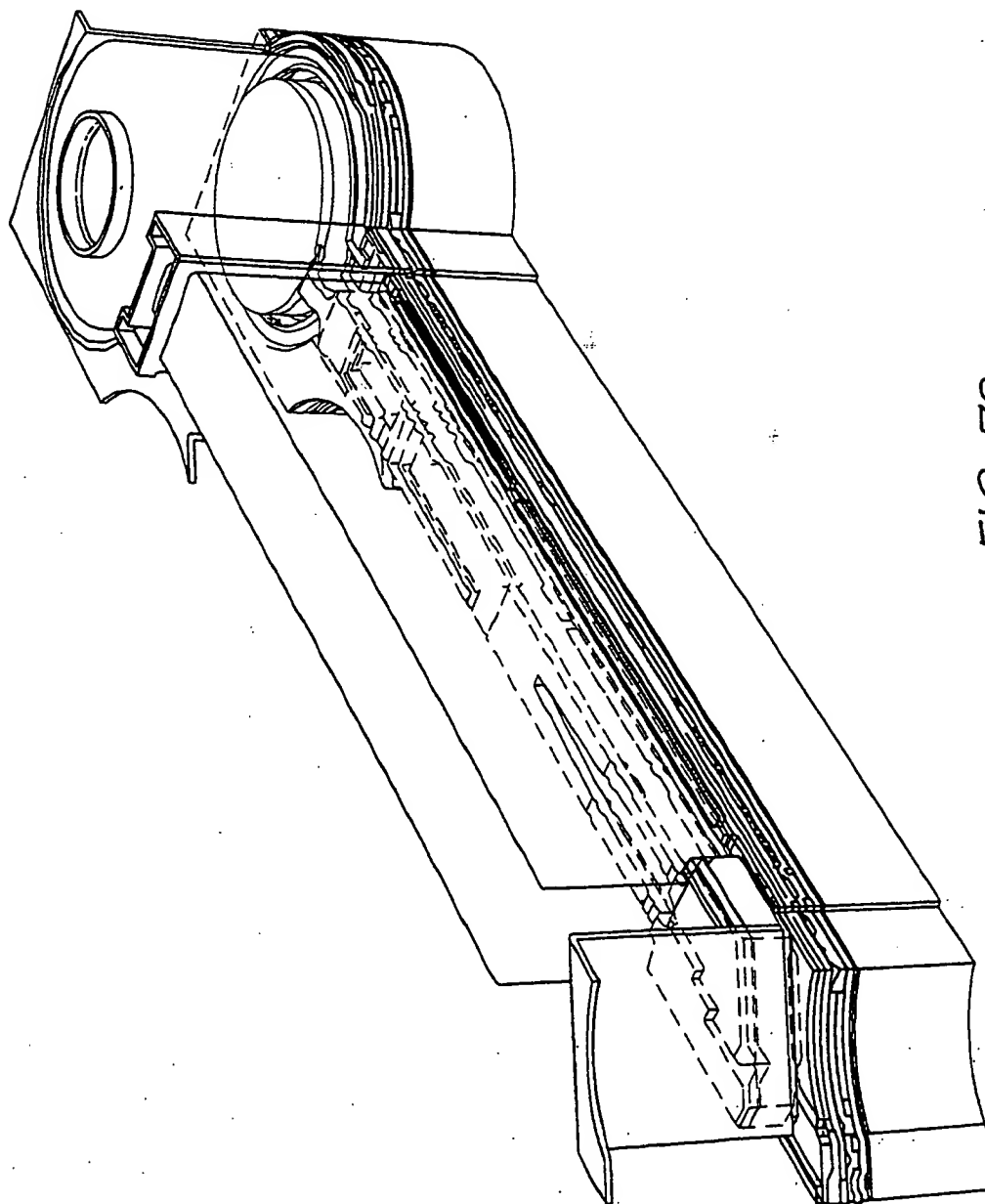


FIG. 72

FIG. 72

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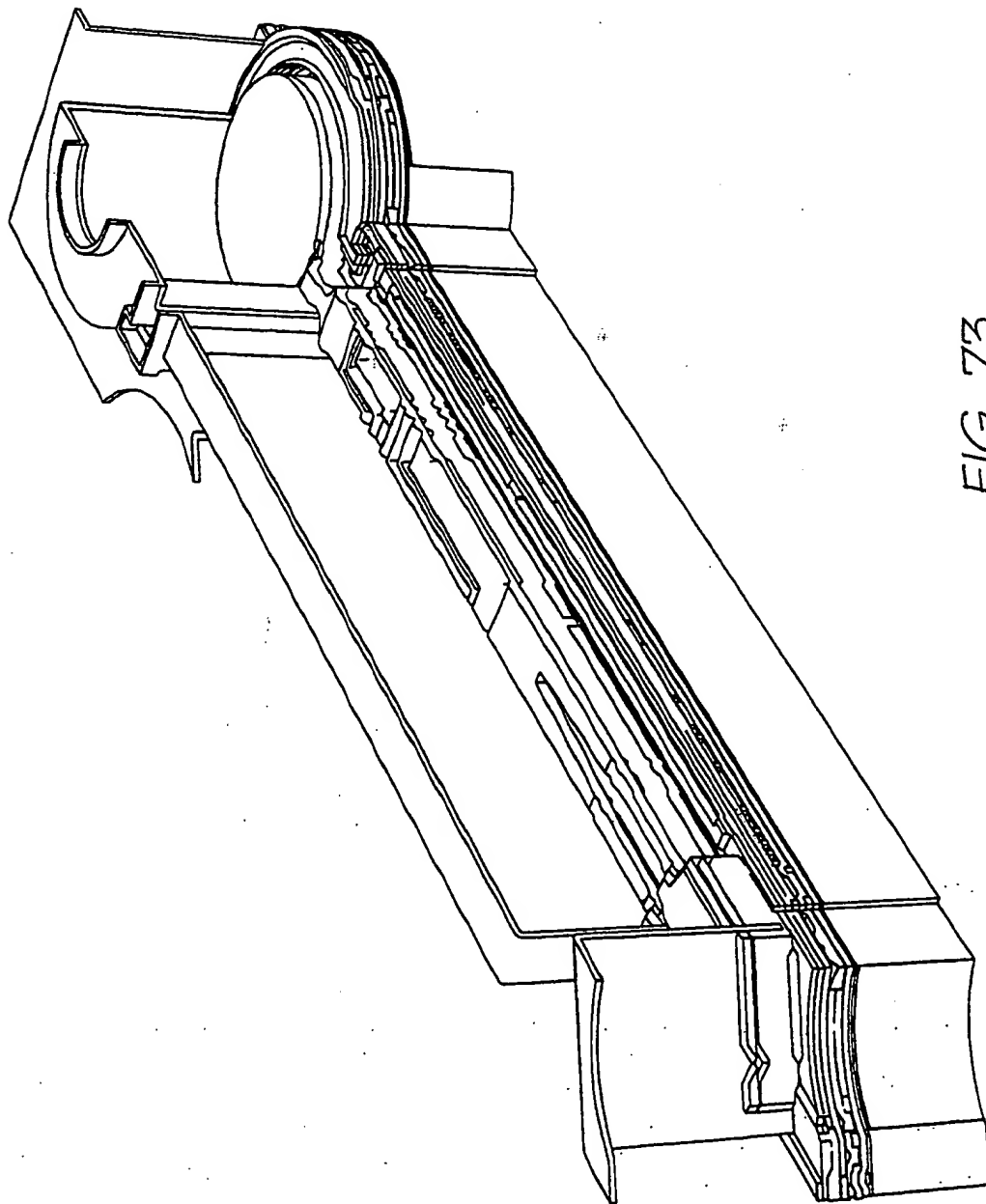
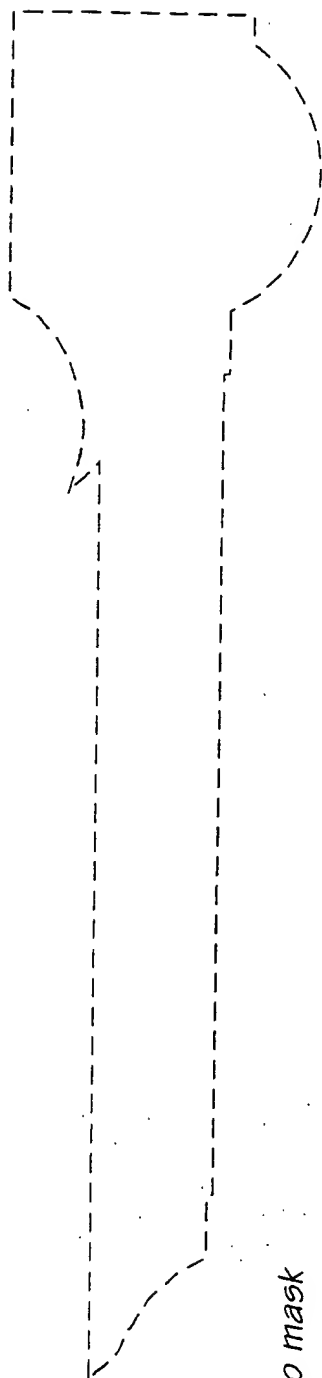


FIG. 73

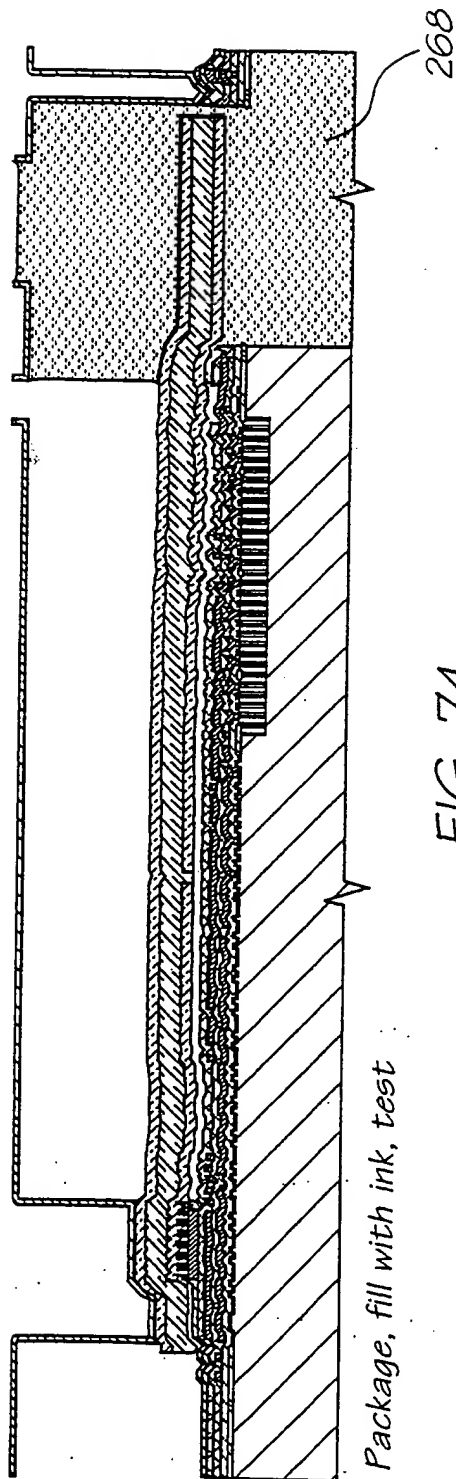
FIG. 73

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FIG. 73



No mask



Package, fill with ink, test

FIG. 74

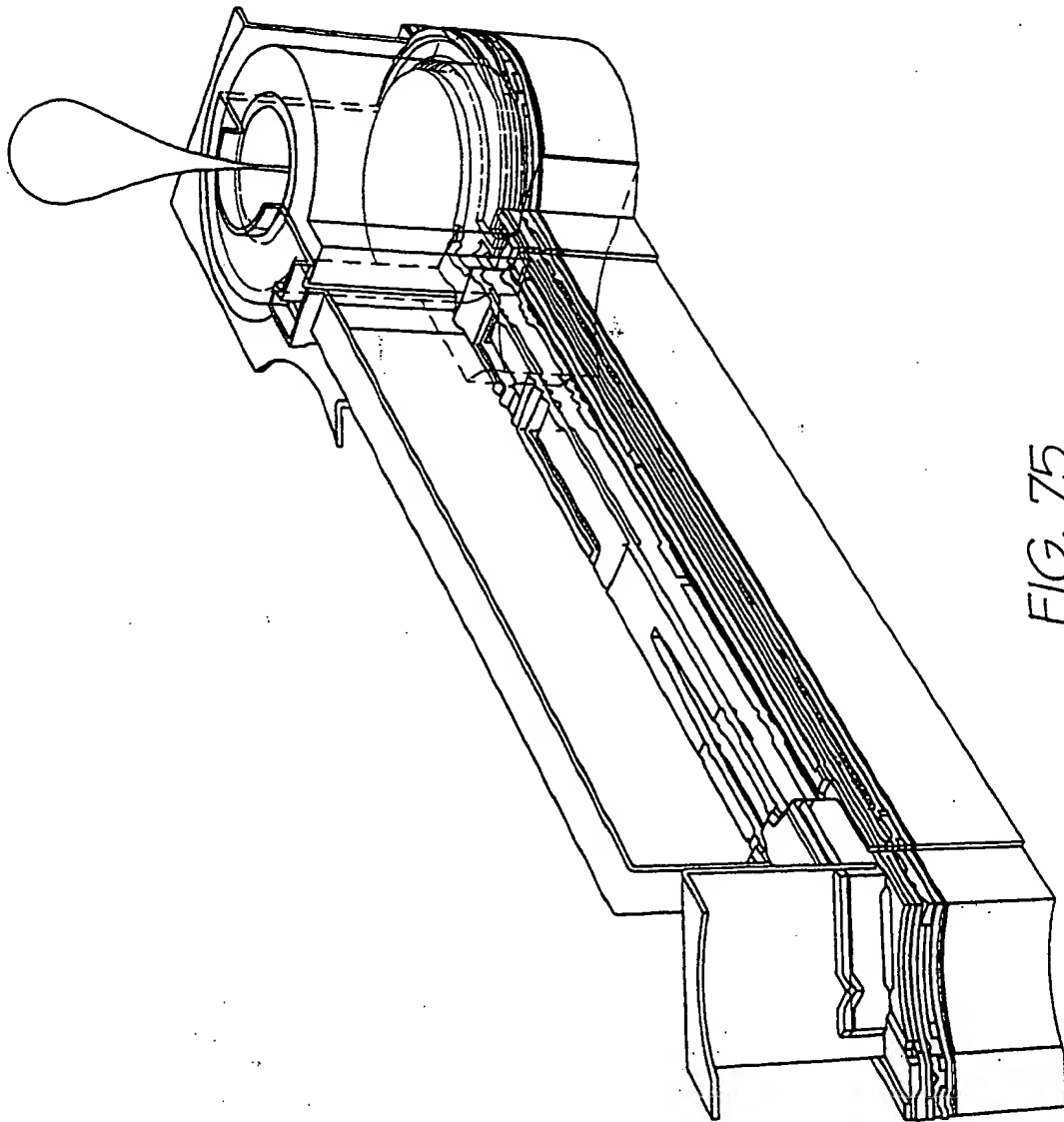


FIG. 75

FIG. 75

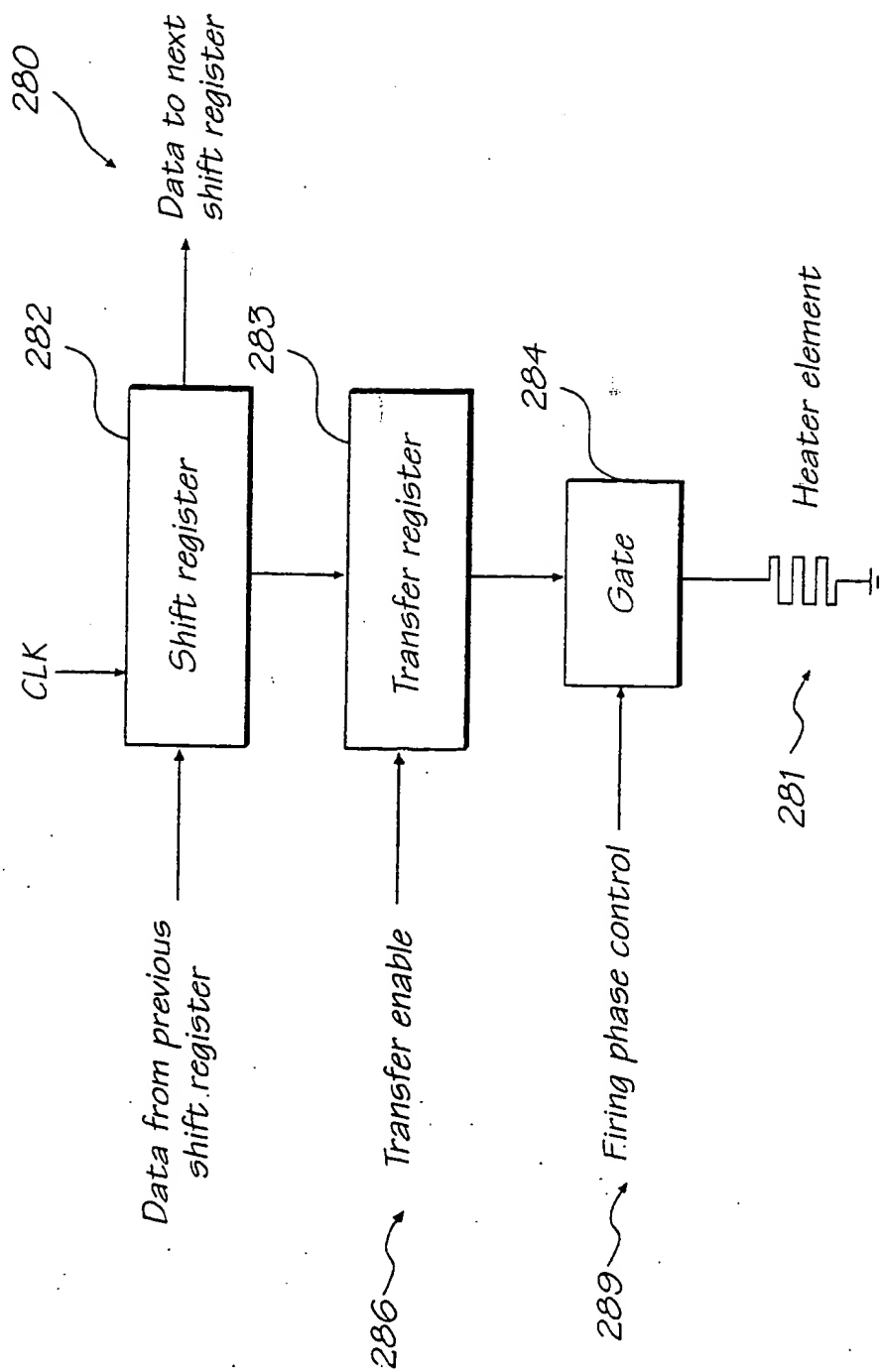


FIG. 76

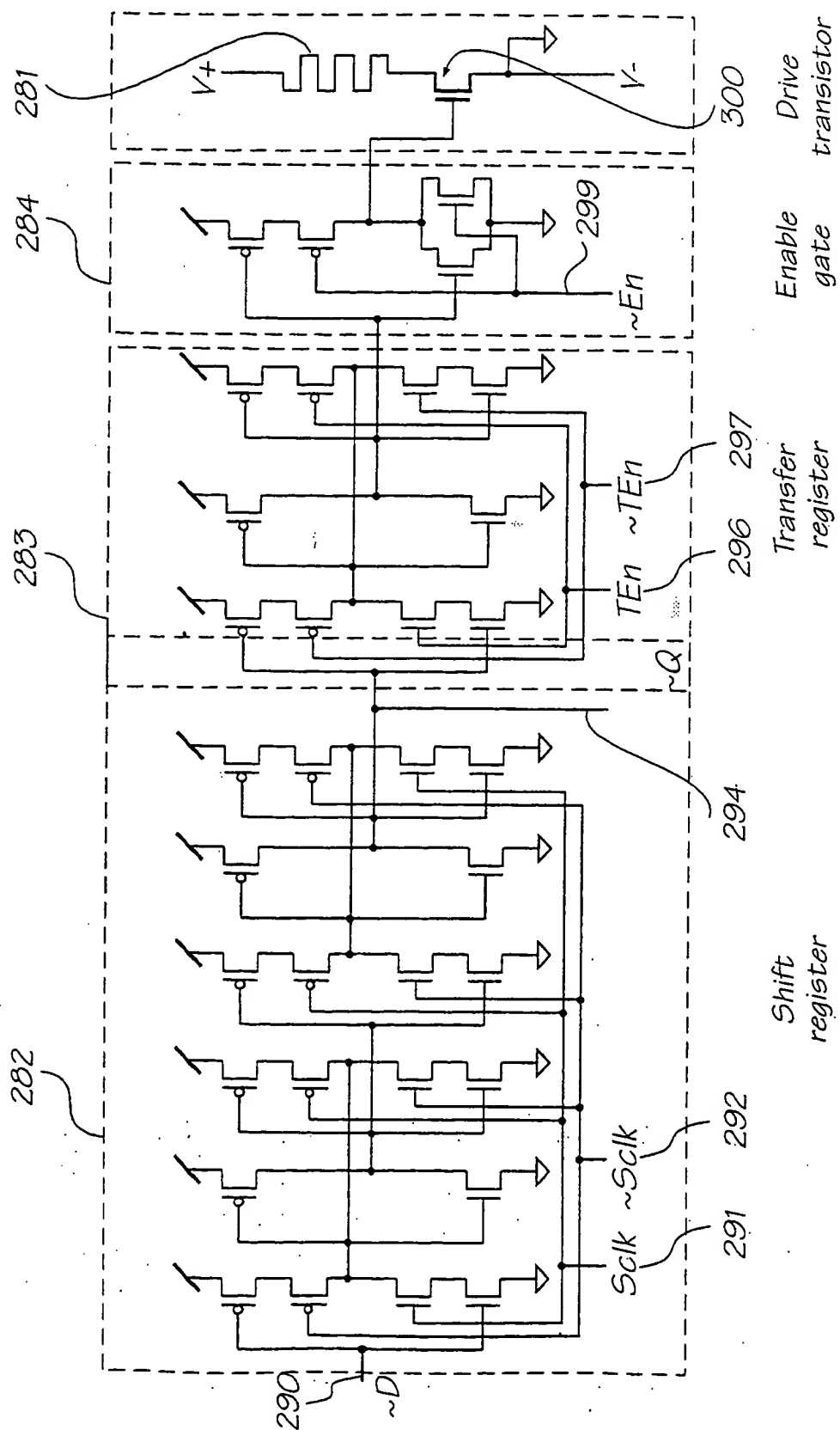


FIG. 77

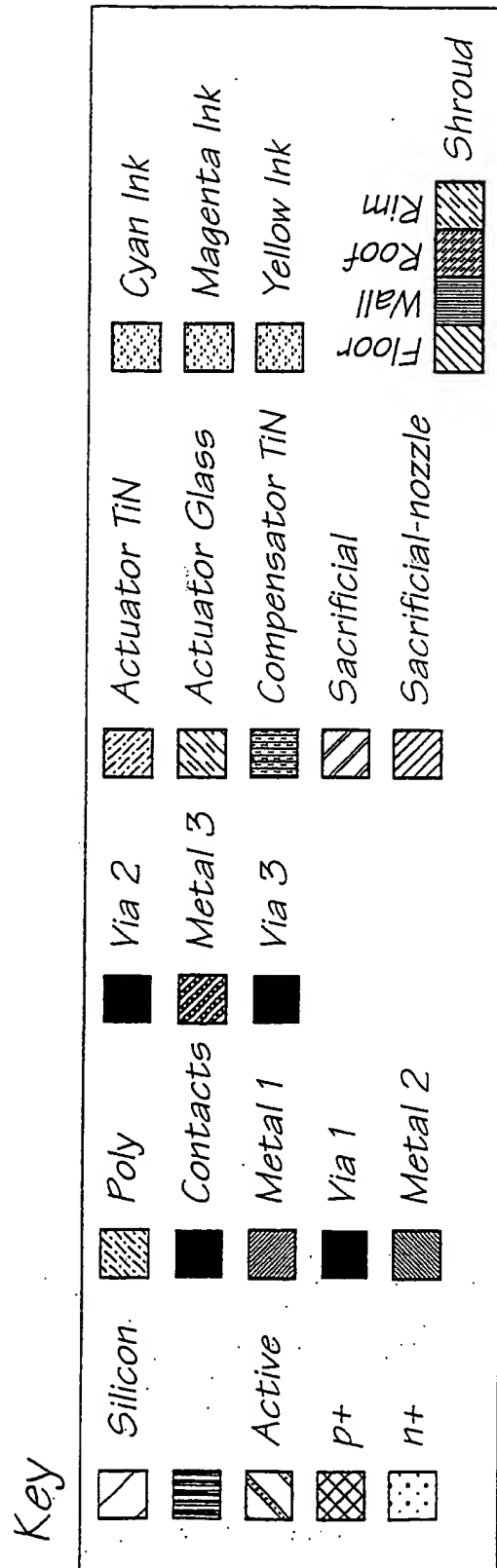


FIG. 78

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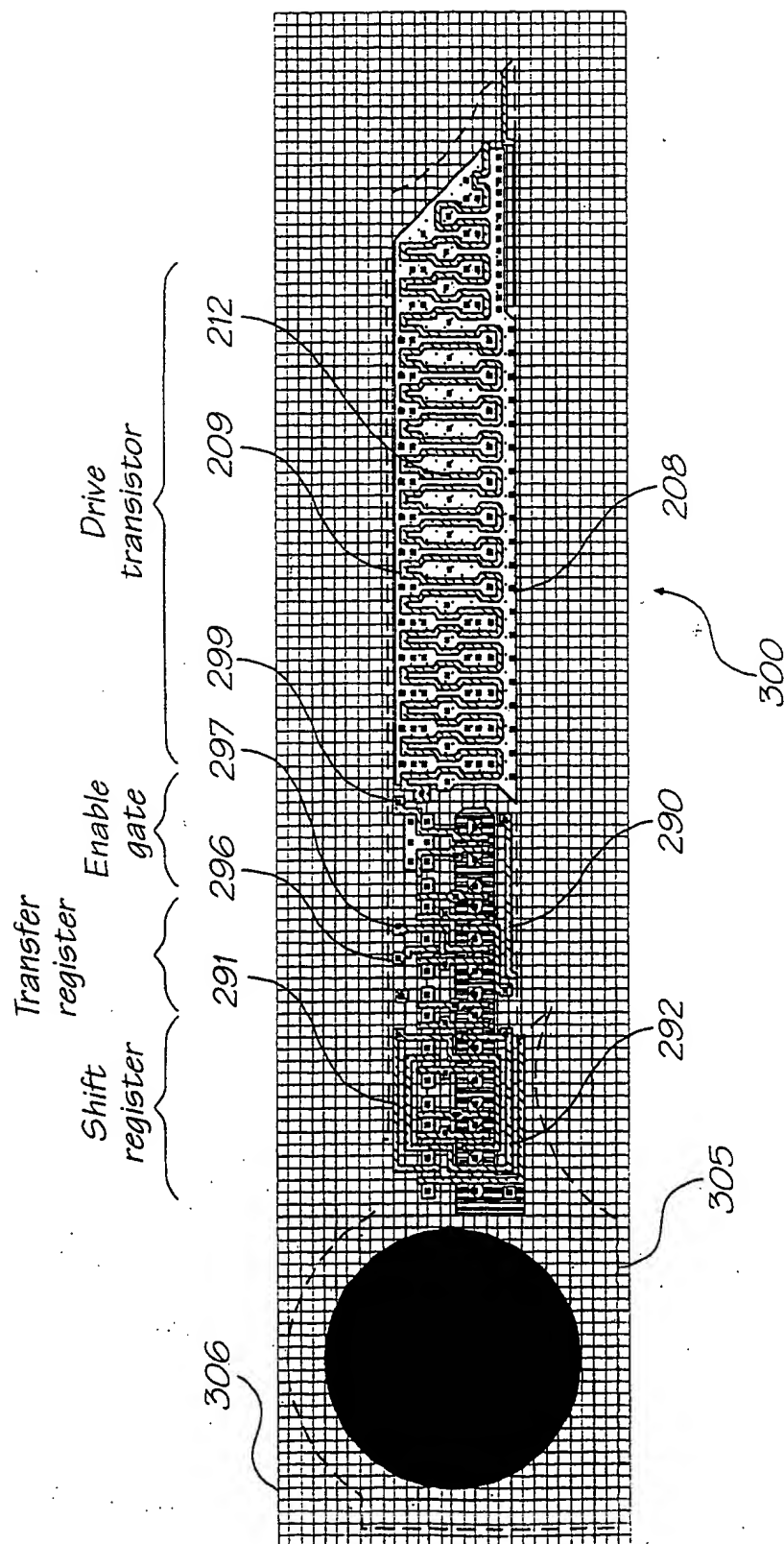


FIG. 79

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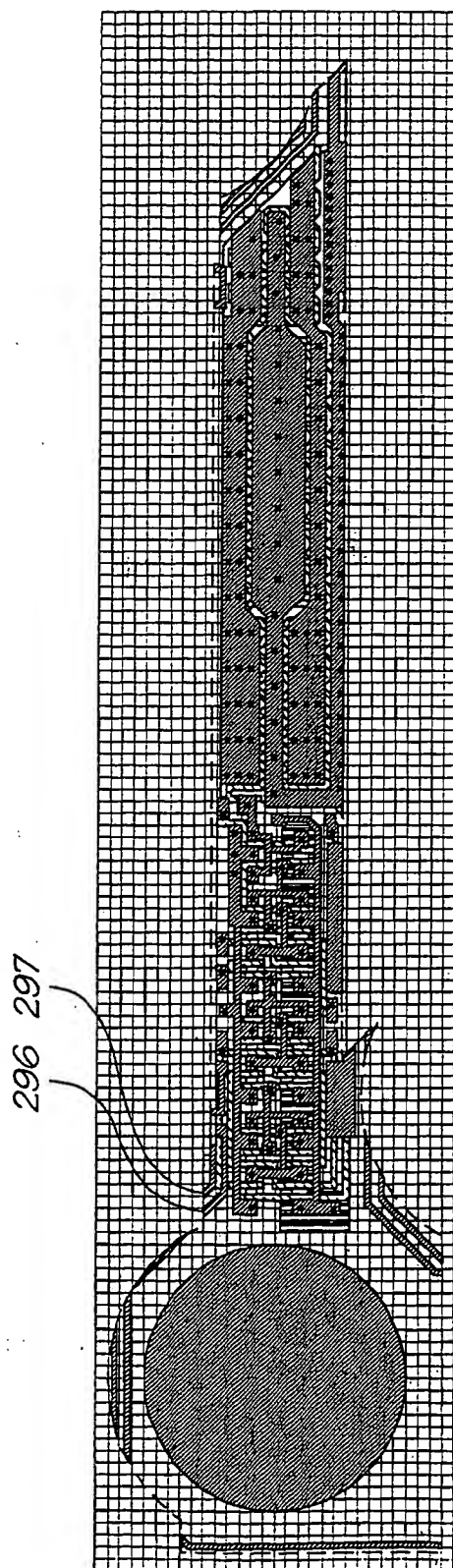


FIG. 80

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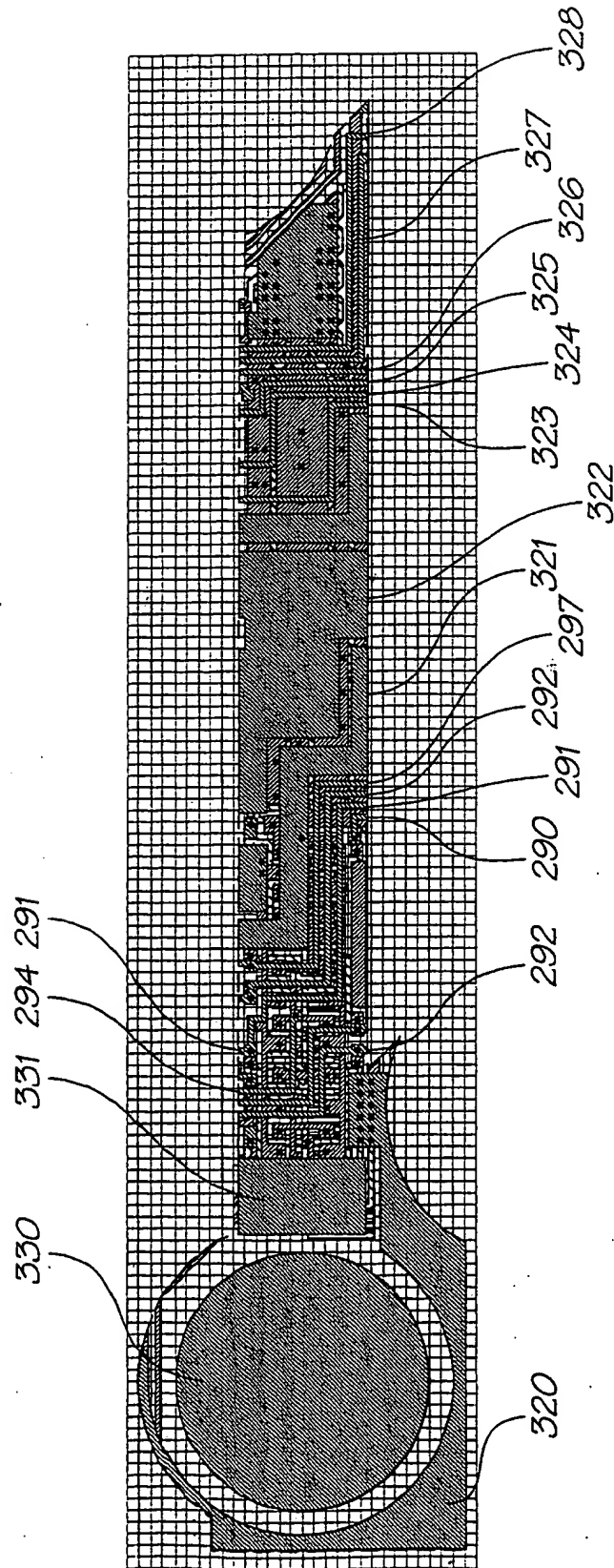


FIG. 81

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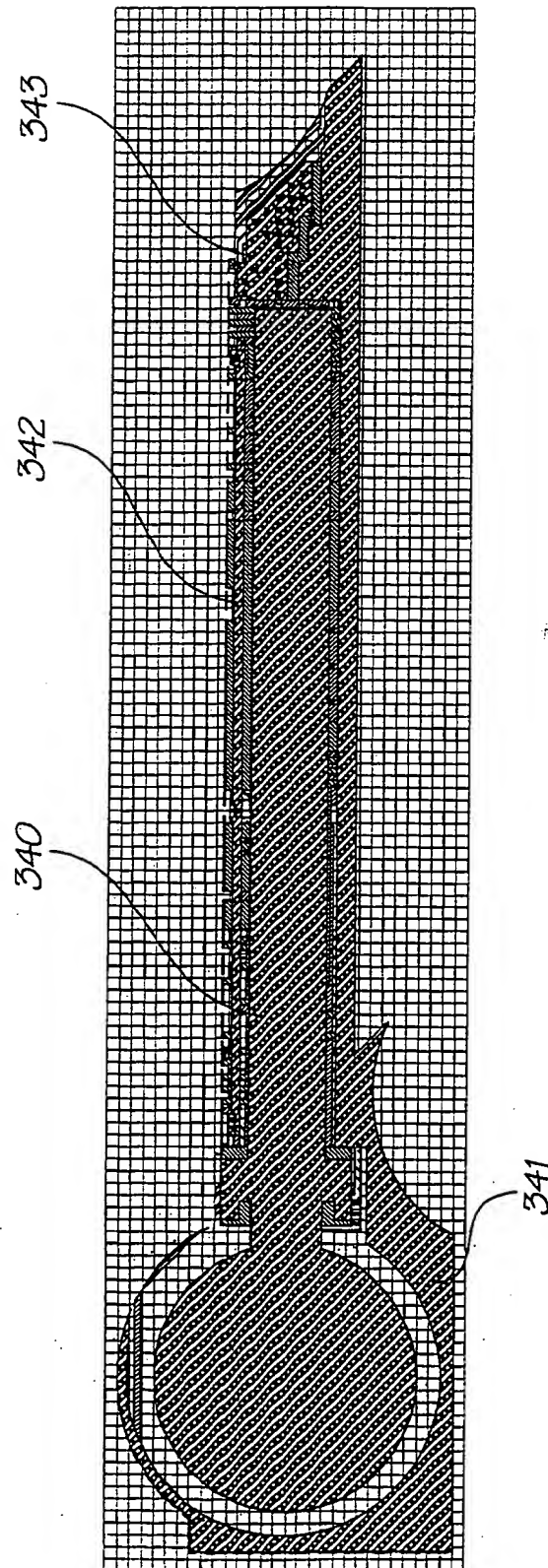


FIG. 82

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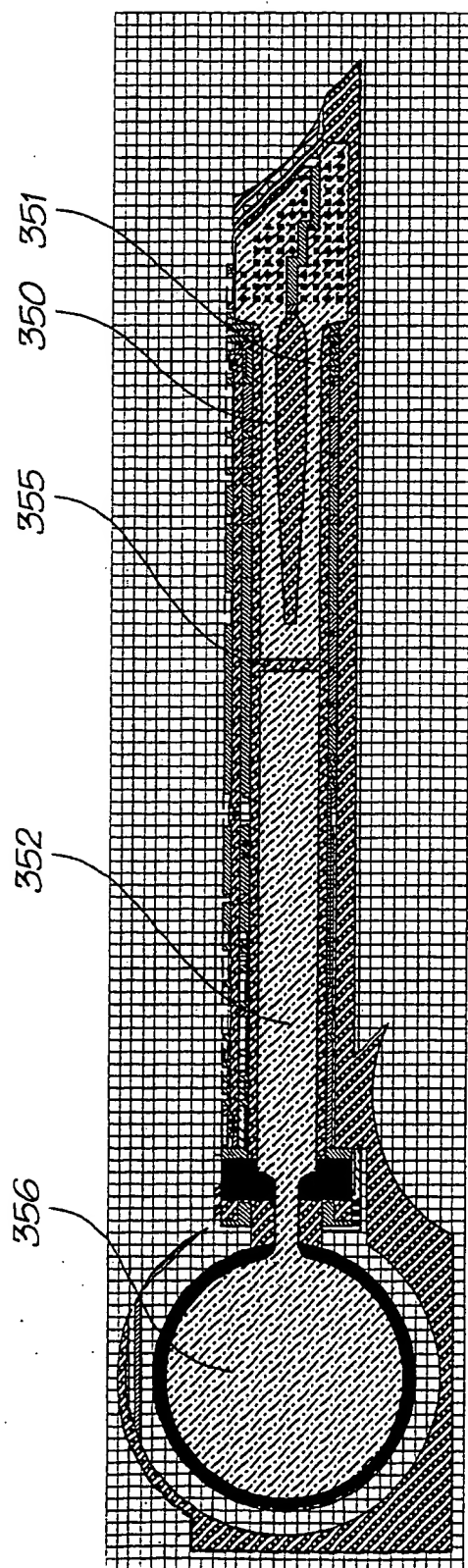


FIG. 83

FIG. 83

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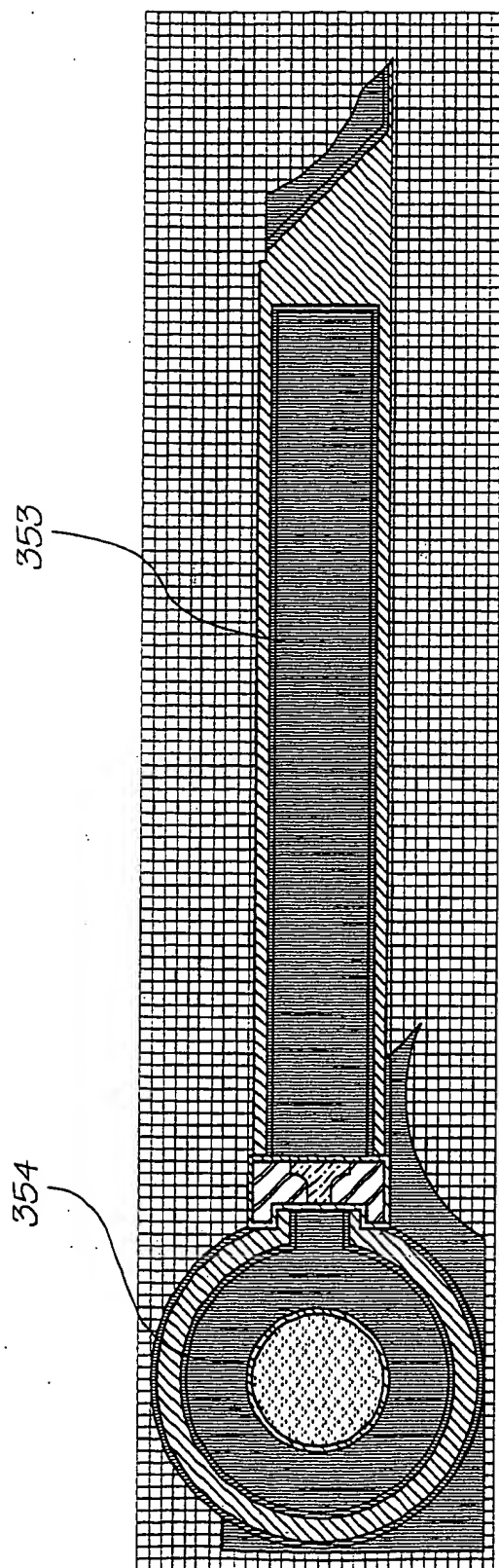


FIG. 84

FIG. 84

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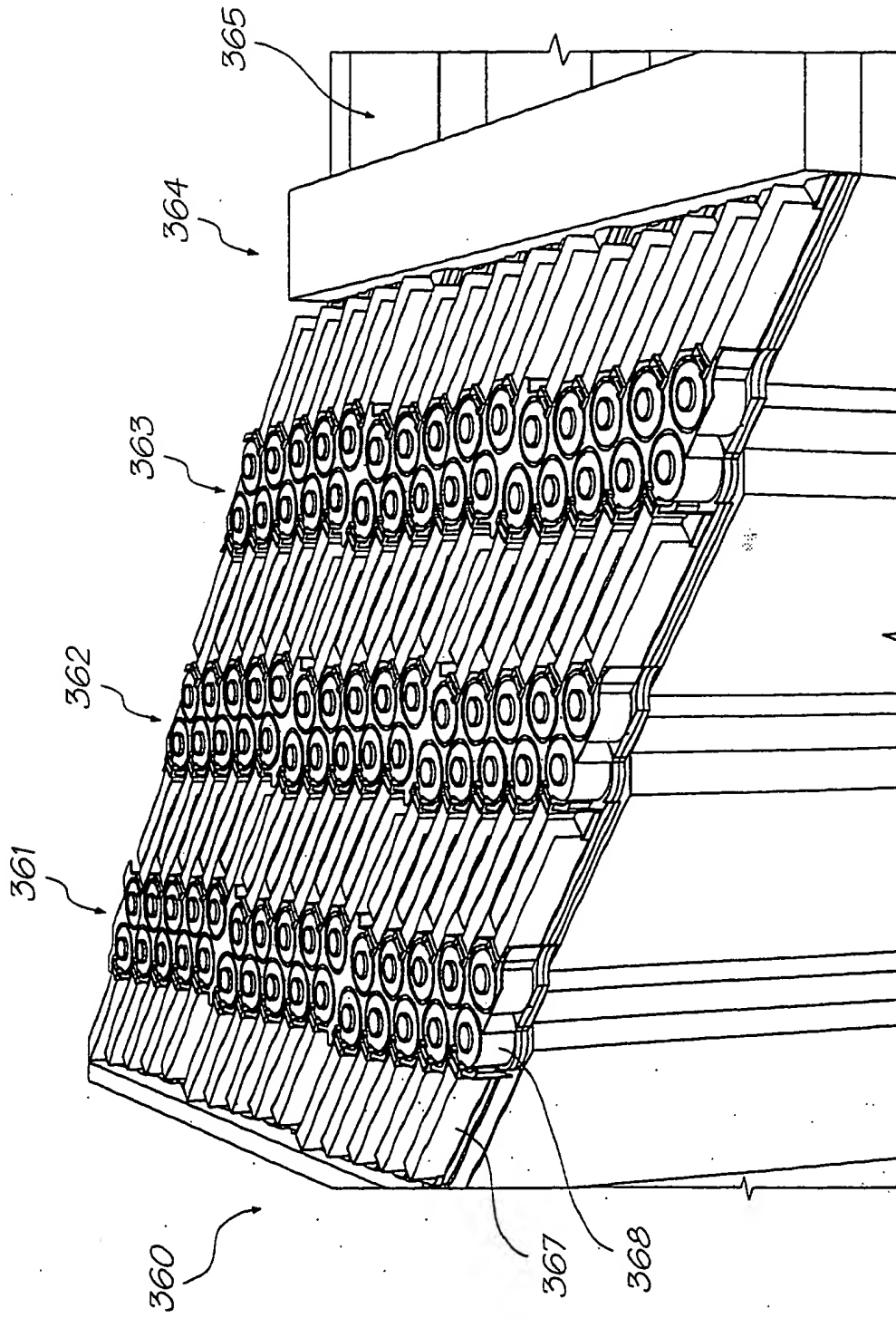


FIG. 85

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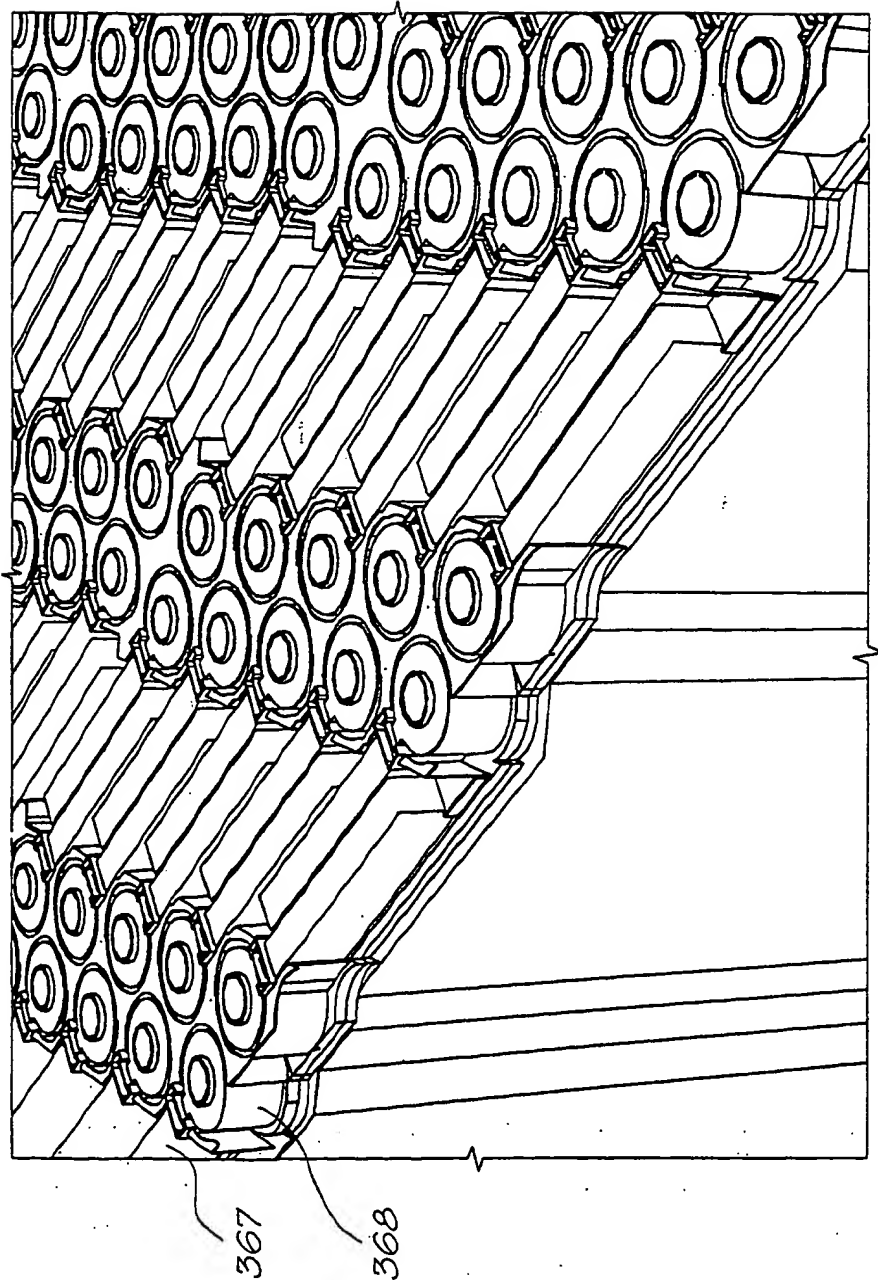


FIG. 86

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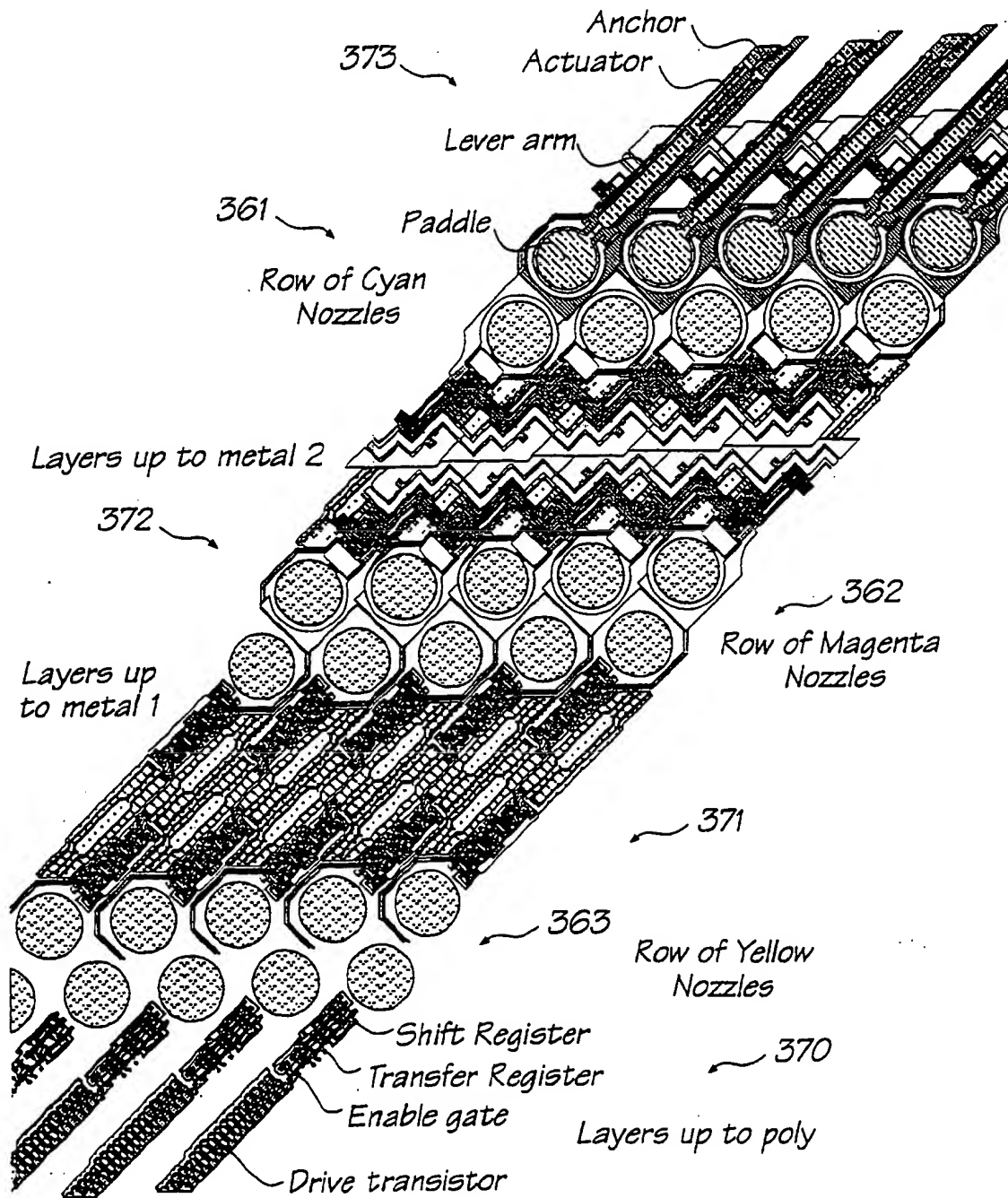


FIG. 87

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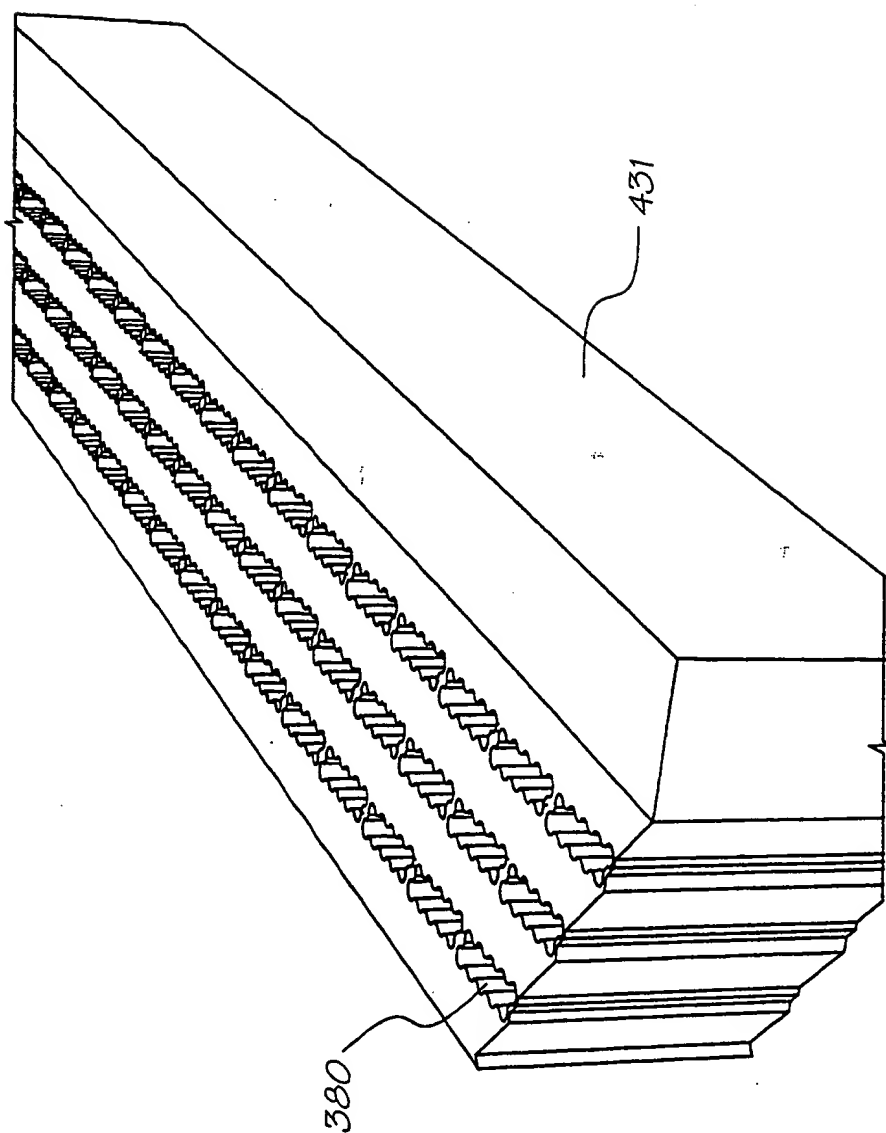


FIG. 88

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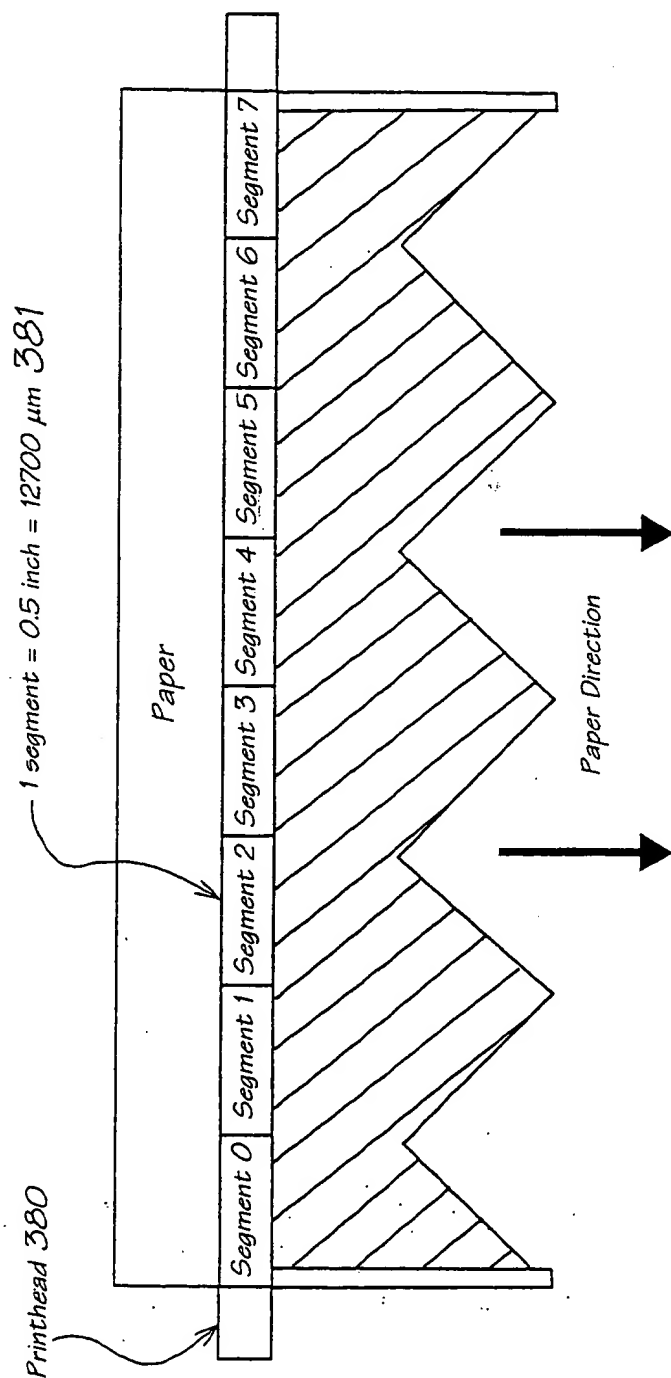
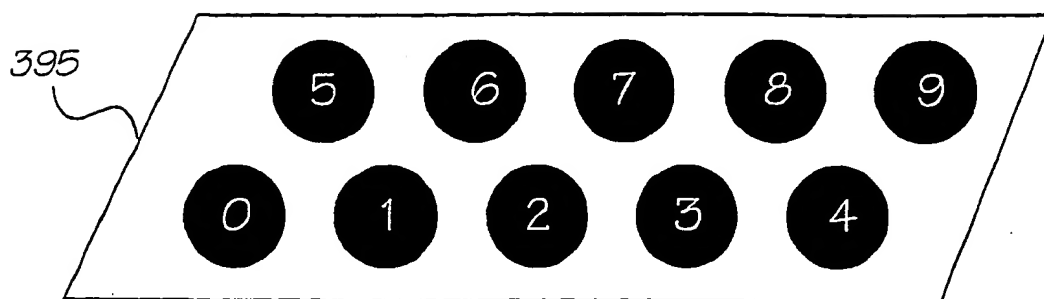


FIG. 89

FIG. 89

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A single pod, numbered by firing order

Fig. 90

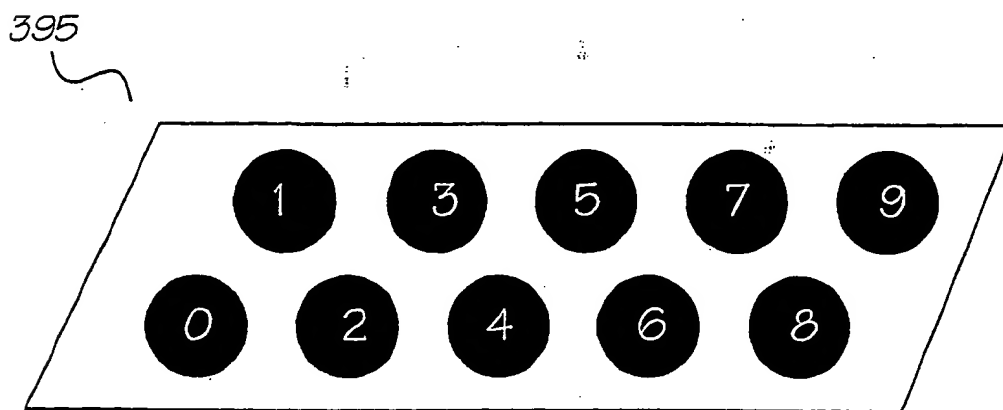


Fig. 91

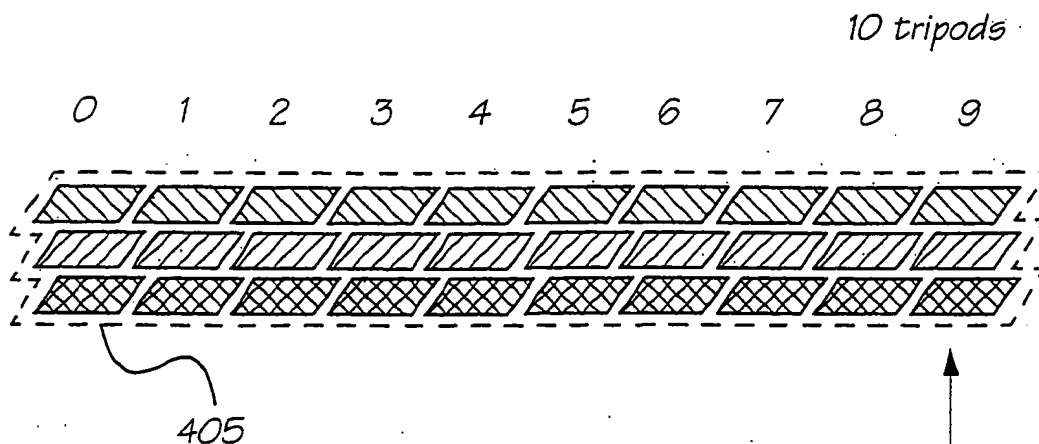


Fig. 93

FIG. 90

FIG. 92

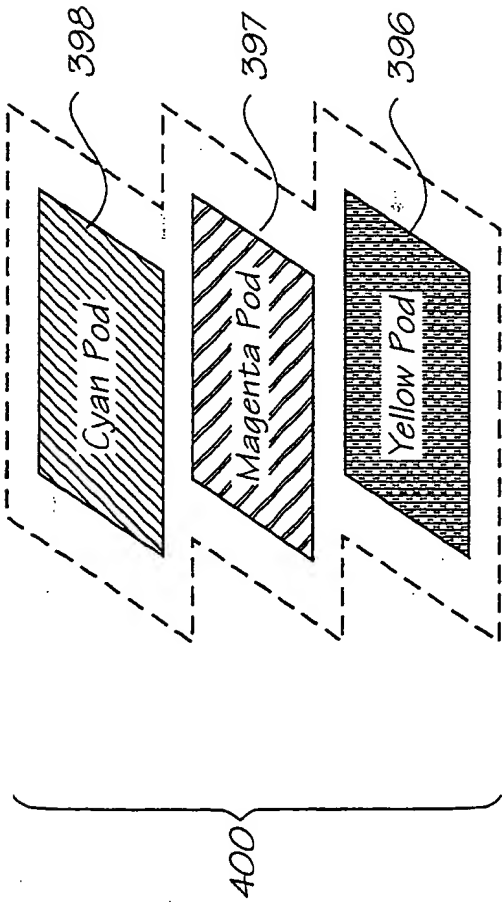


FIG. 92

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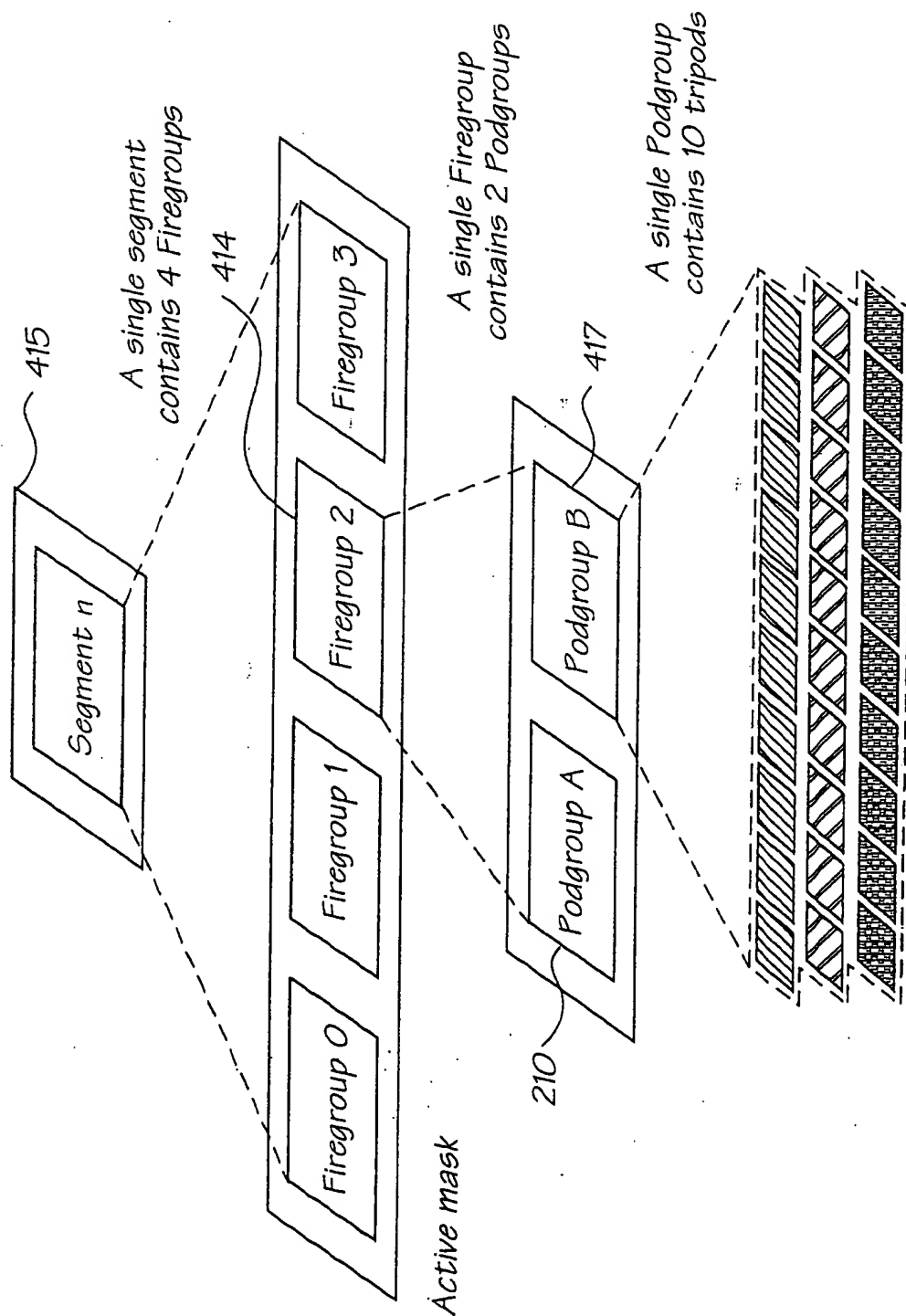


FIG. 94

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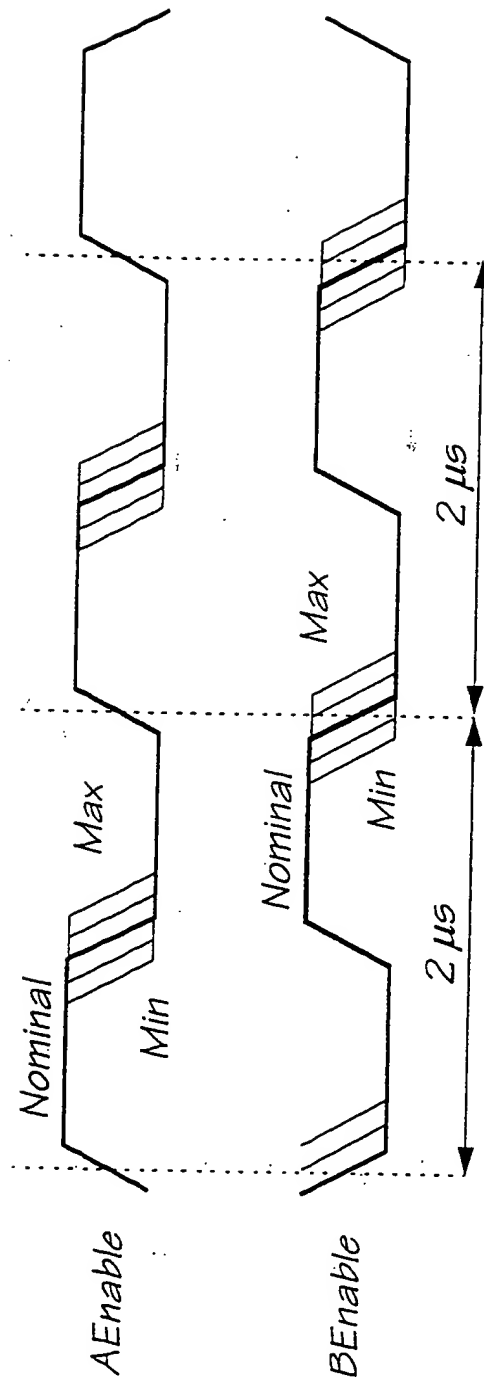


FIG. 95

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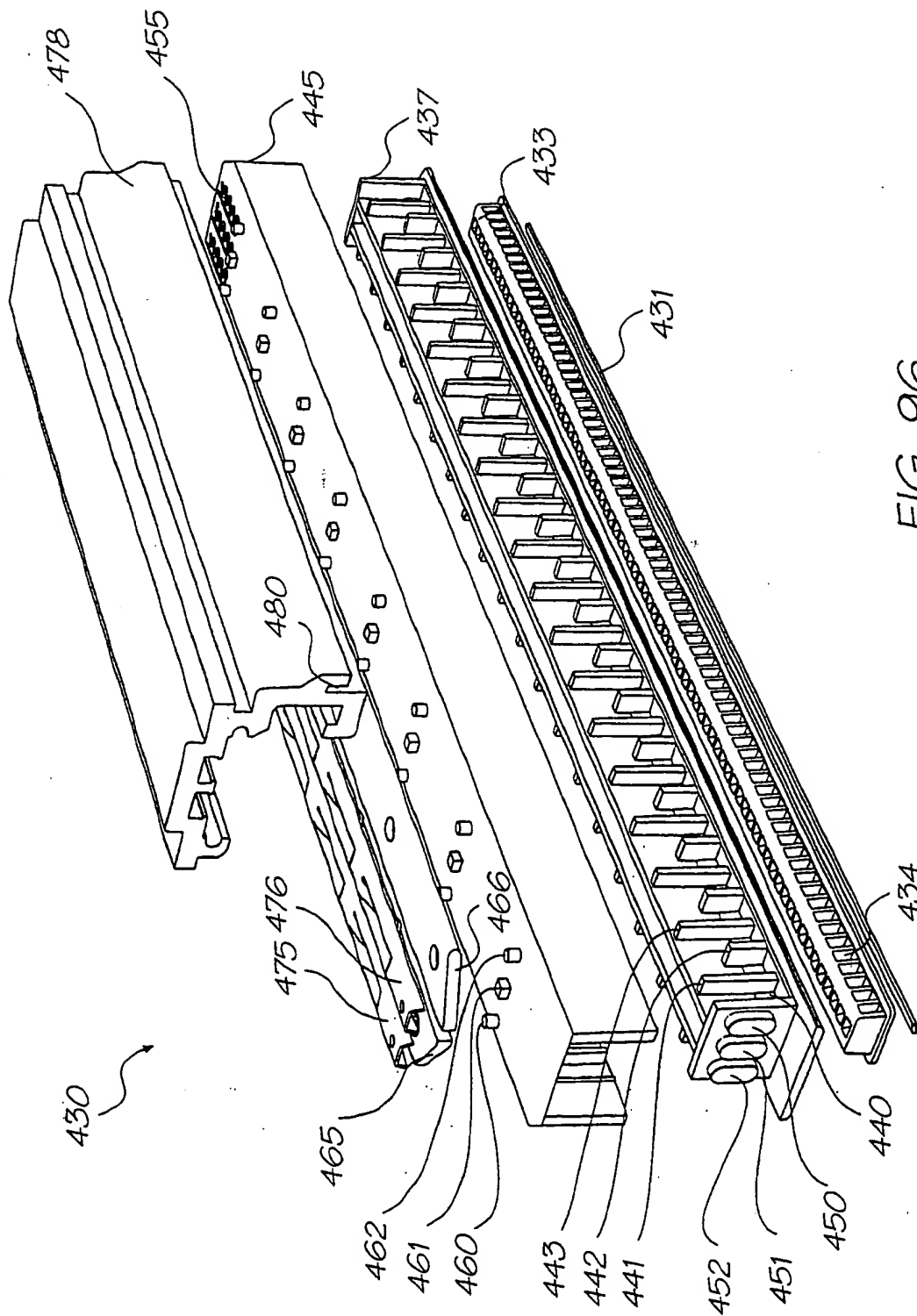


FIG. 96

FIG. 96

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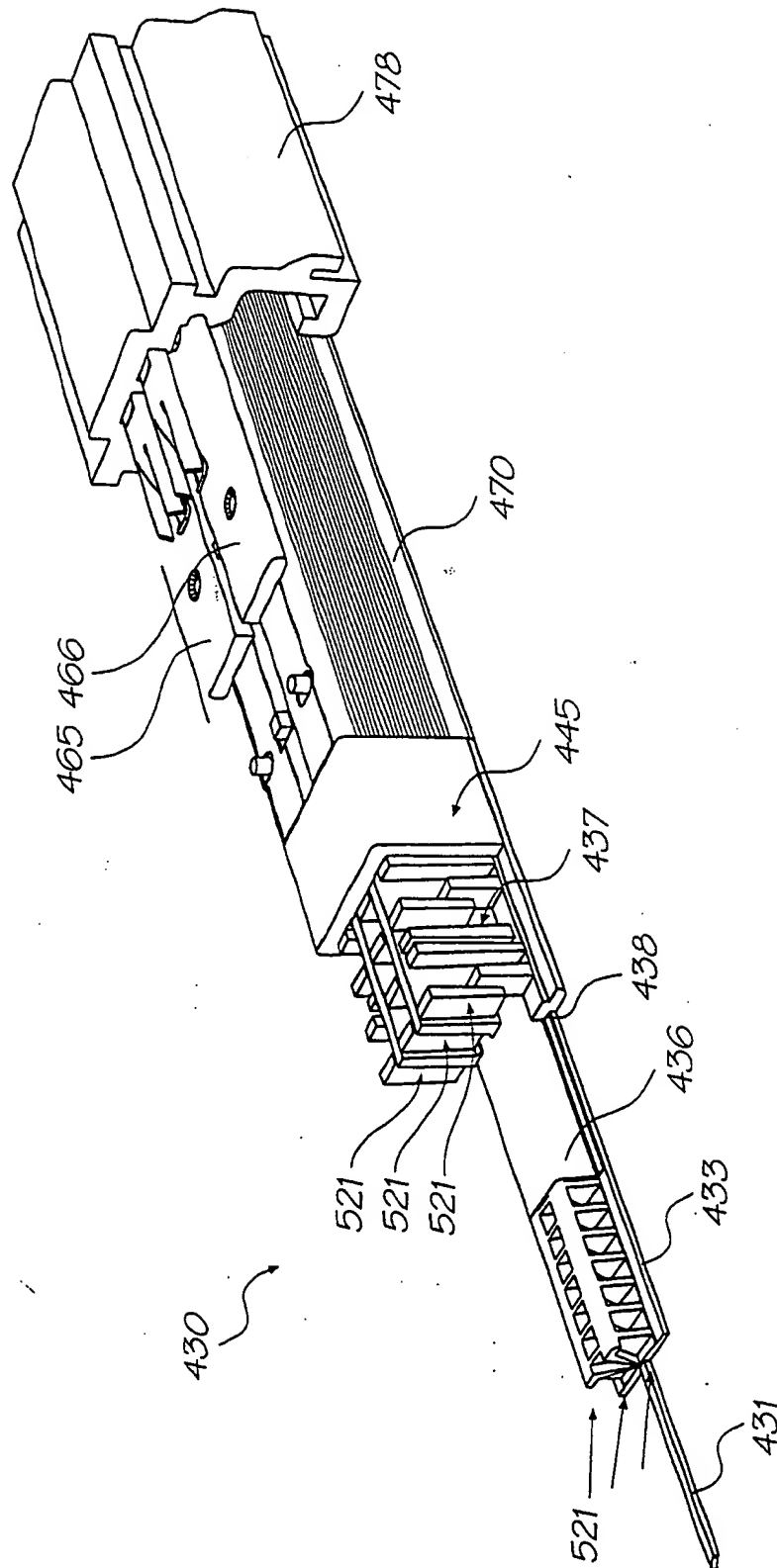


FIG. 97

FIG. 97

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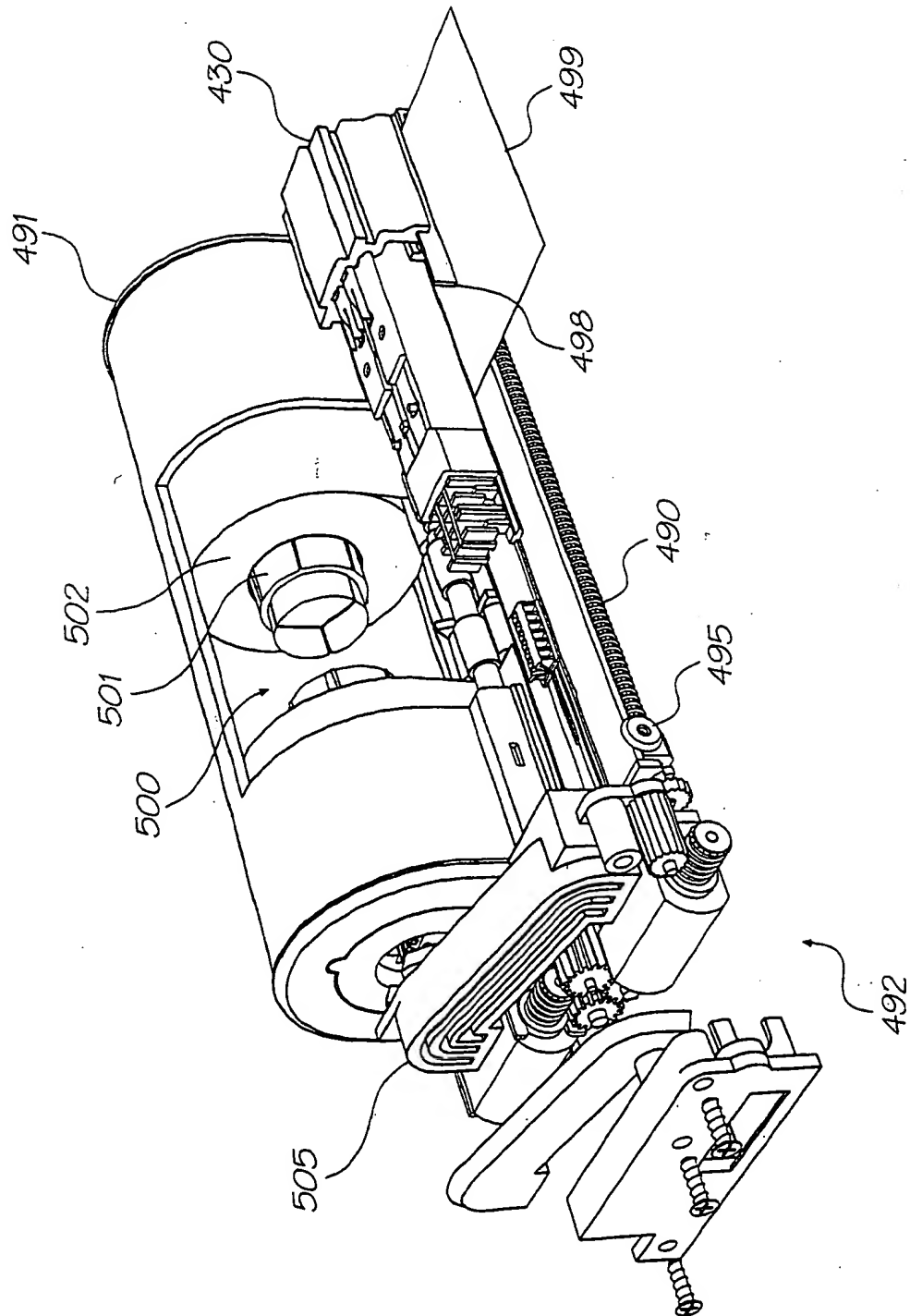


FIG. 98

FIG. 98 is a perspective view of a mechanical assembly, likely a camera or optical device, showing various components labeled with reference numerals.

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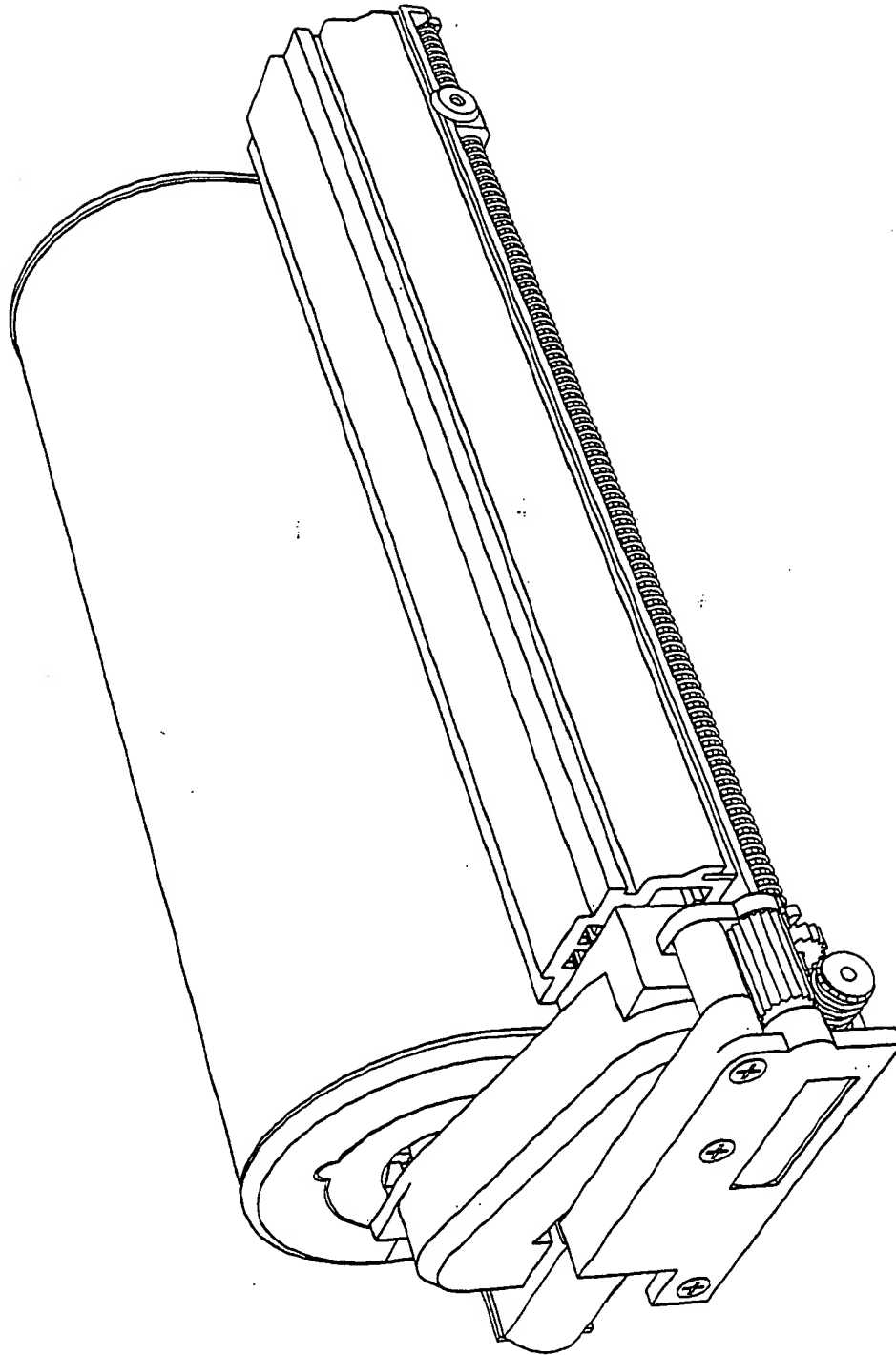


FIG. 99

093371-041601
FIG. 99

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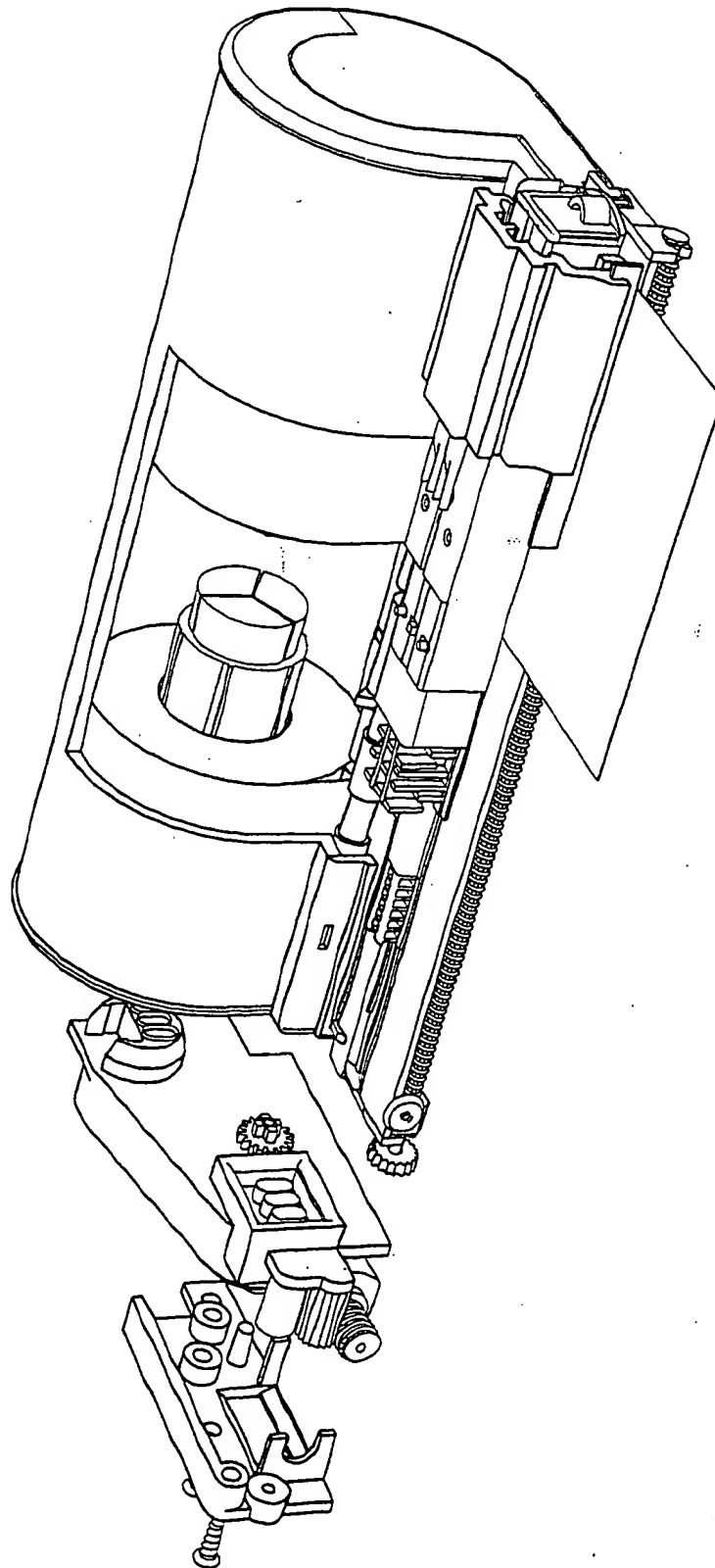


FIG. 100

FIG. 100

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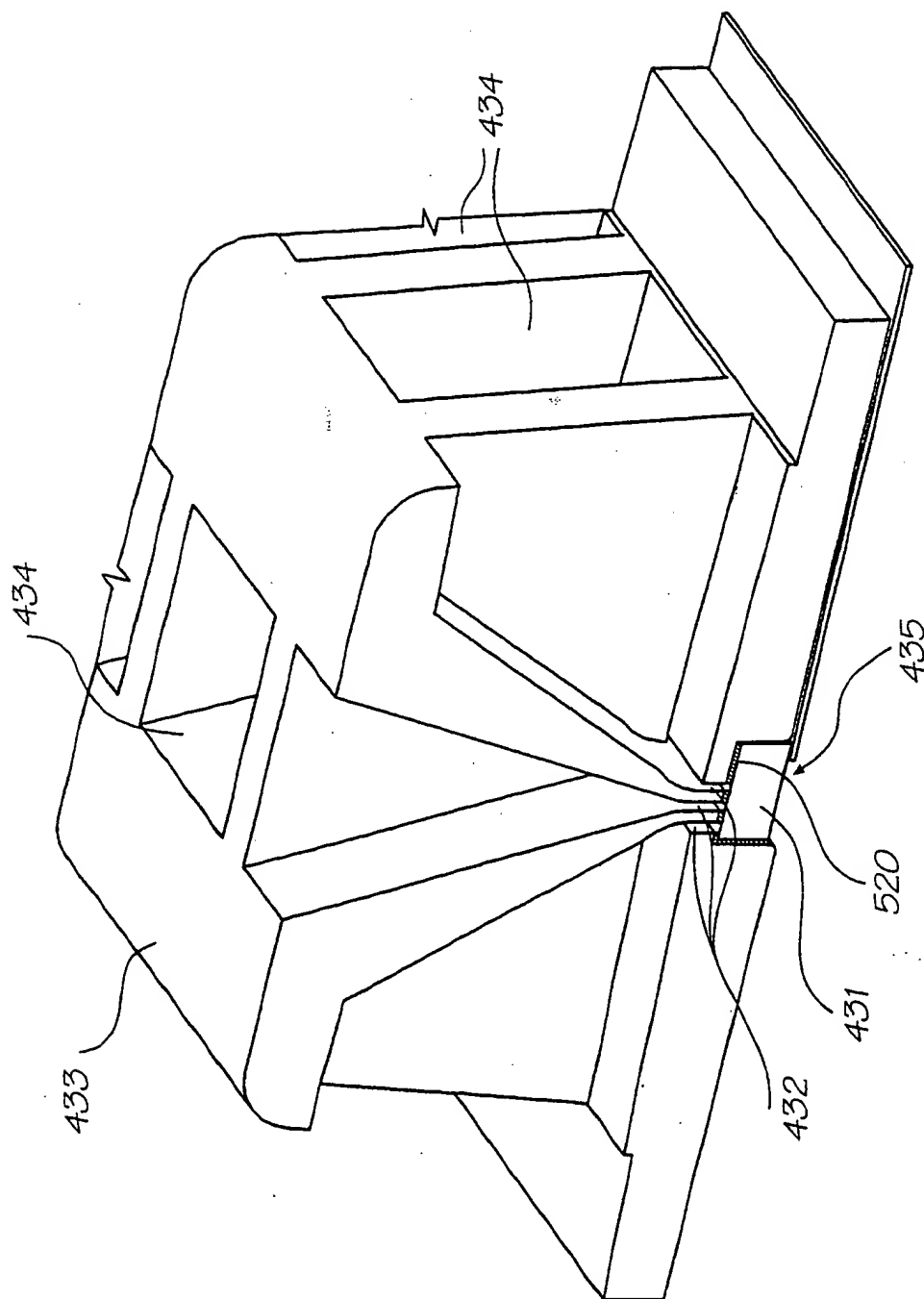


FIG. 101

FIG. 101

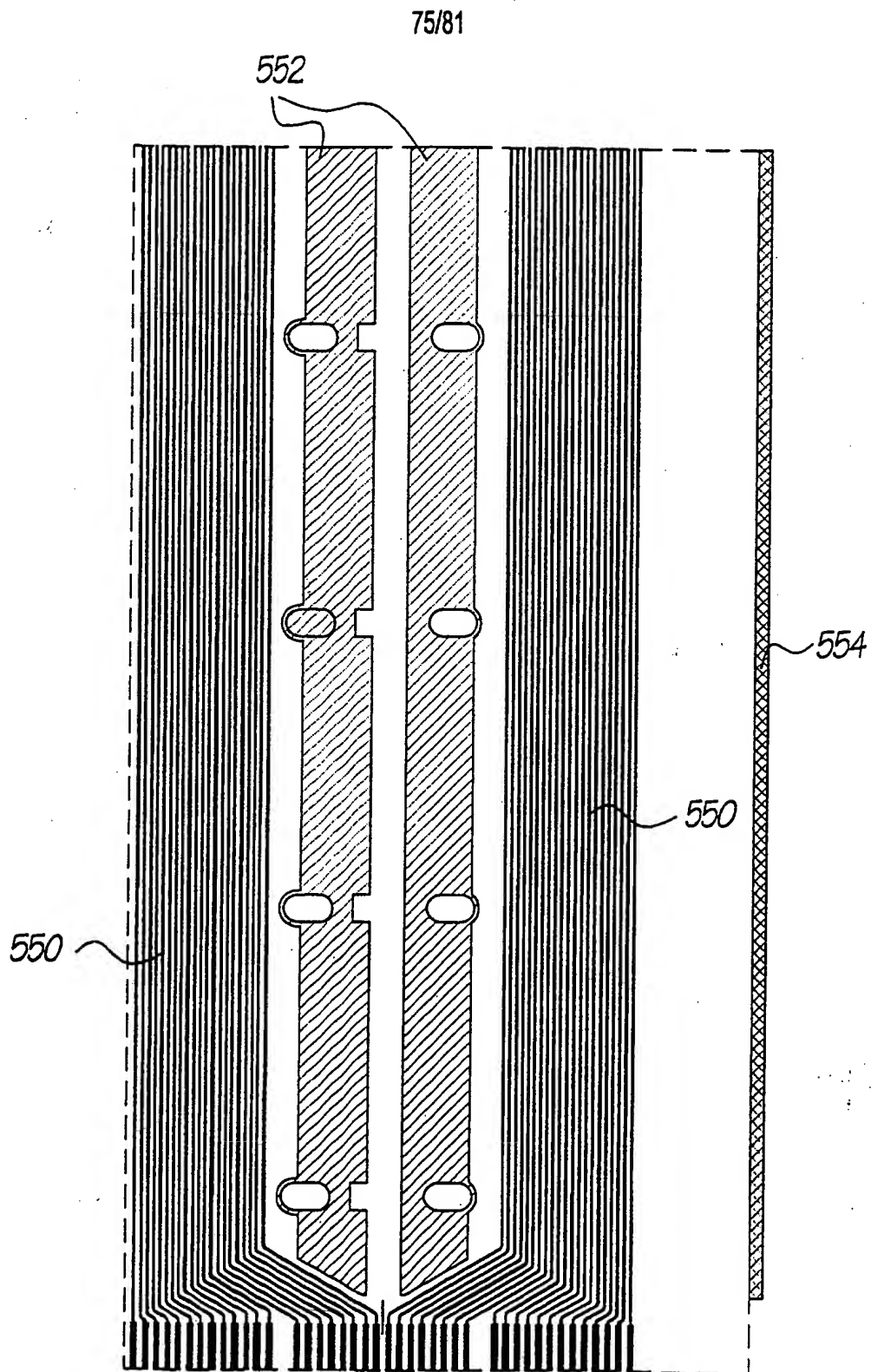


FIG. 102

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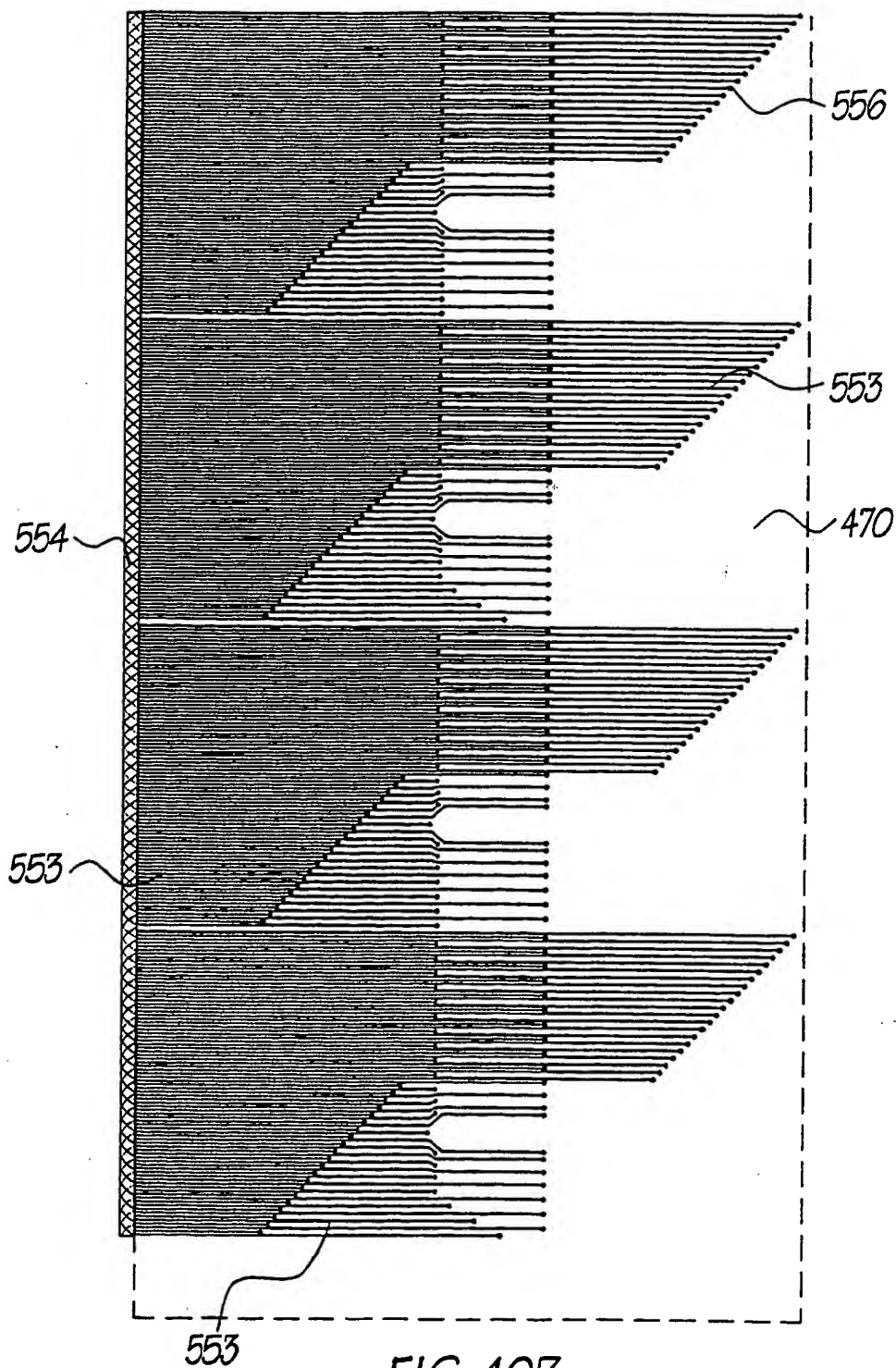


FIG. 103

FIG. 103

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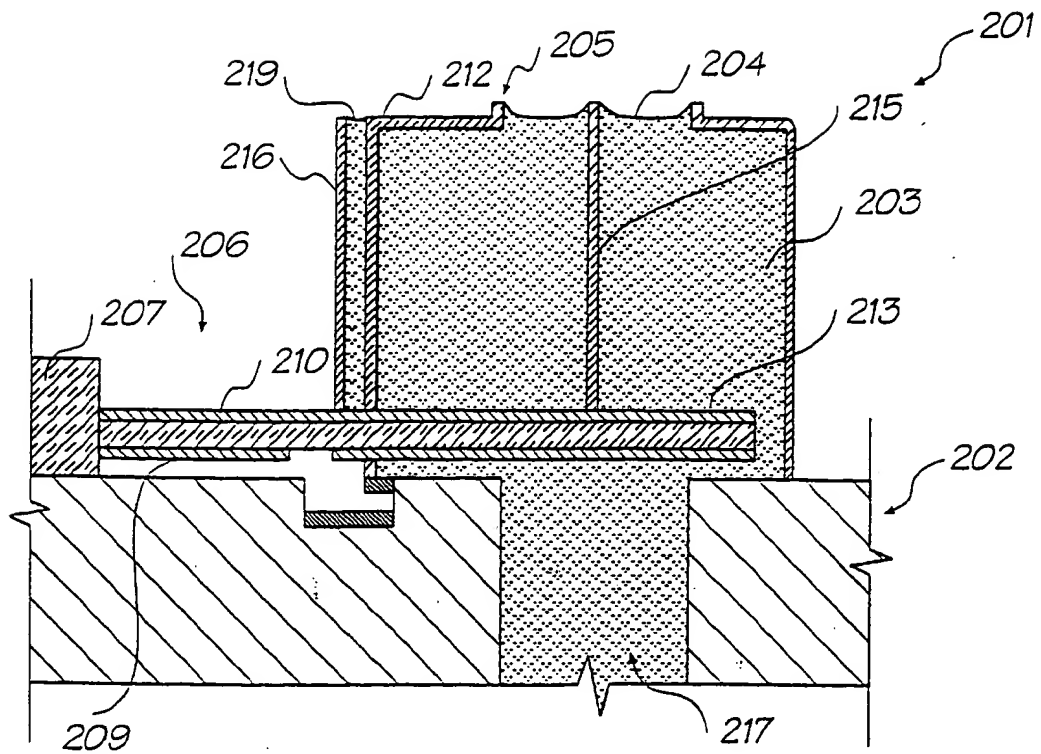


FIG. 104

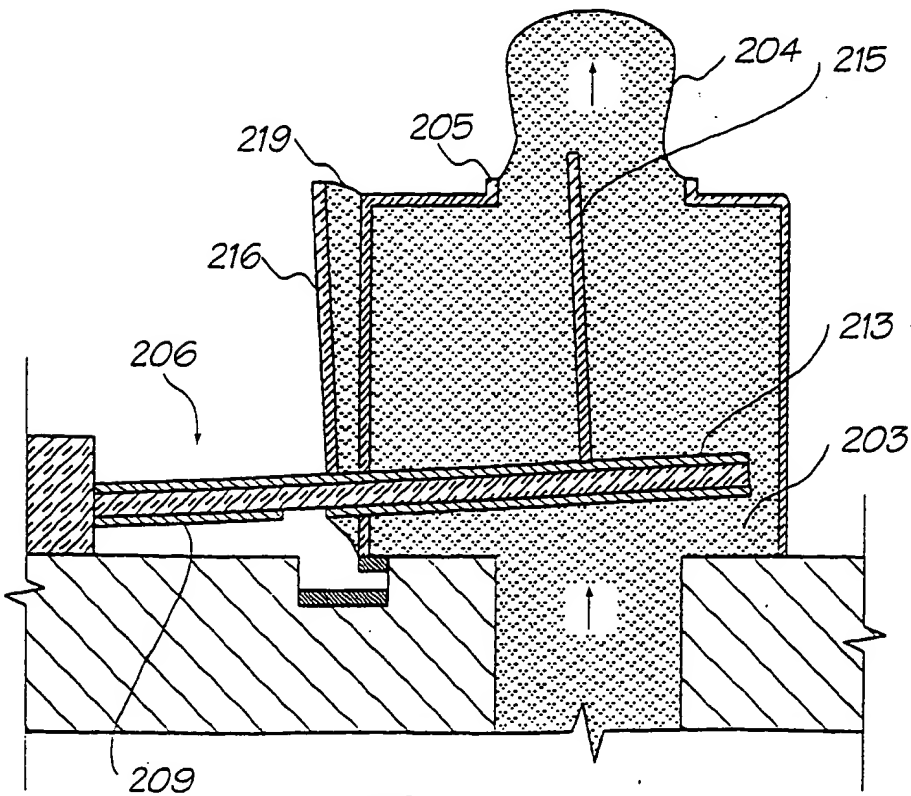


FIG. 105

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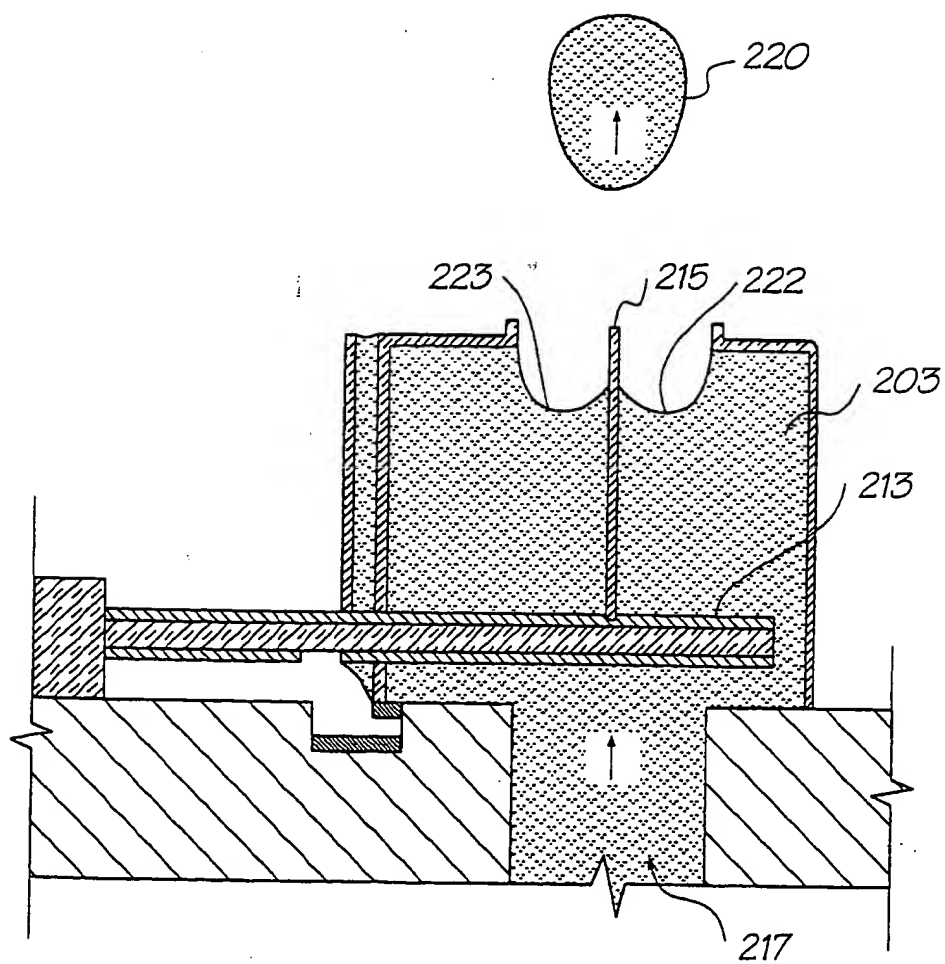


FIG. 106

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FIG. 107

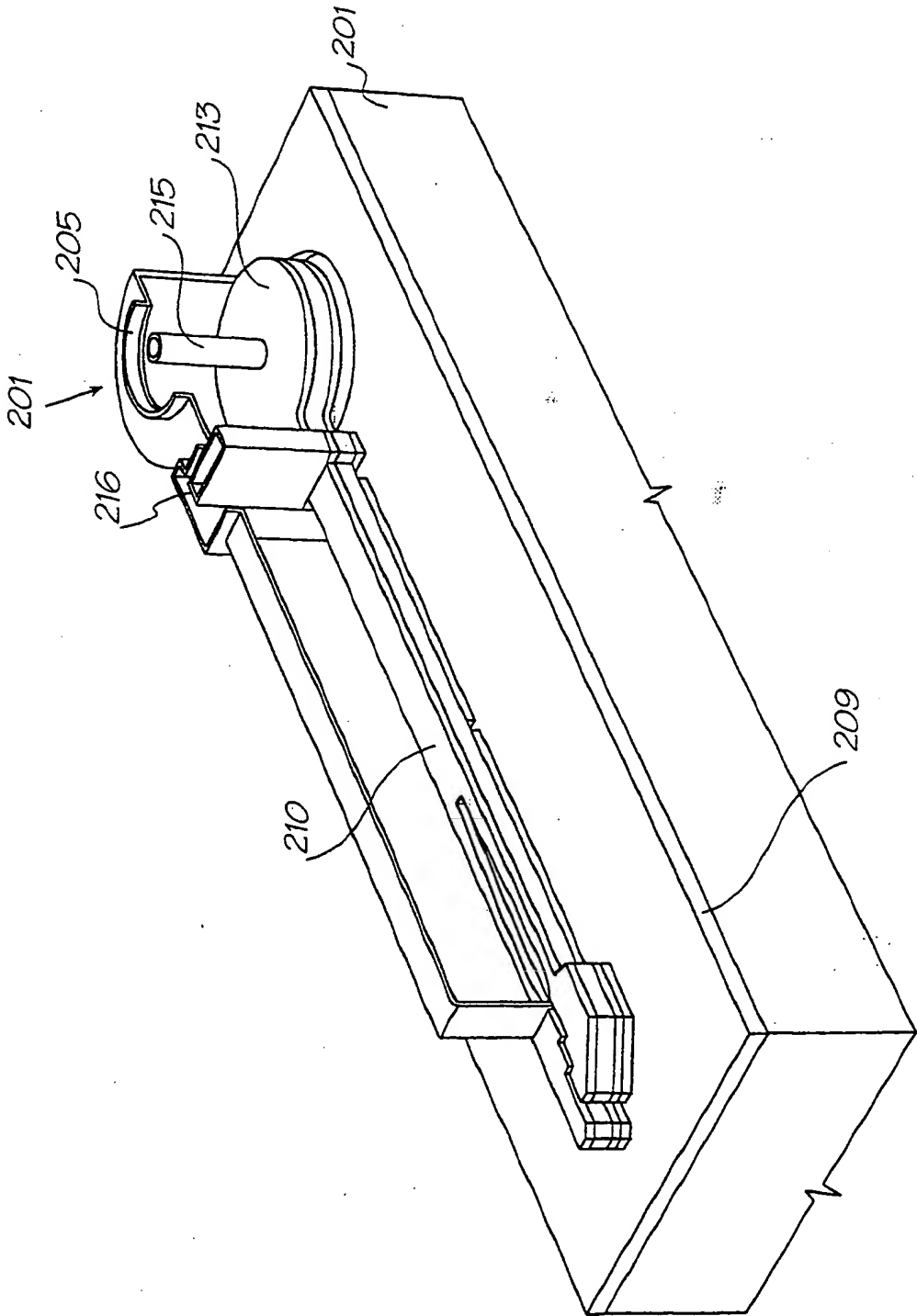


FIG. 107

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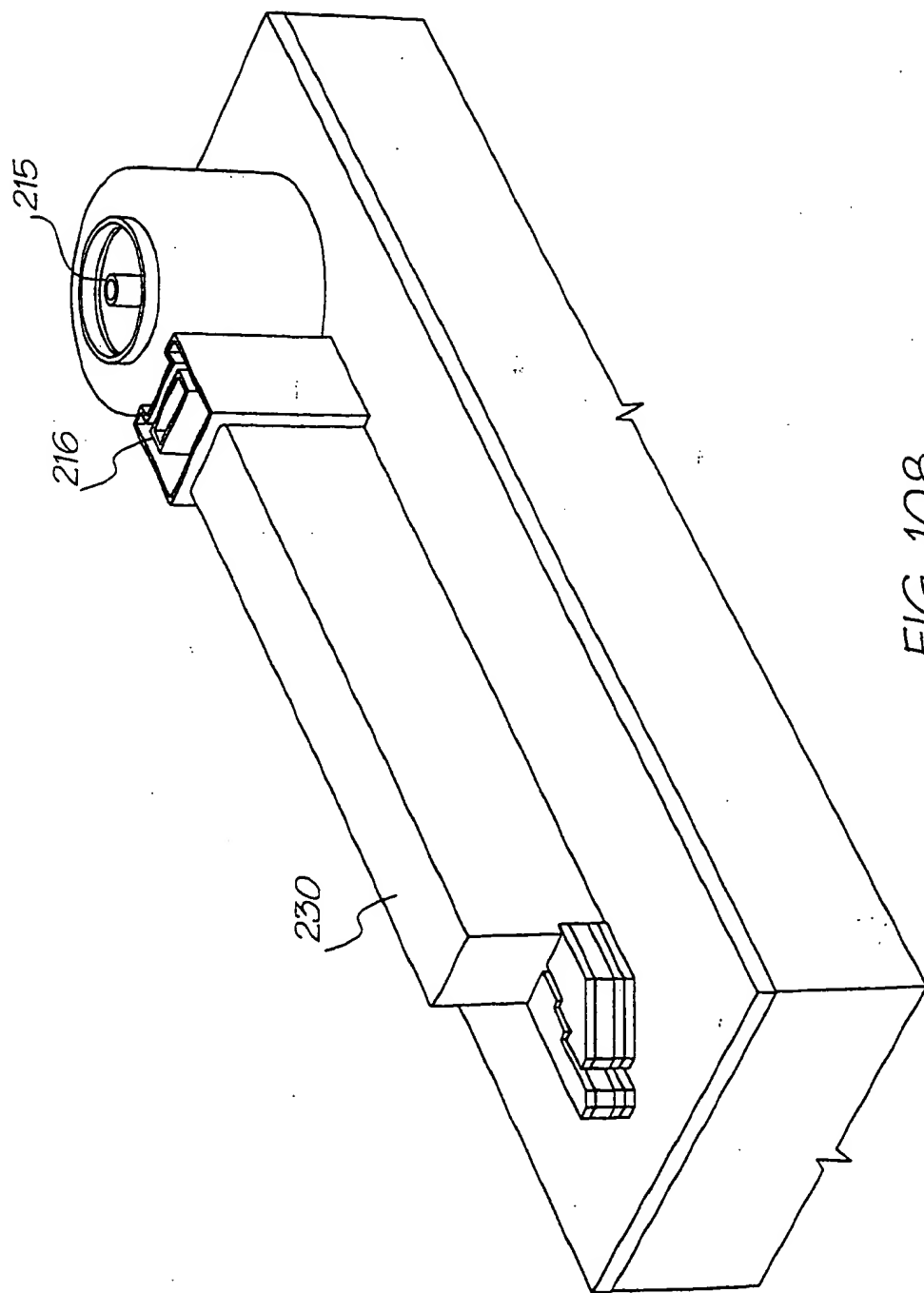


FIG. 108

FIG. 108

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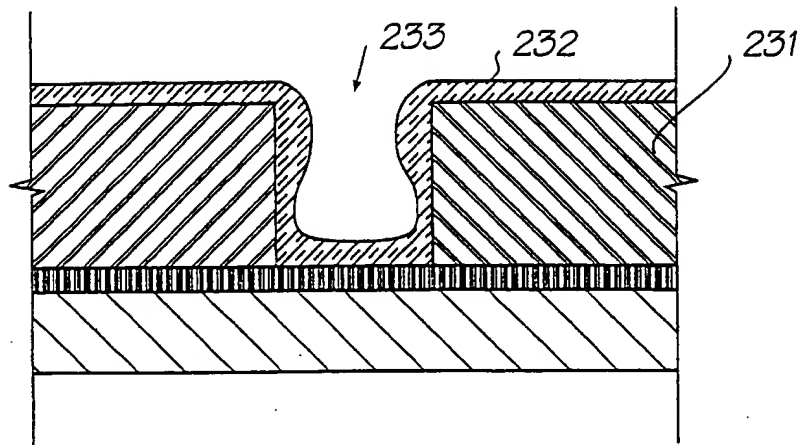


FIG. 109

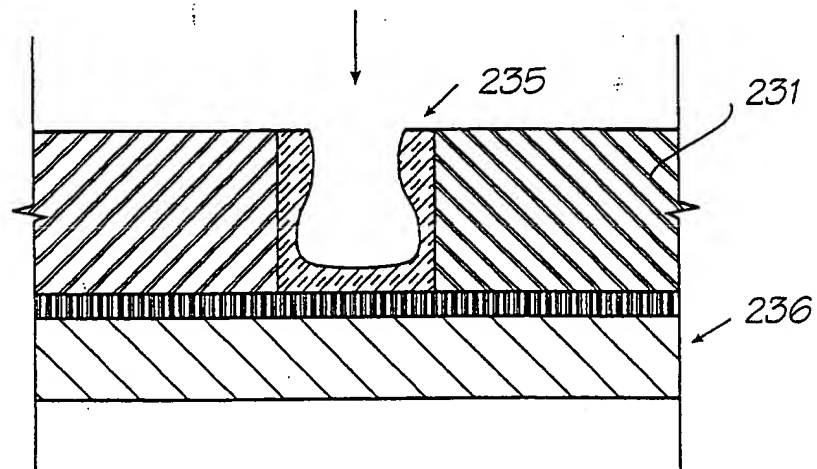


FIG. 110

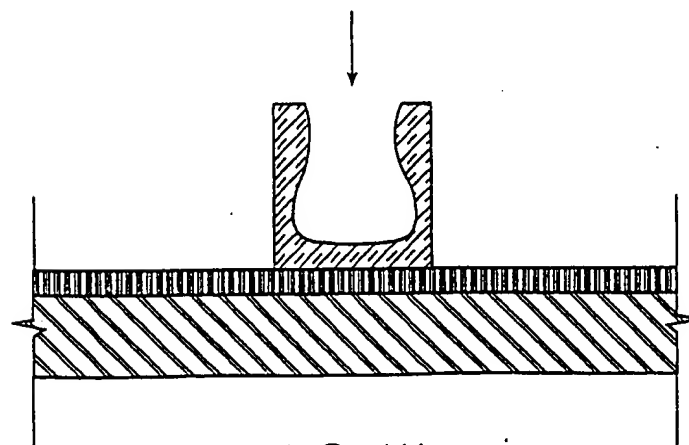


FIG. 111

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